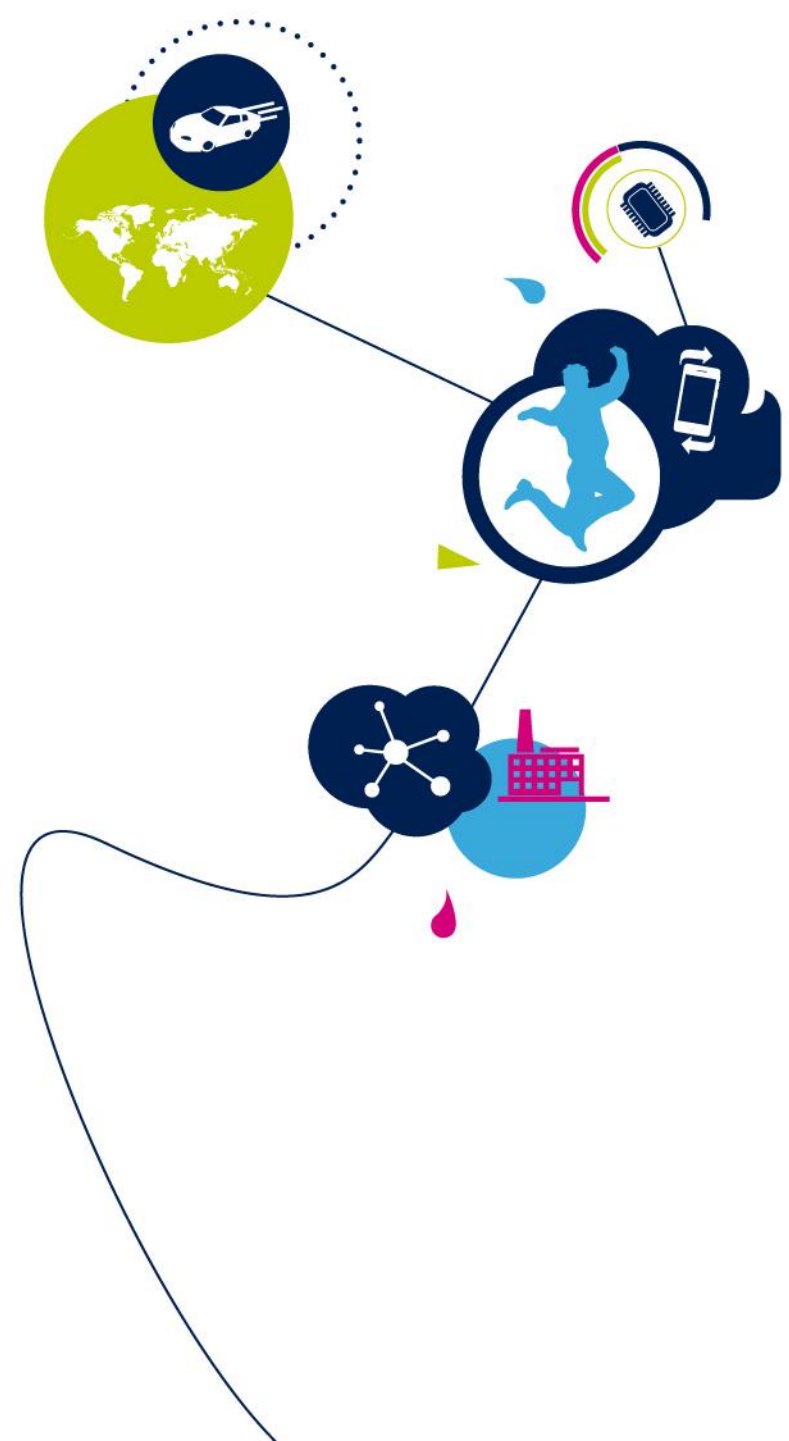


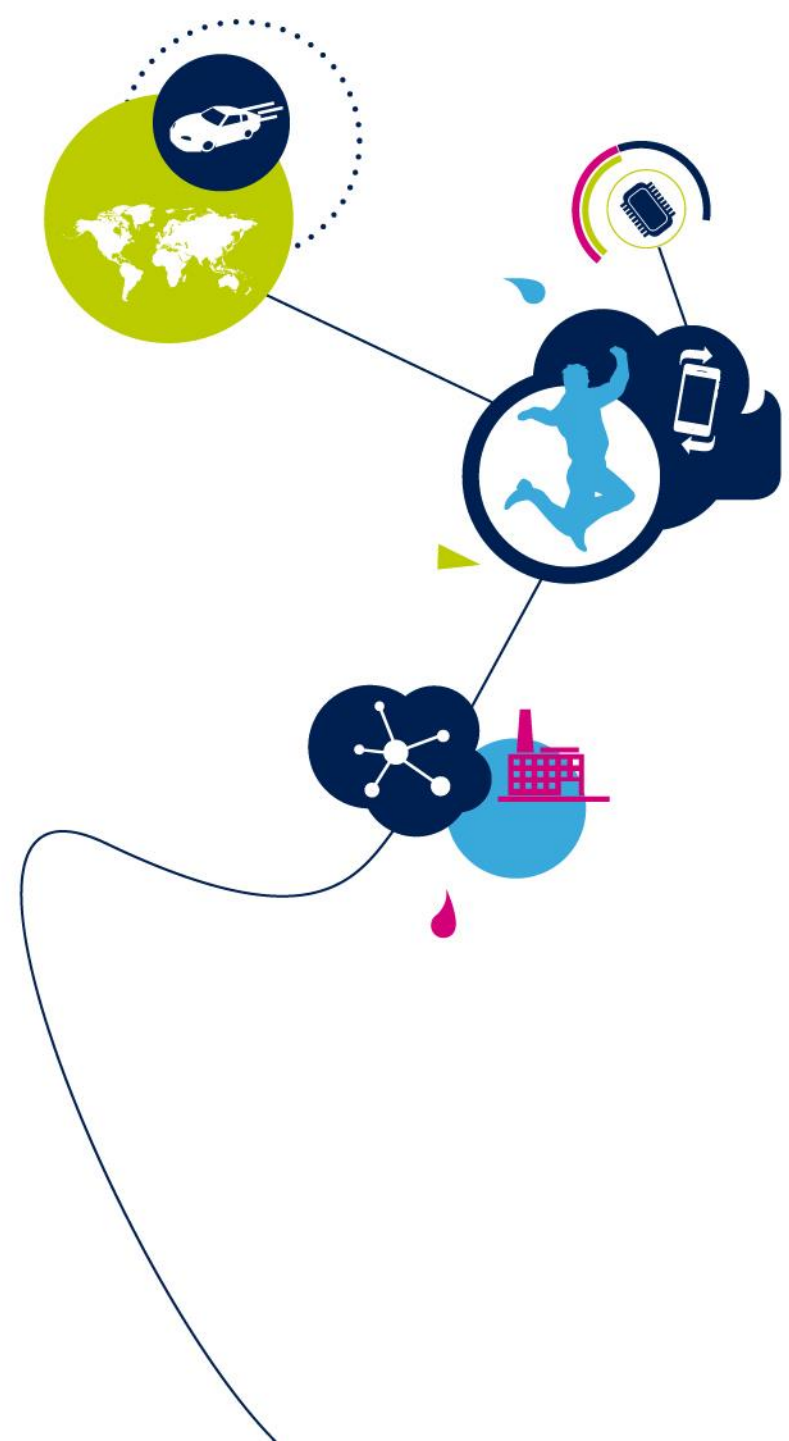
STMicroelectronics Capital Markets Day 2019



Welcome

Celine Berthier

Group Vice President, Head of Investor Relations



9:00 a.m. **Welcome**
Celine Berthier, Group Vice President, Head of Investor Relations

Introduction
Jean-Marc Chery, President & CEO

Market and End Market Strategy
Marco Cassis, President, Sales, Marketing, Communications and Strategy Development

Automotive and Discrete Group
Marco Monti, President, Automotive and Discrete Group

Analog, MEMS and Sensors Group
Benedetto Vigna, President, Analog, MEMS and Sensors Group

Microcontrollers and Digital ICs Group
Claude Dardanne, President, Microcontrollers and Digital ICs Group

11:00 a.m. **BREAK – DEMOS**

11:30 a.m. **Manufacturing Strategy**
Orio Bellezza, President, Technology, Manufacturing and Quality

Financial Results & Priorities
Lorenzo Grandi, President, Finance, Infrastructure and Services, Chief Financial Officer

12:15 p.m. **Q&A PANEL**

1:15 p.m. **LUNCH – DEMOS**

2:30 p.m. **END**

Forward Looking Statements

Some of the statements contained in this release that are not historical facts are statements of future expectations and other forward-looking statements (within the meaning of Section 27A of the Securities Act of 1933 or Section 21E of the Securities Exchange Act of 1934, each as amended) that are based on management's current views and assumptions, and are conditioned upon and also involve known and unknown risks and uncertainties that could cause actual results, performance, or events to differ materially from those anticipated by such statements, due to, among other factors:

- Changes in global trade policies, including the adoption and expansion of tariffs and trade barriers, that could affect the macro-economic environment and adversely impact the demand for our products;*
- Uncertain macro-economic and industry trends, which may impact end-market demand for our products;*
- Customer demand that differs from projections;*
- The ability to design, manufacture and sell innovative products in a rapidly changing technological environment;*
- Changes in economic, social, labor, political, or infrastructure conditions in the locations where we, our customers, or our suppliers operate, including as a result of macro-economic or regional events, military conflicts, social unrest, labor actions, or terrorist activities;*
- Unanticipated events or circumstances, which may impact our ability to execute our plans and/or meet the objectives of our R&D and manufacturing programs, which benefit from public funding;*
- The Brexit vote and the perceptions as to the impact of the withdrawal of the U.K. may adversely affect business activity, political stability and economic conditions in the U.K., the Eurozone, the EU and elsewhere. While we do not have material operations in the U.K. and have not experienced any material impact from Brexit on our underlying business to date, we cannot predict its future implications;*
- Financial difficulties with any of our major distributors or significant curtailment of purchases by key customers;*
- The loading, product mix, and manufacturing performance of our production facilities and/or our required volume to fulfill capacity reserved with suppliers or third party manufacturing providers;*
- Availability and costs of equipment, raw materials, utilities, third-party manufacturing services and technology, or other supplies required by our operations;*
- The functionalities and performance of our IT systems, which are subject to cybersecurity threats and which support our critical operational activities including manufacturing, finance and sales, and any breaches of our IT systems or those of our customers or suppliers;*
- Theft, loss, or misuse of personal data about our employees, customers, or other third parties, and breaches of global and local privacy legislation, including the EU's General Data Protection Regulation ("GDPR");*
- The impact of intellectual property ("IP") claims by our competitors or other third parties, and our ability to obtain required licenses on reasonable terms and conditions;*
- Changes in our overall tax position as a result of changes in tax rules, new or revised legislation, the outcome of tax audits or changes in international tax treaties which may impact our results of operations as well as our ability to accurately estimate tax credits, benefits, deductions and provisions and to realize deferred tax assets;*
- Variations in the foreign exchange markets and, more particularly, the U.S. dollar exchange rate as compared to the Euro and the other major currencies we use for our operations;*
- The outcome of ongoing litigation as well as the impact of any new litigation to which we may become a defendant;*
- Product liability or warranty claims, claims based on epidemic or delivery failure, or other claims relating to our products, or recalls by our customers for products containing our parts;*
- Natural events such as severe weather, earthquakes, tsunamis, volcano eruptions or other acts of nature, health risks and epidemics in locations where we, our customers or our suppliers operate;*
- Industry changes resulting from vertical and horizontal consolidation among our suppliers, competitors, and customers; and*
- The ability to successfully ramp up new programs that could be impacted by factors beyond our control, including the availability of critical third party components and performance of subcontractors in line with our expectations.*

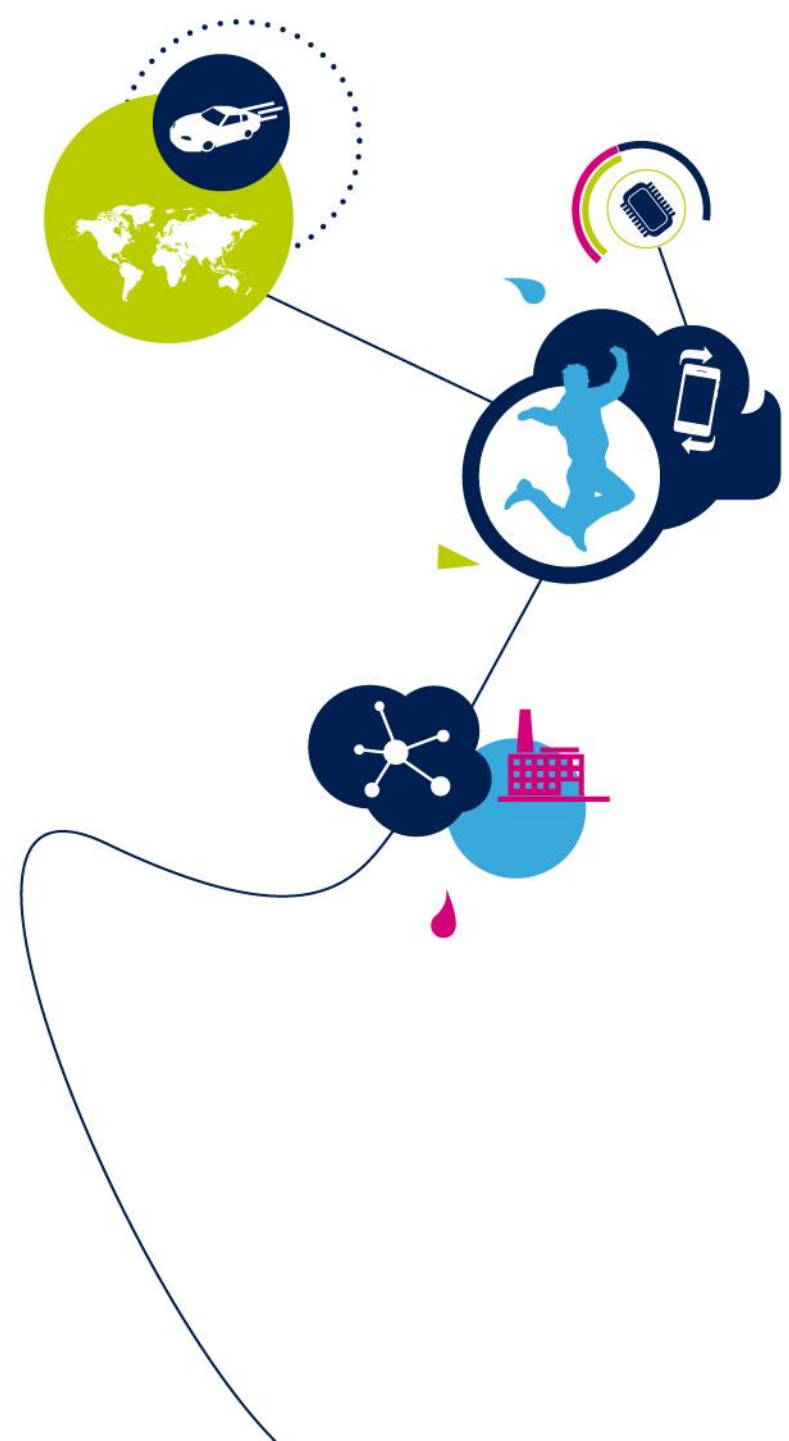
Such forward-looking statements are subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the forward-looking statements. Certain forward-looking statements can be identified by the use of forward looking terminology, such as "believes," "expects," "may," "are expected to," "should," "would be," "seeks" or "anticipates" or similar expressions or the negative thereof or other variations thereof or comparable terminology, or by discussions of strategy, plans or intentions.

Some of these risk factors are set forth and are discussed in more detail in "Item 3. Key Information — Risk Factors" included in our Annual Report on Form 20-F for the year ended December 31, 2018, as filed with the SEC on February 28, 2019. Should one or more of these risks or uncertainties materialize, or should underlying assumptions prove incorrect, actual results may vary materially from those described in this release as anticipated, believed, or expected. We do not intend, and do not assume any obligation, to update any industry information or forward-looking statements set forth in this release to reflect subsequent events or circumstances.

Introduction

Jean-Marc Chery

President and CEO



ST Value Proposition

For our shareholders



Return value in line with our sustainable, profitable growth objective

Sustainable and profitable growth

For our customers



Provide differentiating enablers

Independent, reliable & secure supply chain

For other stakeholders



Committed to sustainability

Our values: Integrity – People – Excellence

Enabling Strategic Electronic Demand Trends



ST provides innovative solutions help our customers make driving **safer, greener and more connected** for everyone



ST technology and solutions enable customers to increase **energy efficiency** everywhere and support the use of renewable energy sources



ST provides **sensors, embedded processing solutions, connectivity, security and power management**, as well **tools and ecosystems** to make development fast and easy for our customers

End Markets

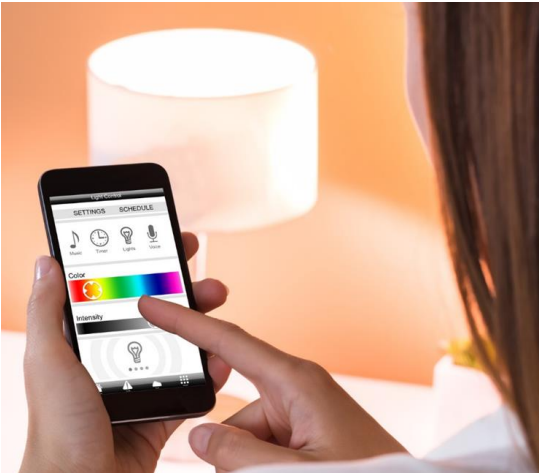
End Markets Strategy

Automotive

Industrial

Personal Electronics

Communications Equipment, Computers & Peripherals



Broad offering & market reach

Selected opportunities leveraging ST strengths

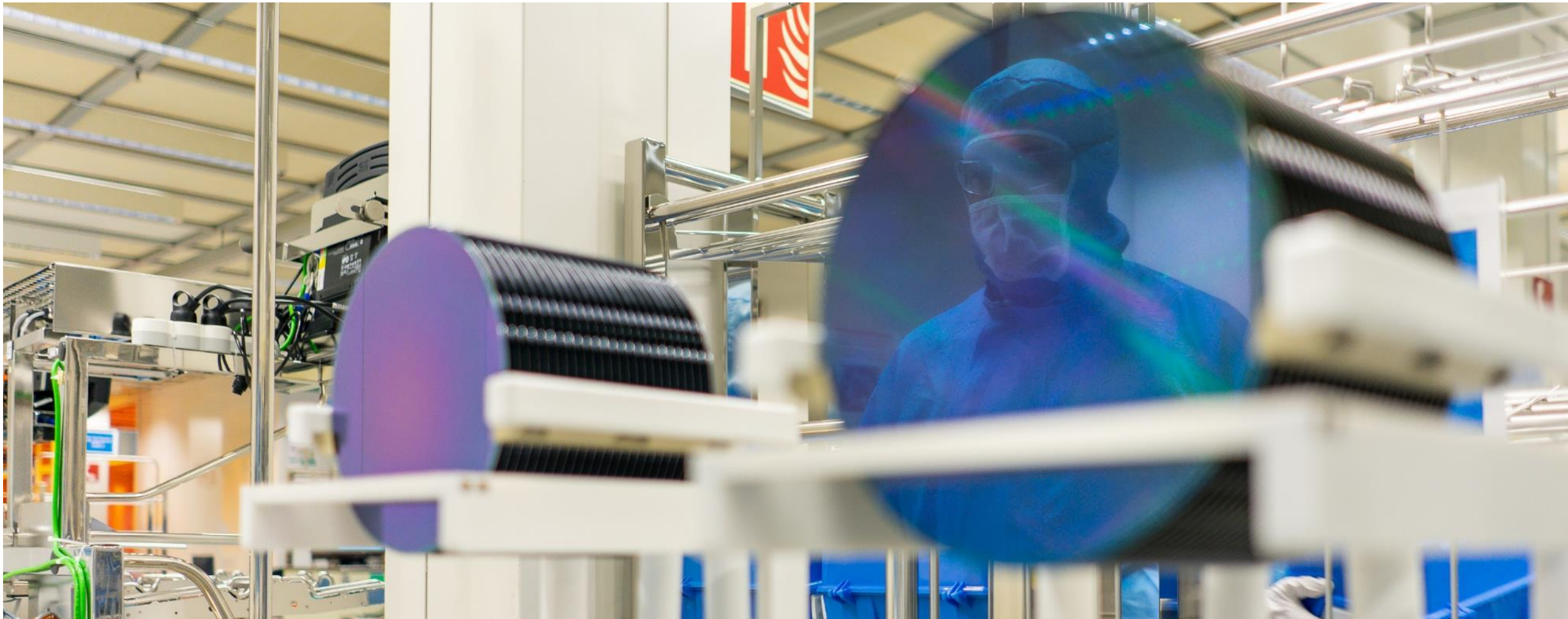
ST Product Portfolio Enabling Strategic Trends

Product Portfolio

Dedicated Automotive ICs	Discrete & Power Transistors	Analog, Industrial & Power Conversion ICs	GP MCU/MPU Secure MCUs EEPROM	MEMS & Specialized Imaging Sensors	ASICs based on ST proprietary technologies



Manufacturing as a Key Business Enabler



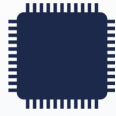
Strategic Objectives

Strategic Objectives

Leadership in car electrification



Leadership in industrial embedded processing



Leadership in selected high-volume smartphone applications: sensors, secure solutions, power management, analog and Front End Module



Transform approach to communication infrastructure: from digital wireline to cellular and satellite



Leadership in car digitalization



Expansion in industrial power & energy management



Acceleration of growth with industrial OEMs



Capture opportunities in 5G with RF mixed signal



Markets and End Market Strategy

Marco Cassis

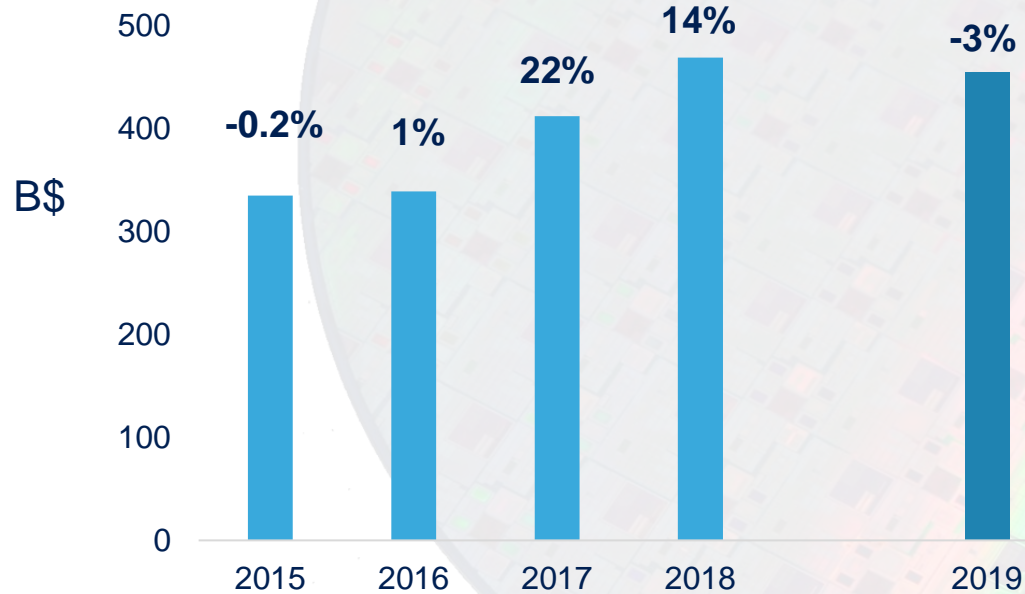
President

Sales, Marketing, Communications and Strategy Development

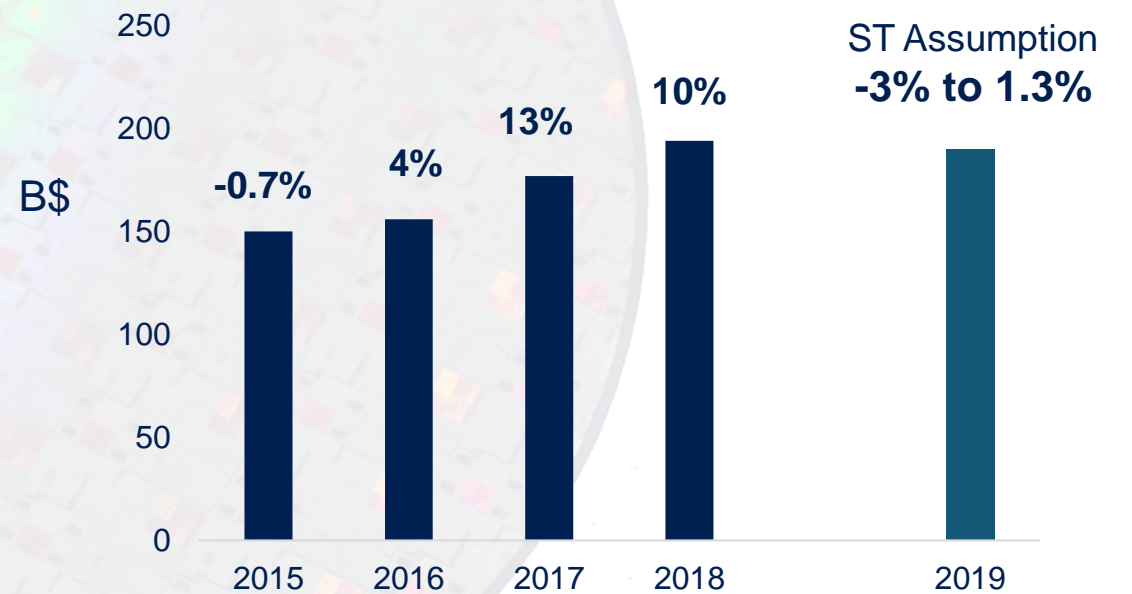


2019: Entering the Soft Part of the Semiconductor Market Cycle

Total Available Market (TAM)



Served Available Market (SAM)



ST SAM Growth Driven by Automotive and Industrial End Markets

Automotive

Industrial

Personal Electronics

Communications Equipment, Computers & Peripherals

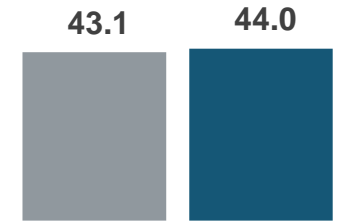
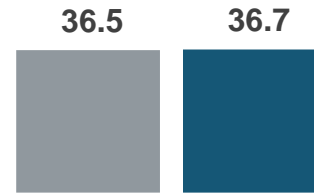
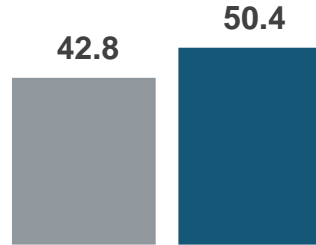
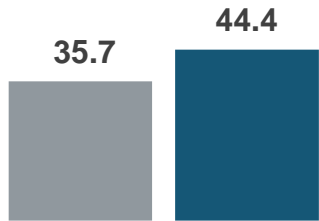
SAM \$B

+8% CAGR

+6% CAGR

0% CAGR

+1% CAGR



2018 2021

2018 2021

2018 2021

2018 2021

~30% of ST Sales*

~30% of ST Sales

~25% of ST Sales

~15% of ST Sales



*Based on ST 2018 Full Year Sales

Source: IHS Markit, Strategy Analytics




ST Has Strong Positions

Across all End-Markets and in Our Selective Focus

All End Markets

	General Purpose & Secure MCU	#1
	Power Discretes & Modules	#3
	MCU	#4
	Analog	#4
	MEMS Sensors	#4

Selective Focus

	Consumer & Mobile MEMS	#1
	Consumer & Mobile Light Sensors	#1
	Analog Mass storage	#3

Serving More Than 100,000 Customers

Top 10 Customers* 2018

Apple
Bosch
Cisco
Conti
HP
Huawei
Mobileye
Samsung
Seagate
Western Digital

*In alphabetical order

Top
10

Globally Managed
Accounts

Unified worldwide account
management tailored to each
account to provide global
coverage and service

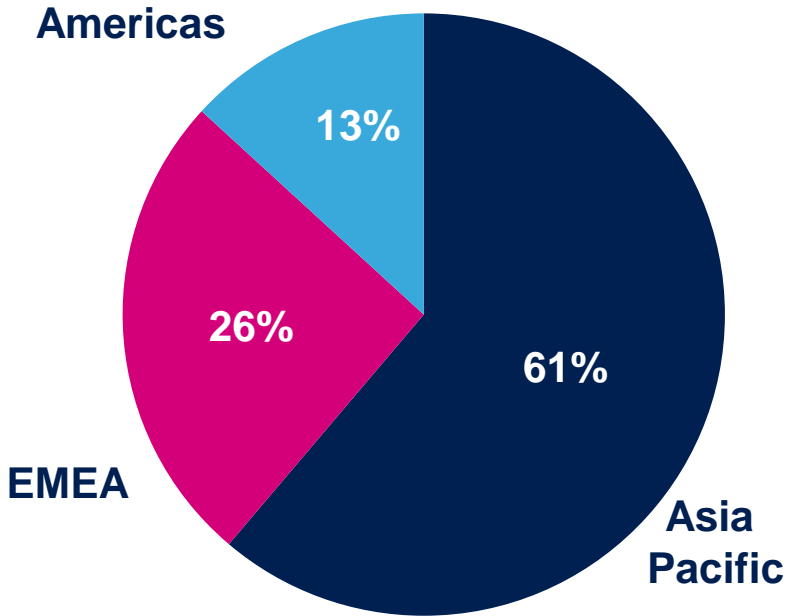
Distribution &
Mass Market

Standard process, reporting &
follow-up in Sales & Marketing
worldwide
Differentiated approach by
type of customer

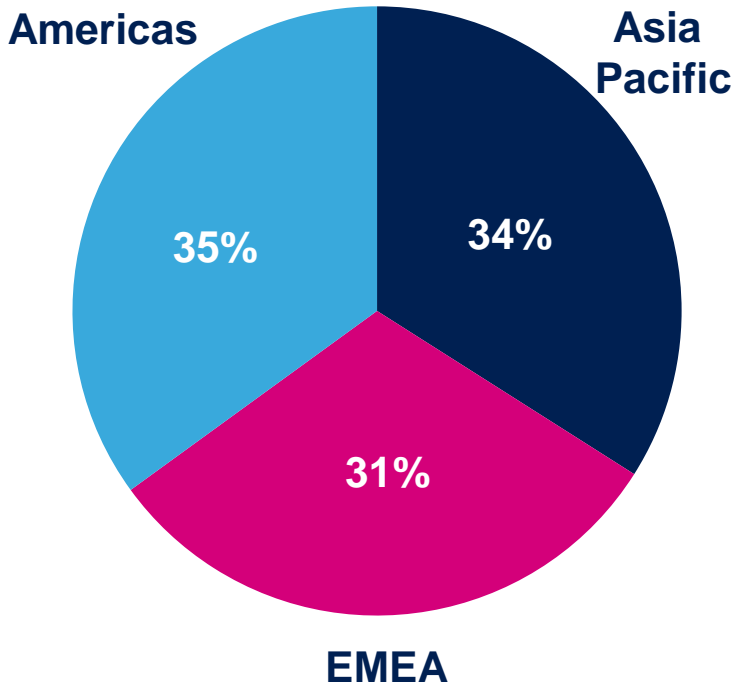
Balanced Sales Across Regions & Channels



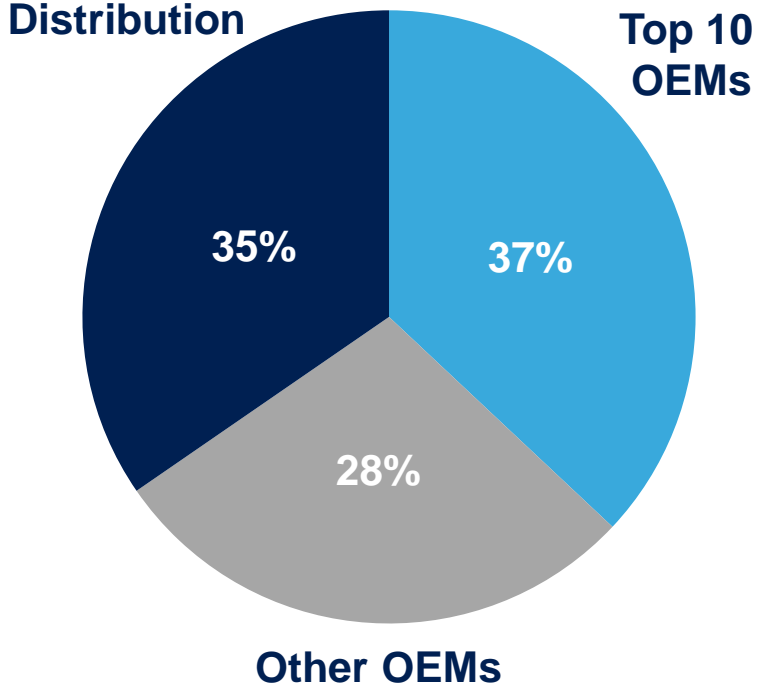
% by shipment location



% by region of origin



% by customer type



Application Approach

Leverage broad and deep knowledge of automotive systems to develop solutions optimized for targeted vehicle subsystems

- Chassis & Safety
- ADAS
- Powertrain for ICE
- Electro-mobility
- Body & Convenience
- In-vehicle Infotainment
- Telematics & Networking
- Mobility Services

Market Approach

Partnerships with Car Manufacturers, Tier 1's and technology leaders



Partnerships with Distribution Including full kit solutions



Partnerships for long-term success in China



ST Strategy in Automotive

Leverage Content and Volume Growth & Disruption

Strategic Objectives

- Leadership in car electrification
- Leadership in car digitalization



Trends & Market

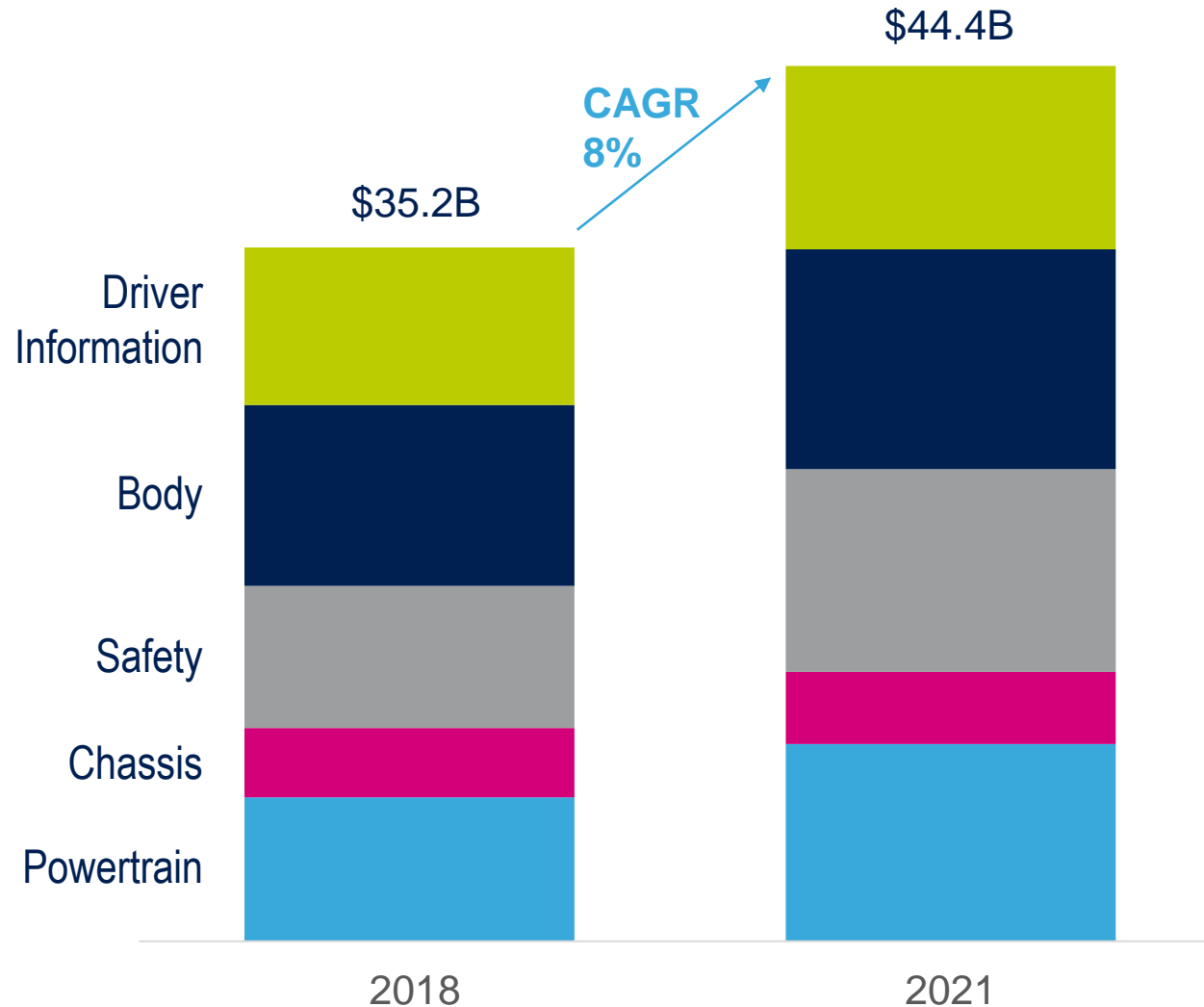
- Semiconductor market growth thanks to volume and content increase
- Traditional car content increase aligned with market volume
- Car electrification and digitalization driving much faster content growth
- Wide-band Gap material introduction causing a disruption
- Digital architecture of vehicle evolving from distributed Electronic Control Unit (ECU) to powerful domain controllers

ST Strategy

- Investment in technology, product and manufacturing capabilities to support leadership objectives
- Leverage Silicon Carbide disruption to lead the car electrification transformation
- Leverage car architecture change through advanced Automotive domain controllers (MCU)
- Partnership with ADAS and V2X Leaders
- Continue leadership in traditional areas thanks to product and technology roadmap

Automotive Semiconductor Market

Strong Existing Positions – Building in New Areas



Rank	Logic
1	STMicroelectronics

Rank	Power
1	Infineon
2	STMicroelectronics

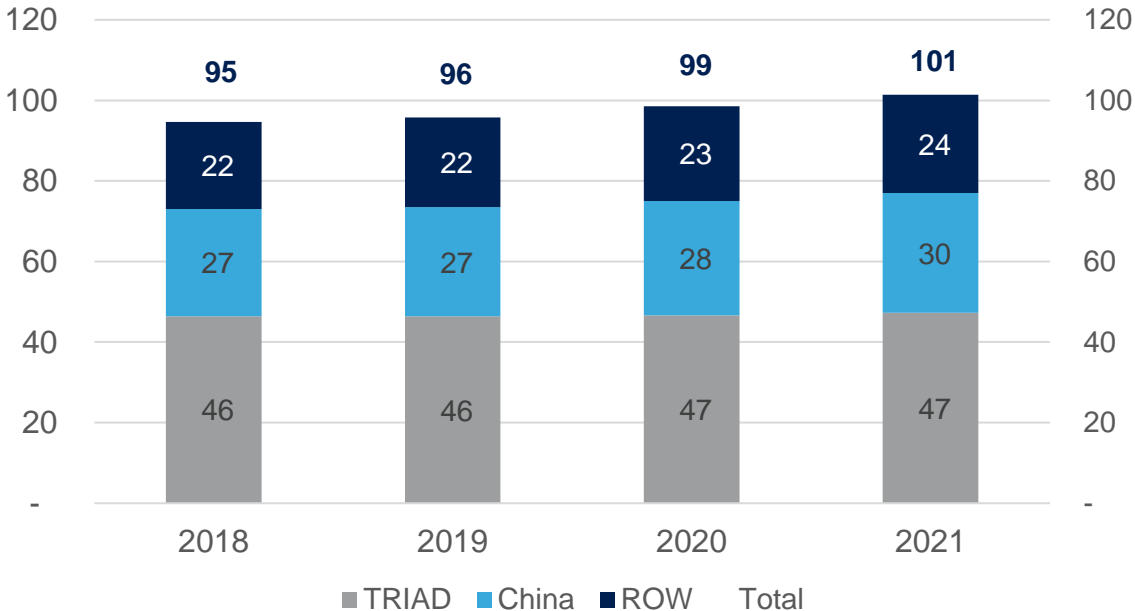
Rank	Analog
1	Texas Instruments
3	STMicroelectronics

Rank	Processors
1	NXP
7	STMicroelectronics

Rank	Sensors
1	Bosch
10	STMicroelectronics

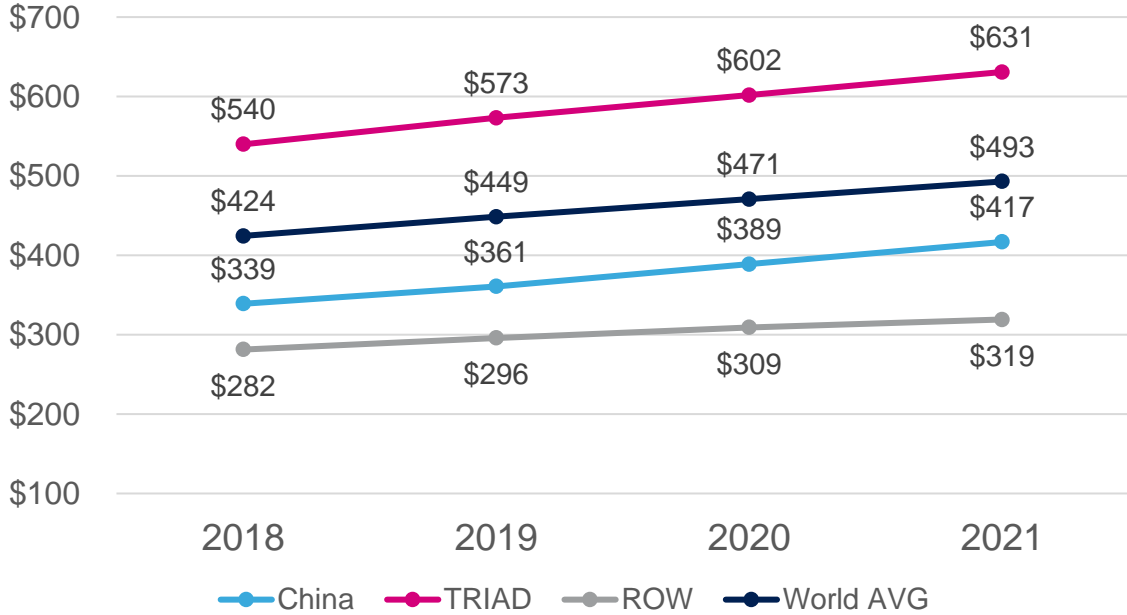
Automotive Market Content and Volume Growth

Vehicle Production (Million Units)



CAGR 2018-2021: **+2.3%**

Semiconductor Content (\$)



CAGR 2018-2021: **+5.1%**

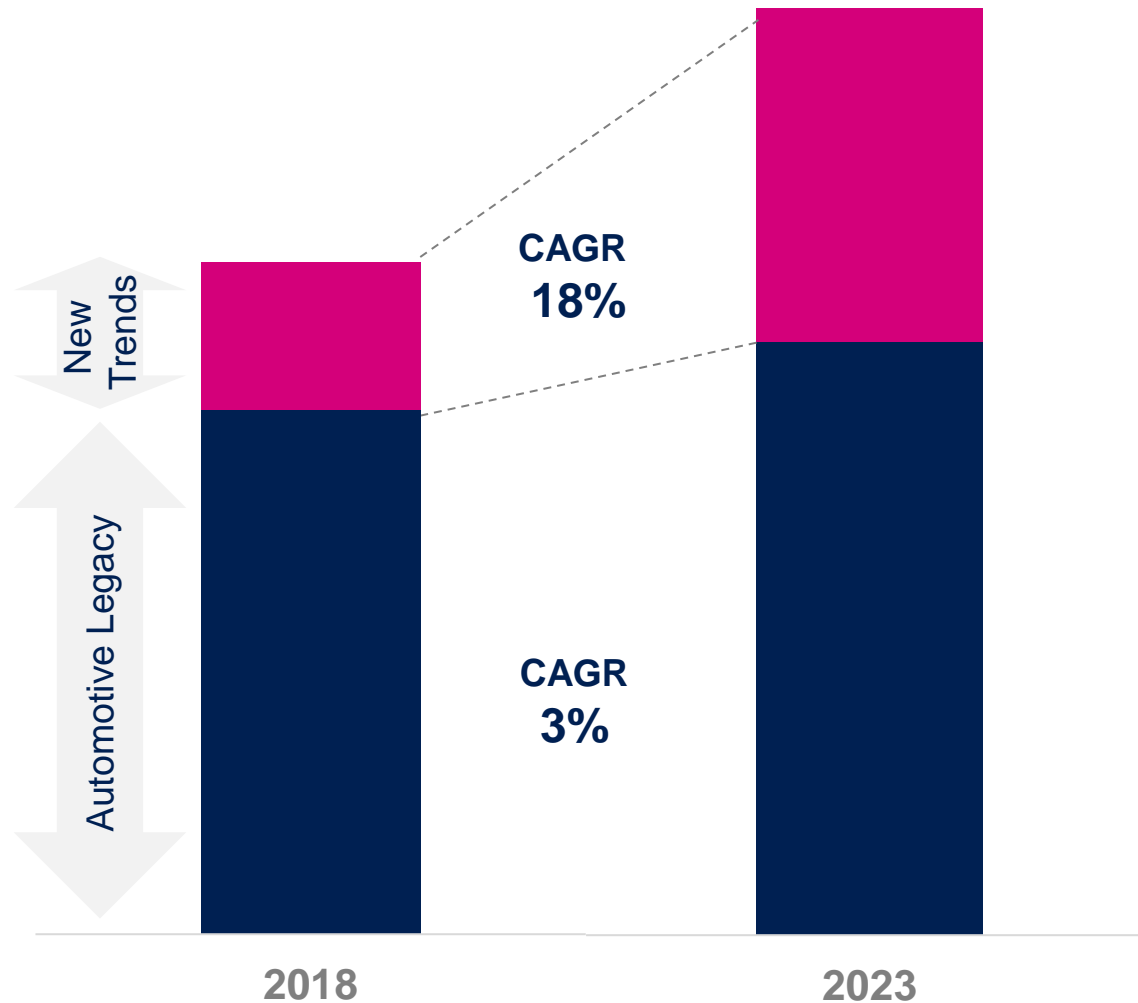
TRIAD : Europe-US-Japan,



Source: Strategy Analytics

Electrification & Digitalization

Driving Growth



Car Digitalization & Car Electrification

Growth driven by silicon pervasion, with smaller impact from growth of car volumes

Automotive Legacy Electronics

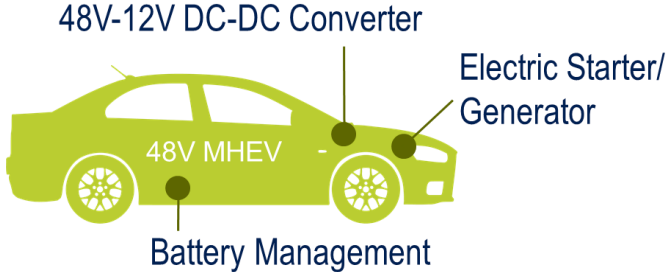
Growth linear with the car volumes
Exposed to market cycles

Car Electrification

ST Leading with Disruptive Technologies

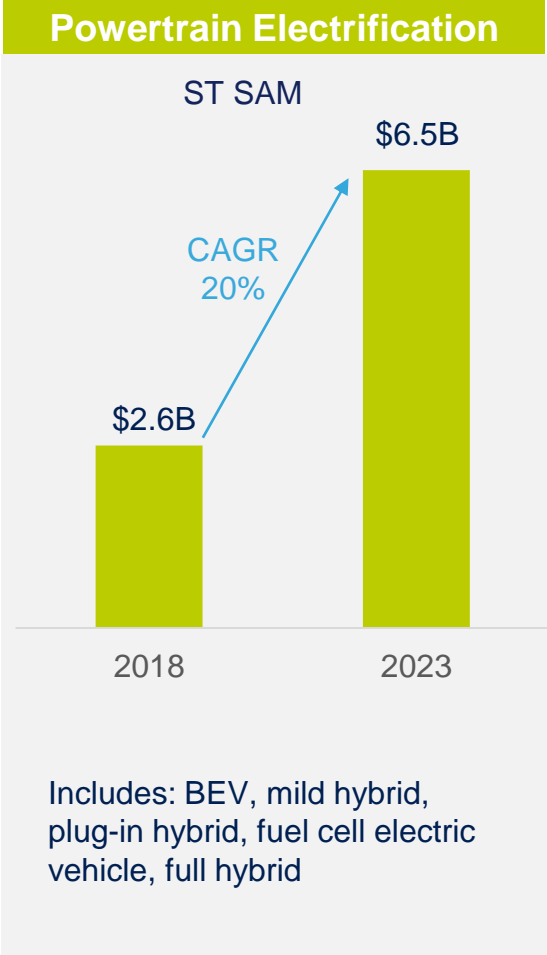
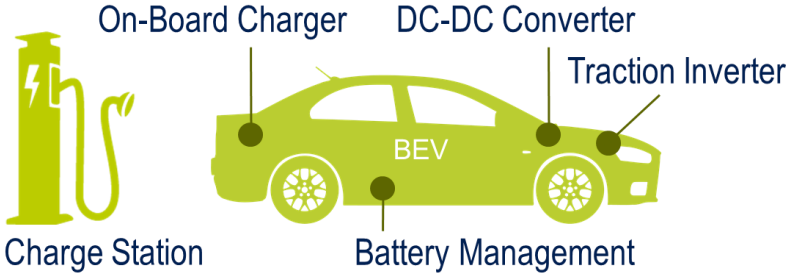
Mild Hybrid 48V

Low-end entry level electrification



Battery Electric Vehicle

High-end battery-based full electric car



Car Digitalization

ST Leading with Disruptive Technologies & Partnerships

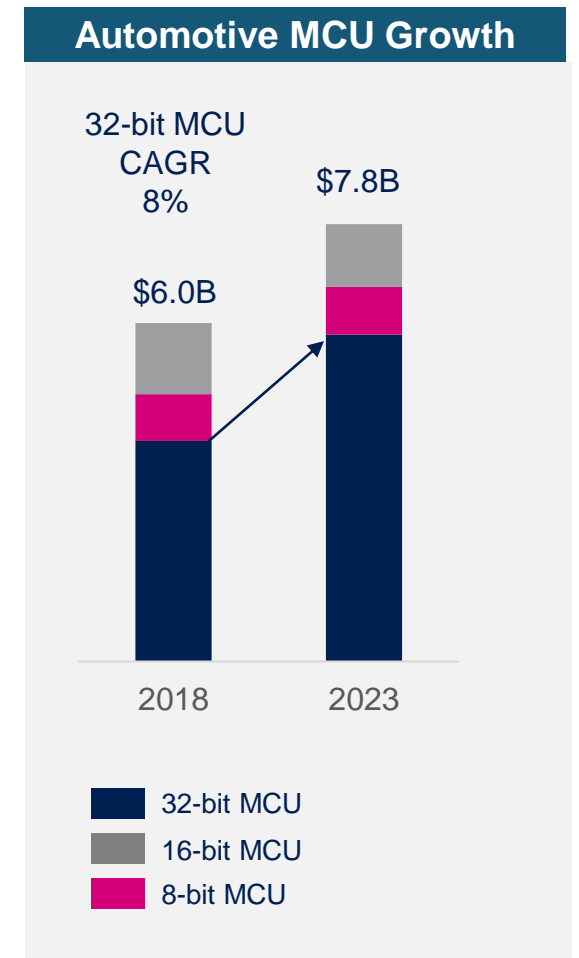
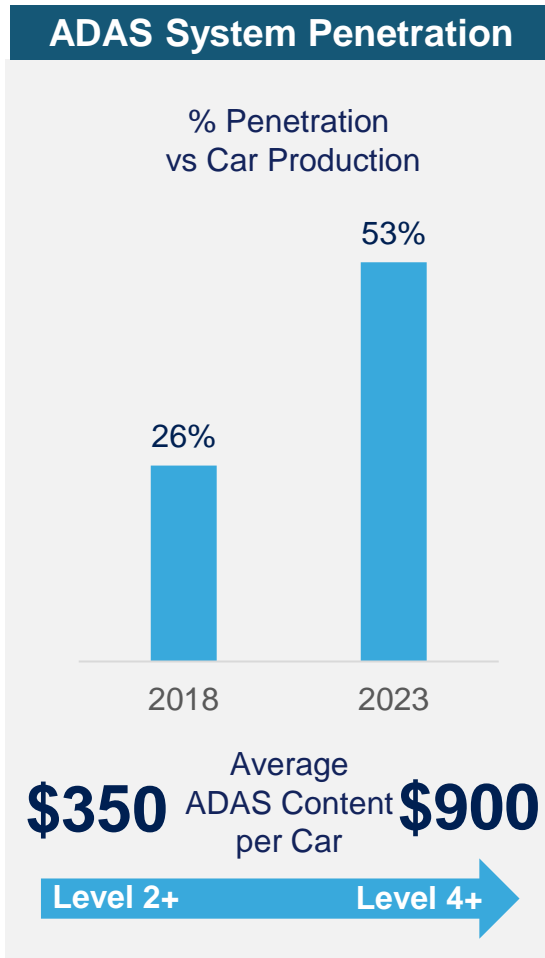
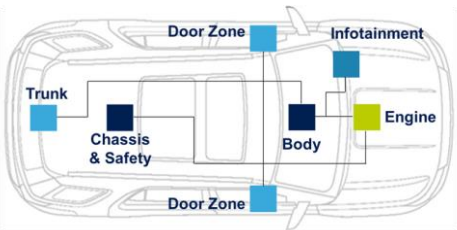
ADAS



Connectivity



Domain controllers



Application Approach

Use deep industrial knowledge to develop solutions optimized for specific applications, combined with a broad portfolio

- Factory Automation
- Motor Control
- Industrial Drives
- Industrial Power & Tools
- Energy Generation & Distribution
- Metering
- LED, General Lighting
- Home, Building & City Automation
- Appliances
- Power Supplies and Converters
- Point of Sales & Retail Logistics
- Medical & Healthcare
- Space, Avionics & Defense
- Smart Farming

Market Approach

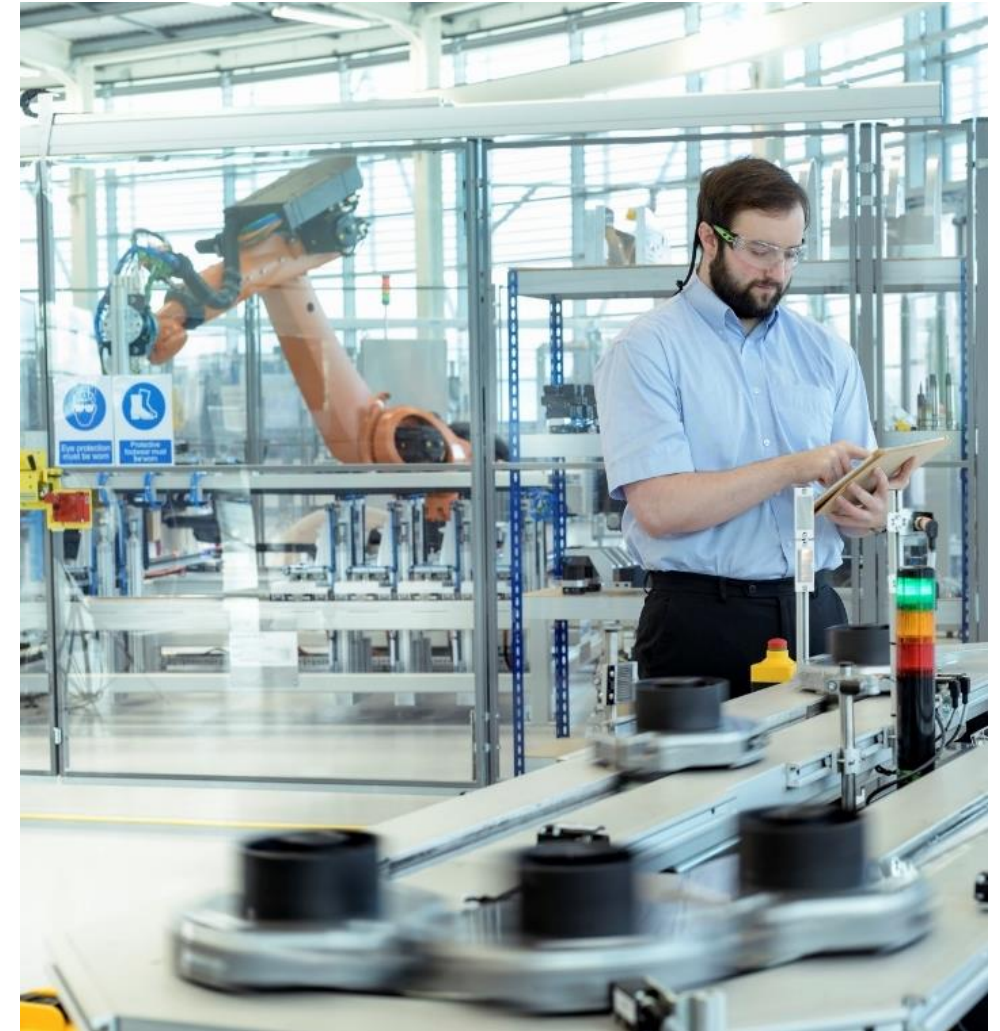
Target industry leaders with leading-edge products adapted to their needs

SIEMENS



PHILIPS

Target wider market with broad portfolio mainly through distribution

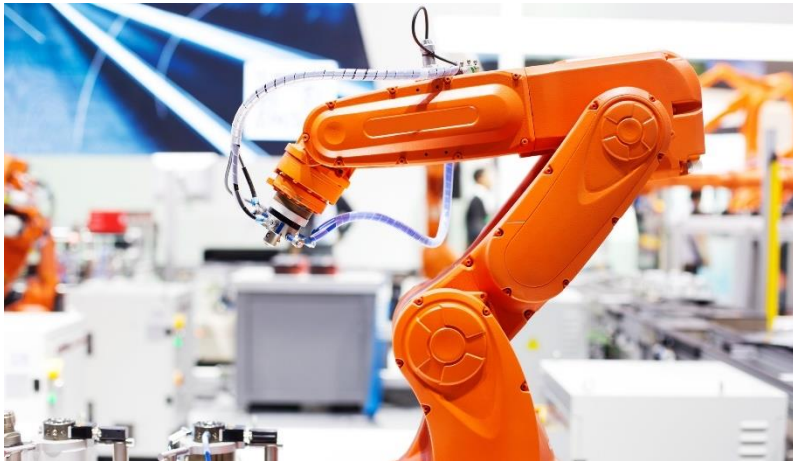


ST Strategy in Industrial

Expand Portfolio and Increase S&M Reach

Strategic Objectives

- Leadership in embedded processing
- Acceleration of growth in analog & sensors
- Expansion in power & energy management
- Acceleration of growth with industrial OEMs



Trends & Market

- Semiconductor content growth driven by automation, need for higher power efficiency, data-centric industrial IoT
- Industrial market highly fragmented with many different applications
- Healthy growth rates across the key applications where ST is focused

ST Approach

- Investing to keep leadership on key technology processes
- Expansion of product portfolio to address key trends and disruptions
- Sales & Marketing reorganized for sharpened industrial focus
- Expanding Field Application Expertise across all regions
- Creating more compelling offer and support for Industrial OEMs as well as for mass market with distribution partners

Industrial Trends

Driving Semiconductor Content



More Autonomous Systems Intelligent & Aware

- Next levels of automation with distributed control
- Safer working environments & new man-machine interaction models
- Artificial Intelligence pervasion



Higher Power Efficiency

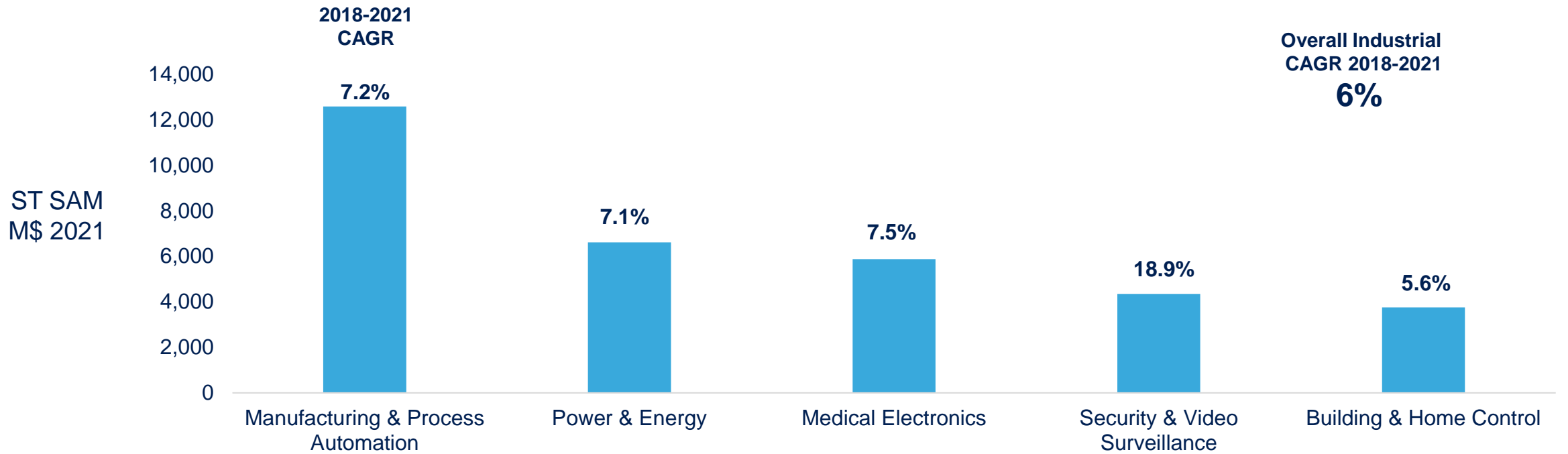
- Higher energy efficiency for industrial machinery and appliances
- Digital power control and optimization



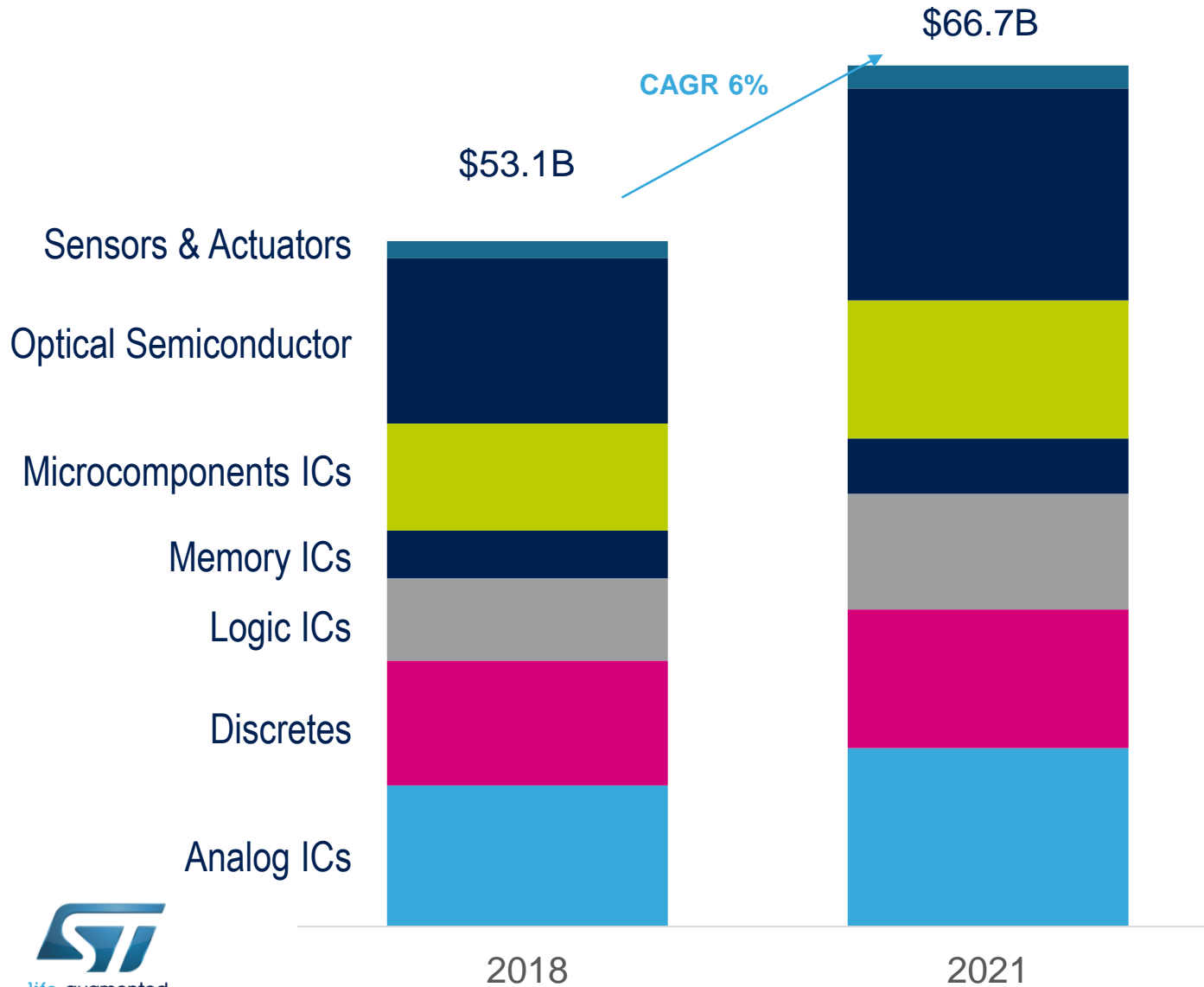
Securely Connected Leveraging the Internet of Things

- Connection of machines inside the factory and to the cloud
- Capture & exploitation of machine condition data for predictive maintenance

ST Focused on Highest Growth Industrial Applications



Industrial Semiconductor Market



Rank	Power Discretets
1	Infineon
2	STMicroelectronics



Rank	Analog IC
1	Texas Instruments
3	STMicroelectronics



Rank	Microcomponents
1	Intel
4	STMicroelectronics



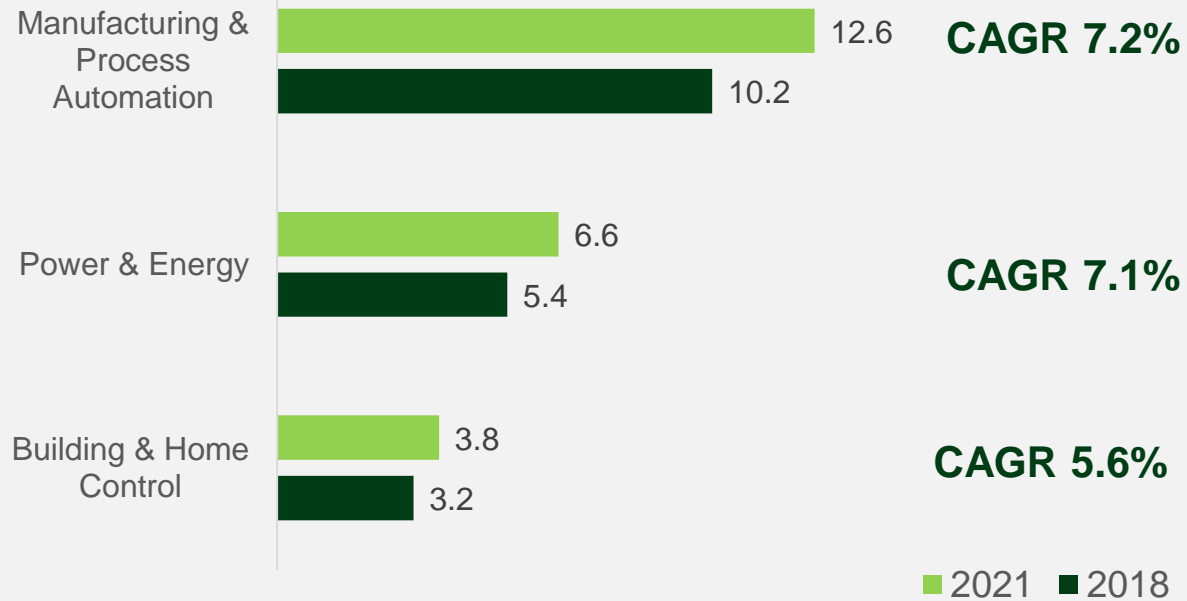
Rank	Sensors & Actuators
1	Analog Devices
9	STMicroelectronics



Power Semiconductors

a Key Enabler of the Industrial Applications

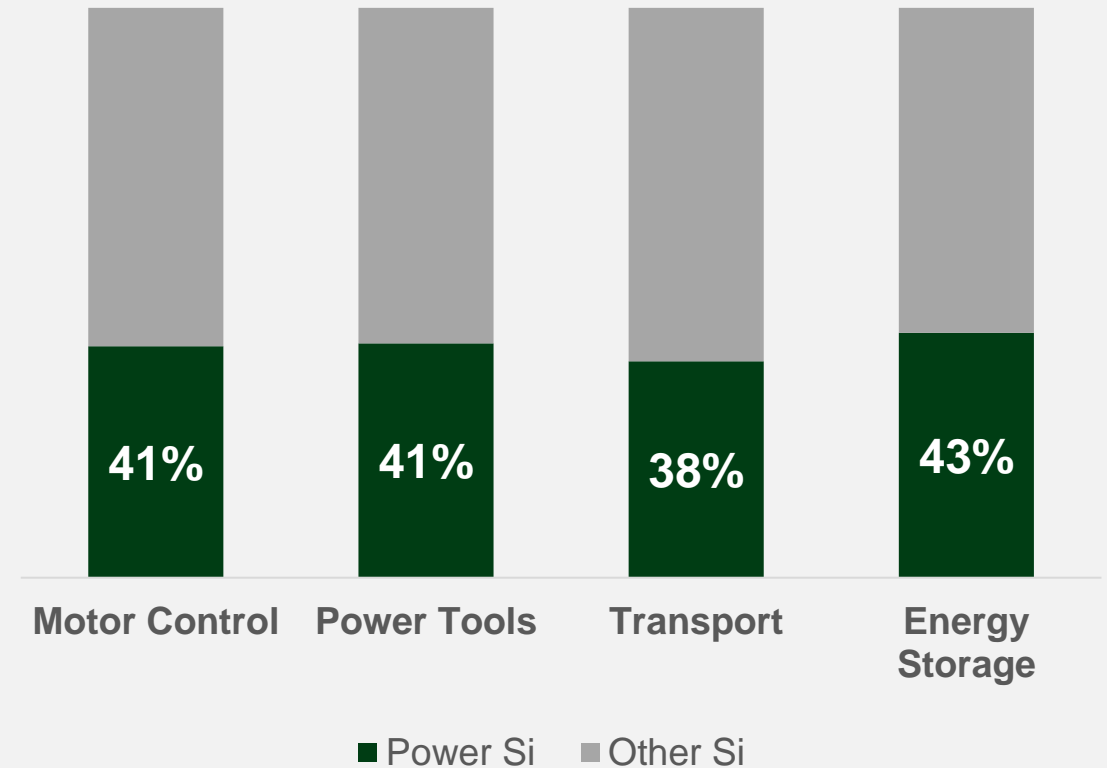
Fast Growing Industrial Applications



>25%
average

Power & Discrete Silicon Content

Applications with very high Power Silicon Content



Personal Electronics

Application Approach

- Smartphone application-specific products also suited for other personal devices
- General purpose portfolio for broader PE market

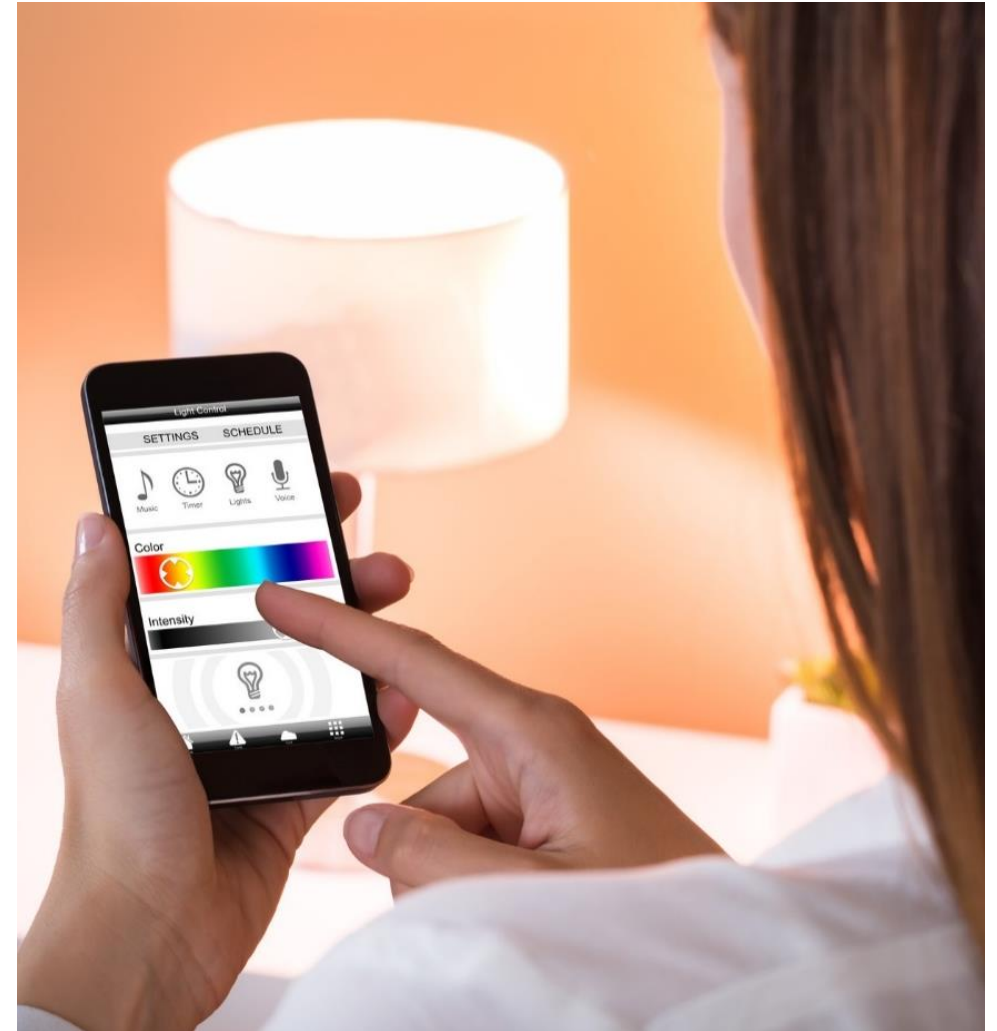
- Smartphones
- Tablets & eReaders
- Wearables
- Personal Care & Hygiene
- Gaming
- Drones
- Audio & Video
- Virtual/Augmented Reality

Market Approach

Dedicated products for Top Smartphone Players



Market leading products for other players



ST Strategy in Personal Electronics

Highly Selective Approach for Technology Leadership

Strategic Objectives

- Leadership in selected high-volume smartphone applications: sensors, secure solutions, power management and analog
- Capture opportunities in 5G



Trends & Market

- Smartphone volumes flat but content growth in specific peripheral areas: user interface, power & energy management, security and 5G RF
- 5G handsets fast growth within flat overall volumes
- Other personal devices using same architecture and peripheral components as smartphones

ST Approach

- Investing to keep technology and product leadership in selected areas
- Focus on 5 areas in Smartphones
 - Specialized Imaging Sensors
 - MEMS Sensors
 - Secure Solutions
 - Power management
 - 5G RF
- Leverage portfolio to address other personal devices

ST Smartphone Content Focus

Power Management

Wireless charging, USB-C, Display PMIC



Sensors & Actuators

3,6-axis, OIS* gyroscope, pressure, temperature



5G RF

Front-End Module



Specialized Imaging Solutions

Depth/3D sensing (ToF, Sensors)



Communications Equipment, Computers & Peripherals

Application Approach

Use deep knowledge of specific applications to develop dedicated products leveraging differentiated technology capabilities & IP portfolio

- Telecom and mobile (4G/5G) Infrastructure
- Advanced RF Amplifiers and Antennas
- Data Centers
- Enterprise Switching
- SOHO Servers
- Computers & Peripherals

Market Approach

Leverage long-standing relationships with networking & computer peripheral makers



Selected customer & product opportunities for networking and satellite communications



Partnerships to address specific technologies/markets



ST Strategy in CECP

Leverage Mixed Signal Technologies, Focus on Wireless

Strategic Objectives

- Transform approach to communication infrastructure: from digital wireline to mixed signal RF for cellular and satellite
- Capture opportunities in 5G with RF mixed signal

Trends & Market

- 5G driving a disruption in the communications market
- Need for new advanced technologies meeting the performance requirements
- Low Earth Orbit (LEO) Satellite communications needs similar technology

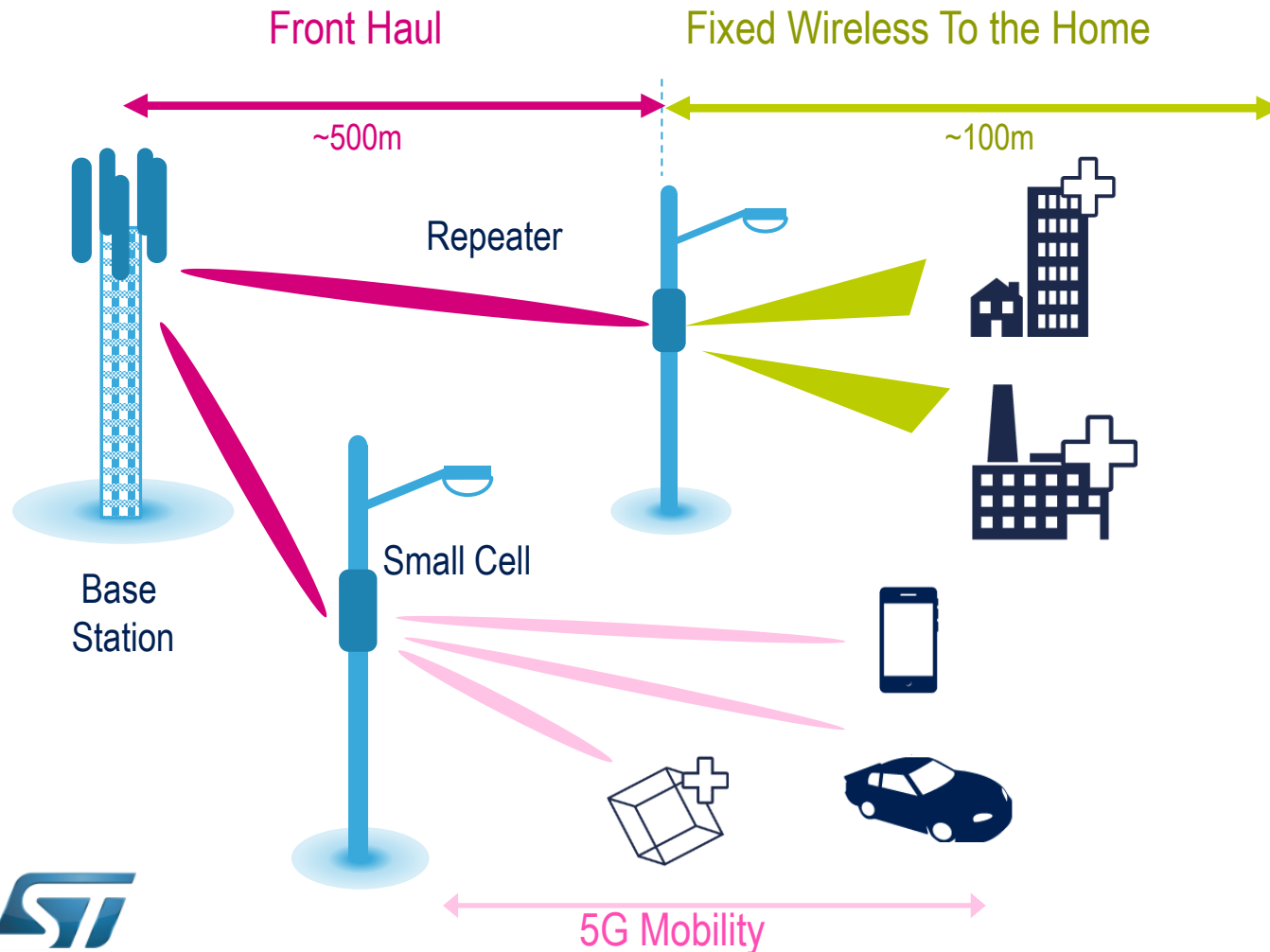
ST Strategy

- Leverage specific ST mixed-signal technologies to take advantage of opportunities in 5G and Satellite communications
- Continue traditional businesses where we are a leader such as power management for data storage



The 5G Disruption

5G mmW Network Infrastructure



- Very high data rate – **x100***
- Reduced latency – **5 times lower***
- Very high reliability – **99.999%** * vs 4G
- Connections of **billions** of nodes
- Improved coverage

- **New architecture** with denser network (small cells)
- **New technologies:** Advanced beam forming, massive MiMo
- **New spectrum:** Use of millimeter wave

5G Will Drive Growth Opportunities in all End Markets

Automotive

Industrial

Personal Electronics

Communications
Equipment,
Computers & Peripherals

V2X
Infotainment & Telematics
Autonomous driving



Industrial IoT using 5G



Smartphones & other
connected personal devices



5G Basestations &
Repeaters



Opportunities for ST

Driver for digitalization
(ADAS, Vehicle Connectivity)
and architecture change in
the car

Many more Smart Connected
devices requiring embedded
processing with integrated
connectivity & security +
sensors, power, ..

5G RF in Smartphones
requiring high performance
front-end components

Technology for mmW
Communication links

RF GaN, RF-SOI

Power management for
basestations

Takeaways

- ST well positioned to grow faster than our served market
- Leveraging technology disruptions to grow with ST proprietary processes
- Sharpened Industrial focus, Automotive content growth and highly selective in our approach to other end markets



Automotive and Discrete Group

Marco Monti

President
Automotive and Discrete Group



37%

ADG Contribution to ST


Automotive and Discrete Group 2018 – Key Financial Figures

ADG 2018 Revenues

\$3.56B
2018 Net revenues

ADG +16%
2018 vs. 2017

ADG by Sub-Group

 **Automotive Product Sub-Group**

\$2.22B

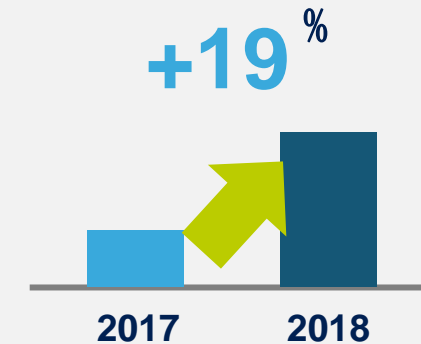
2018 Growth Rate



 **Power Discrete Sub-Group**

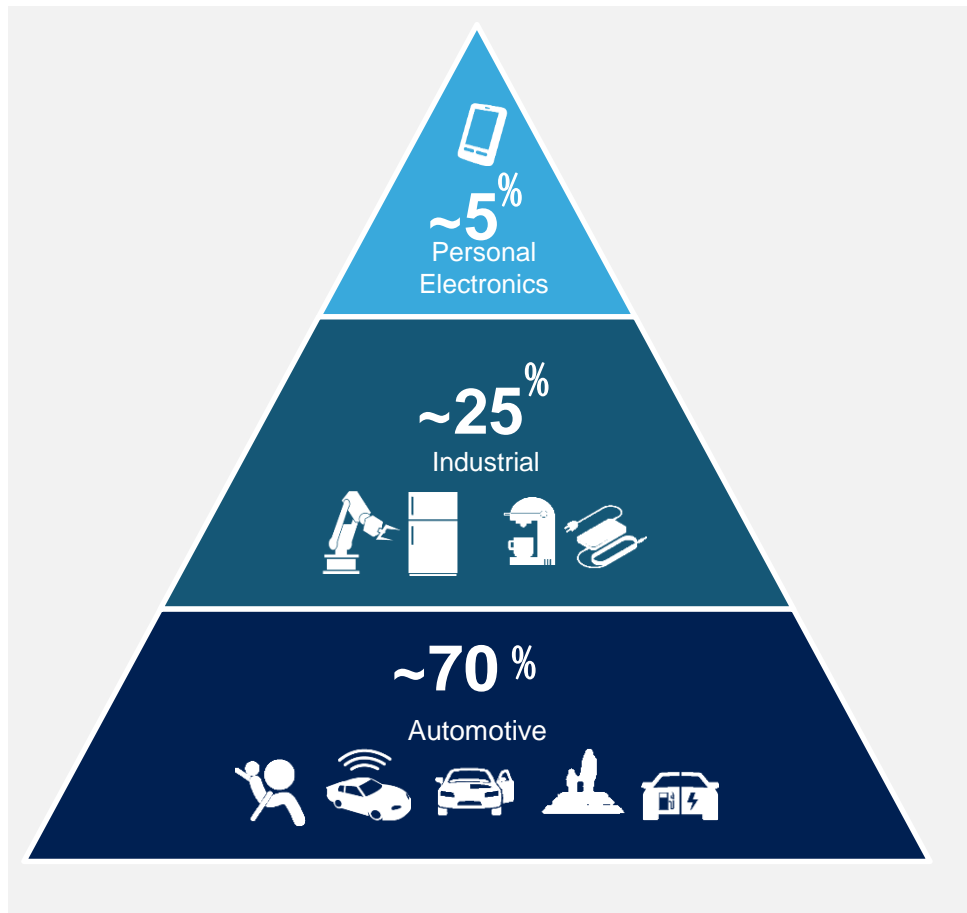
\$1.34B

2018 Growth Rate



End Markets Coverage and Strategy

ADG Market Coverage(*)



(*): % of FY'18 ADG Revenues

Automotive

Main ST growth drivers and application focus:

- Electrification, Assisted and Autonomous Driving (ADAS)
- Car architecture change: Domain control

Key ST Technologies

Smart Power (BCD, ViPower), SiC & GaN MOSFET, IGBT, LV & HV MOSFET, 28nm FD-SOI & Phase change memory (P28), 7nm FinFET (foundry)

Industrial

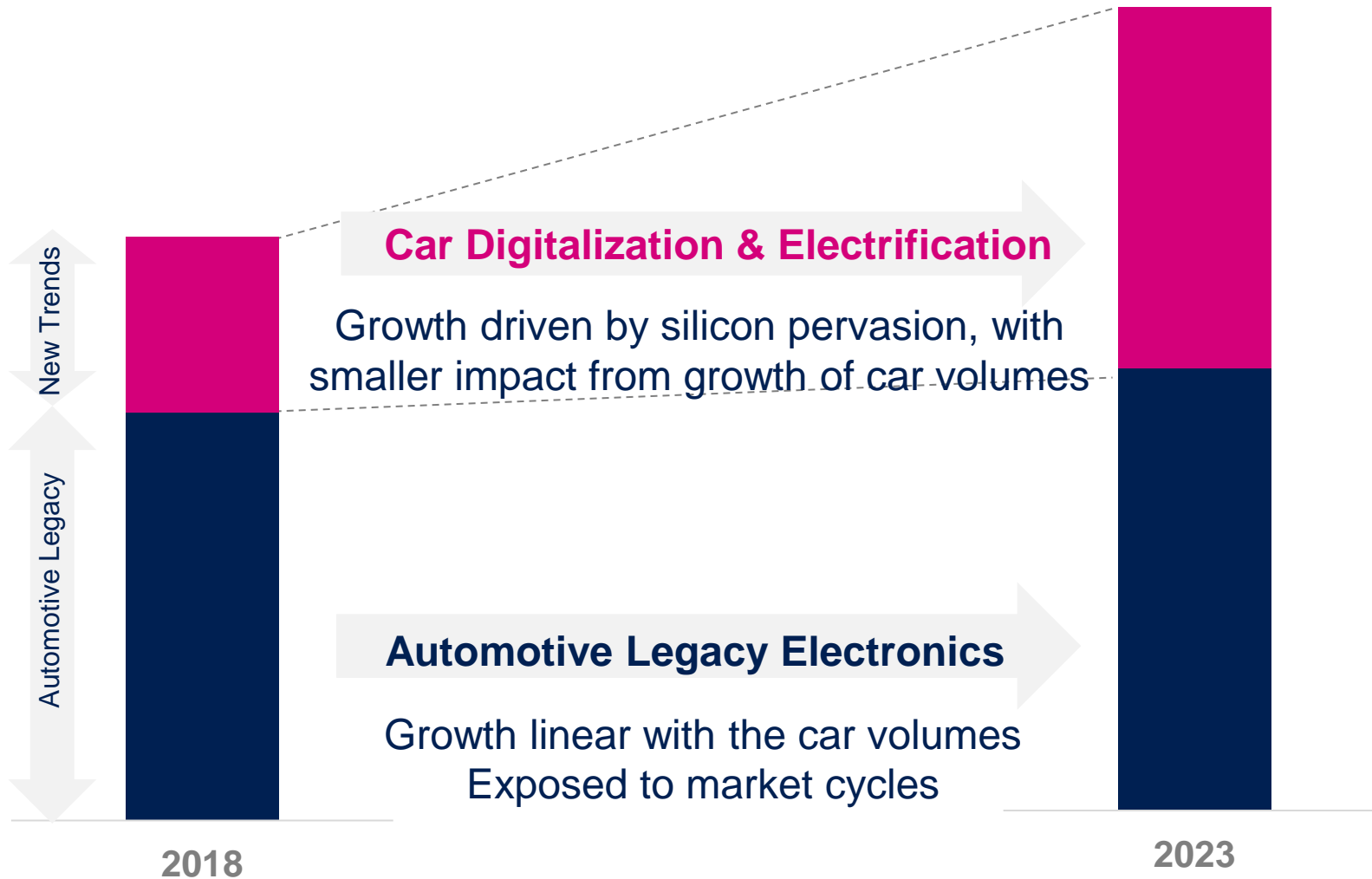
Main ST Growth Drivers and Application Focus:

- Energy Conversion and Storage,
- Factory Automation (Motor Drive),
- Lighting
- Power Tools...

Key ST Technologies

HV MOSFET, IGBT, SiC & GaN MOSFET, Power Module & IPM

Automotive Semiconductor Market Dynamics



Car Electrification
CAGR '18-'23: ~24% **x9**

Car Digitalization
CAGR '18-'23: ~14% **x5**

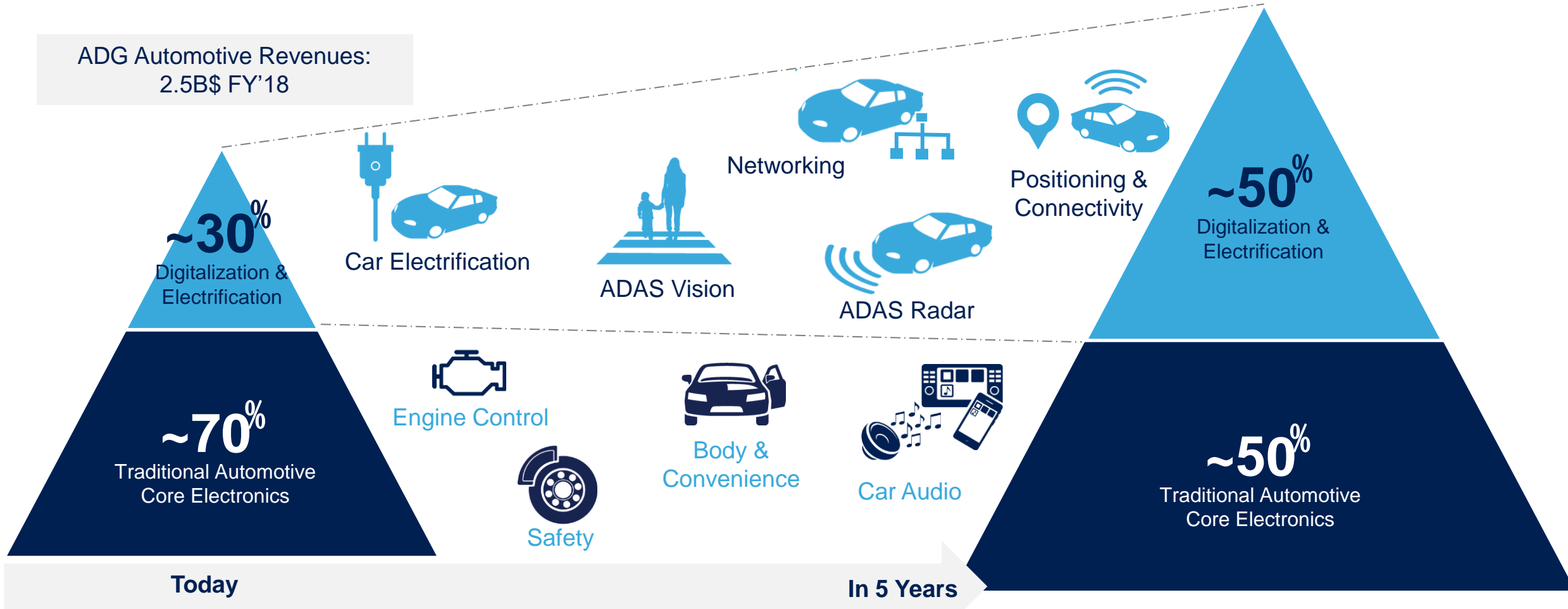
Light Vehicle Production:
CAGR '18-'23: 2.6%

Car legacy Electronics
CAGR '18-'23: 3.5%

ADG Automotive Business Evolution

Digitalization & Electrification Driving ADG Growth

ADG Automotive Revenues:
2.5B\$ FY'18



ADG Outperforming Automotive Market

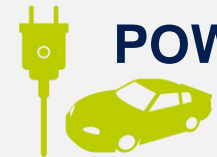
2018 ADG Vs. Auto Market Growth

 **+18%**

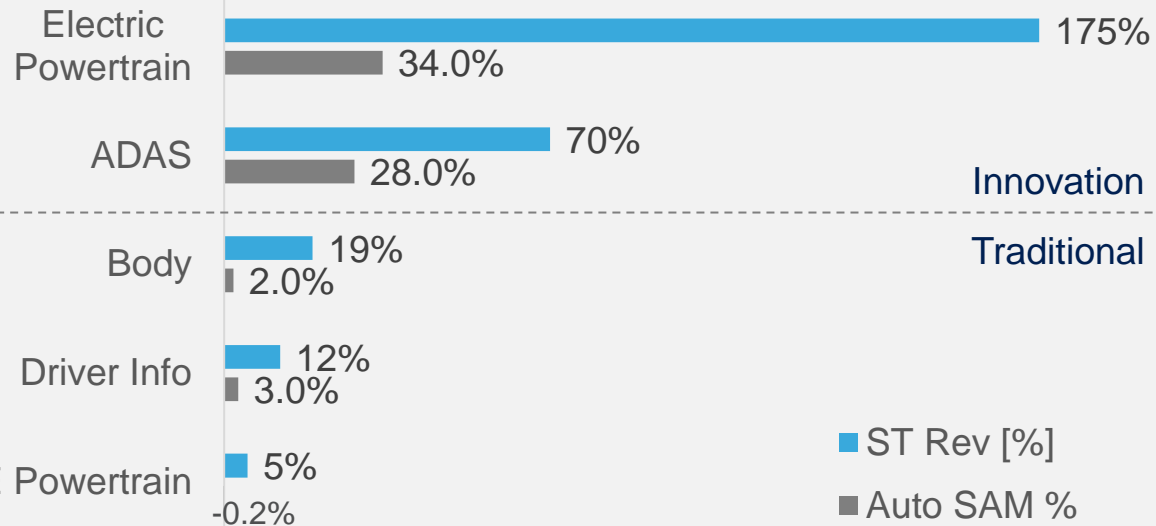
Growth Rate
x2 Vs. Semi Auto TAM

Highest Growth
Vs. Top-10 Semi Auto Vendor

ADG Outperforming Market on Automotive Megatrends

ELECTRIC POWERTRAIN


Traditional Silicon Power (*)
>150%
FY'18 Revenue Growth



ADAS



Vision Processor

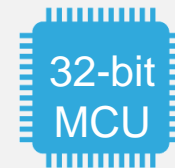
>70%

Radar Solutions(**)

>30%

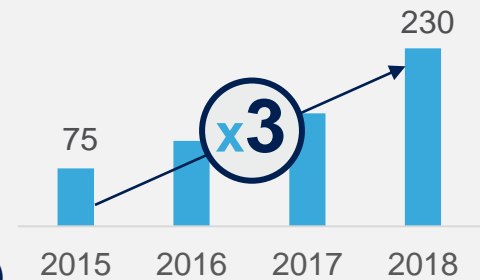
FY'18 Revenue Growth

MICROCONTROLLER



>50%

FY'18 Revenue Growth (\$M)



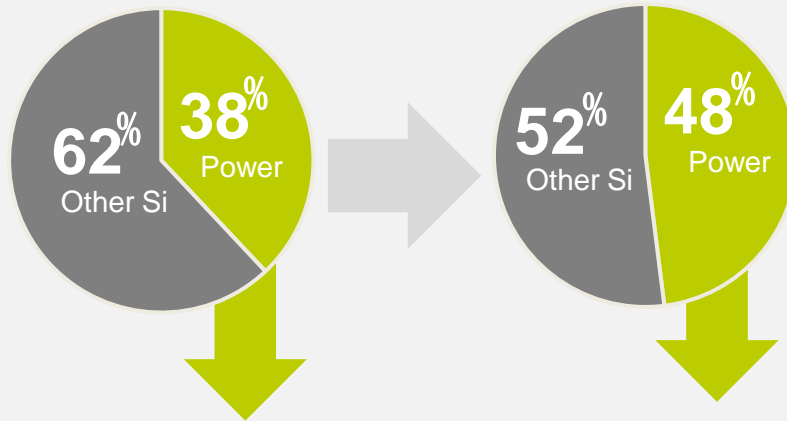
Source: Strategy Analytics

Car Electrification Boosts Power Content

Powertrain TAM Evolution

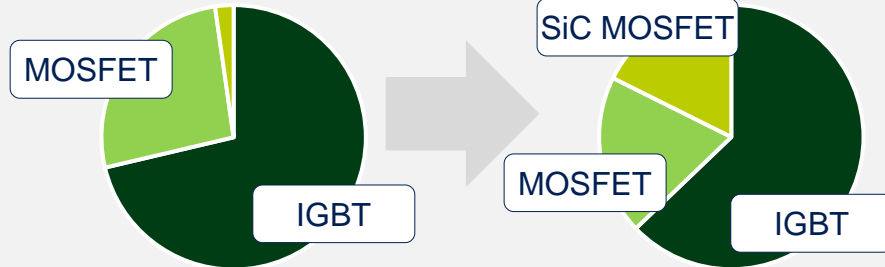
2018

2023



2018

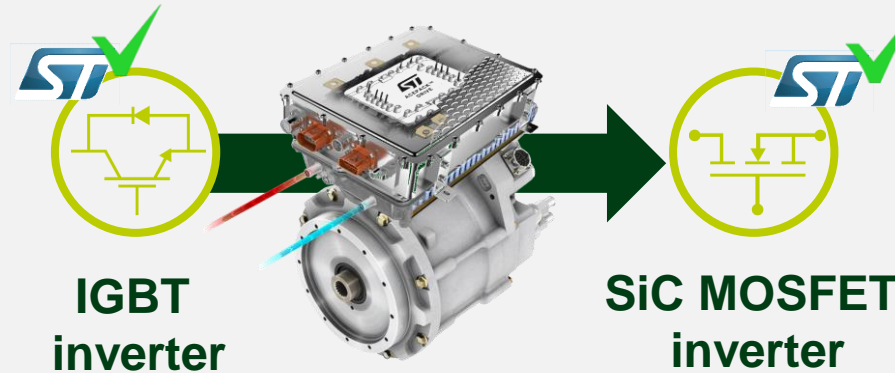
2023



IGBT and SiC MOSFET inverters will co-exist for several years

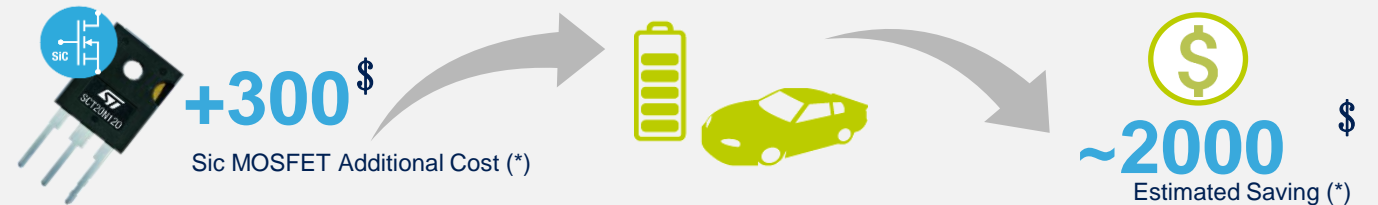
SiC MOSFET Vs. IGBT Advantages in Traction Inverter

Electric car motor and inverter

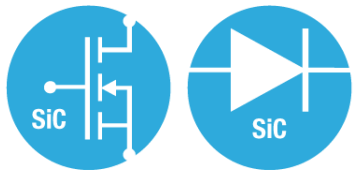


- 80% switching loss saving
- Direct inverter integration
- No separate liquid cooling
- Better thermal management
- Faster charging time

Potential saving thanks to SiC MOSFET usage in electric car



SiC MOSFET market size by 2030 estimated to be > 10B\$
representing ~50% of the incremental growth of power semiconductor in 2019~2030



ST Silicon Carbide

In Line with our Target of >30% Market Share by 2025

Silicon Carbide: Business Status

>\$100^M >\$200^M

SiC MOSFETS /Diodes Revenues in 2018

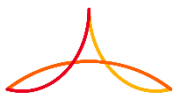
2019 Projection

#1 WW **Automotive** Supplier with SiC MOSFETs

Awards rate acceleration: More than **20 Car Makers** engaged

>10[#] OEM in production with ST SiC MOSFET

8 **European Car-Makers** ramping-up by 2019-20



RENAULT NISSAN MITSUBISHI

Partnering with **Renault Nissan Mitsubishi** on several SiC projects



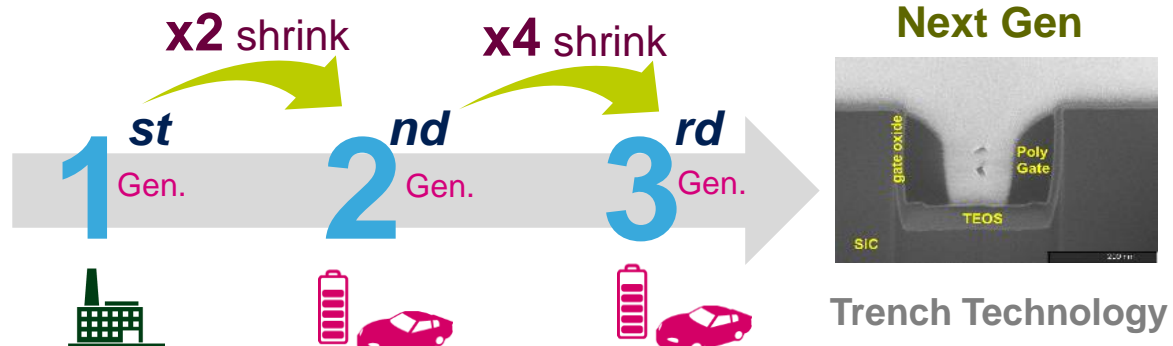
HYUNDAI

Cooperating with **Hyundai Kia Motor** on several **SiC MOSFET & Diodes**



life.augmented

ST Strategy and Execution



SiC Supply Chain

Vertical Integration Norstel AB

ST acquired majority stake to secure **Internal Supply** for SiC wafer substrates

Extended and Secured Supply Chain capability through Multi-Year supply agreement with **Cree-Wolfspeed**

Silicon Power Innovation

Electrification Beyond Silicon Carbide

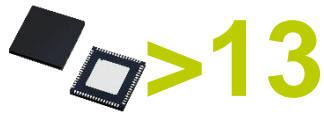
Battery Management up to 800V to support the Chinese electrical mobility market

Innovative cell monitoring architecture in cooperation with ~10 Chinese car makers and IMECAS as part of “China 2025” national program - Production start Q4 2019

Lithium cell monitoring

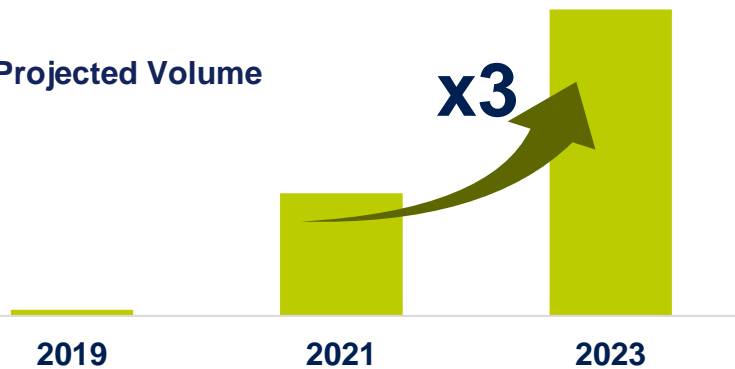


Devices per Vehicle



Suitable for **Hybrid** and **Full** Electrical vehicles

Projected Volume



IGBT for EV applications

> 15 OEMs in production in '19

Multiple projects-wins in EV applications with new IGBT Trench Technology

Agrate Fab

300mm



Investing in new Facilities to sustain **Power Silicon** solution growth

ST-IGBT
>30%
FY'18-'23 CAGR



Solution for Mild-Hybrid vehicle (48V)

Tailored Low Voltage **MOSFET** suitable for **48V systems**

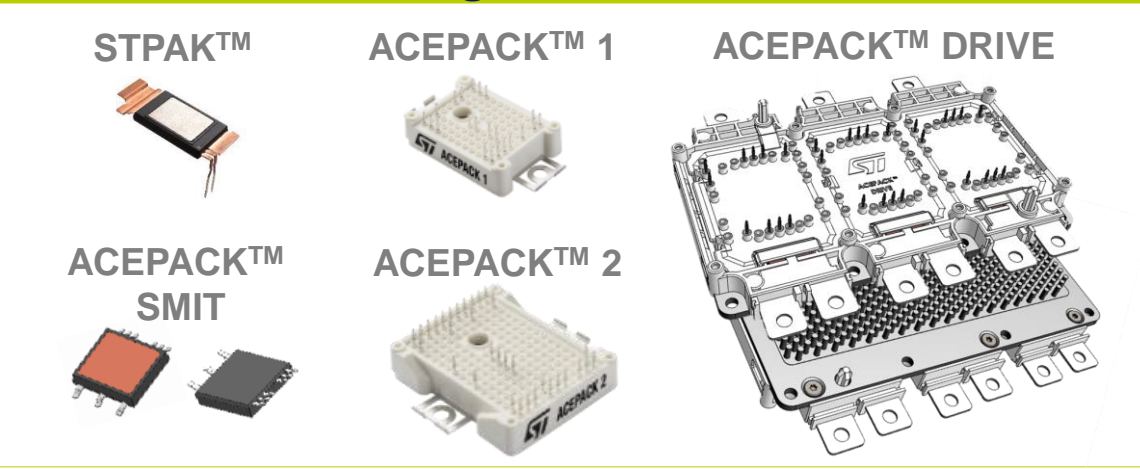
➔ Already in production in multiple Hybrid Cars with Top Car Makers in EU, US and Asia

New VIPower™ intelligent power switches for Mild Hybrid:
48V Power Distribution and **Motor Control**
Targeting market leadership

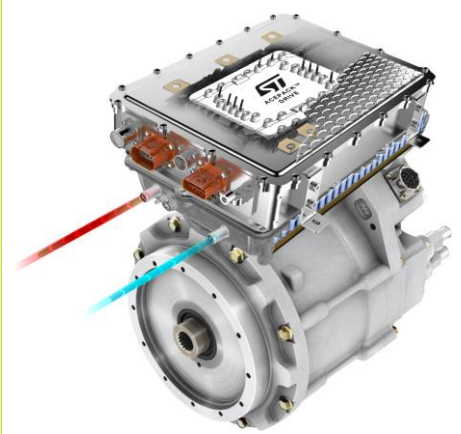
Power Modules

Standard & Custom Solutions Targeting Market Leadership

Broad range Module Portfolio



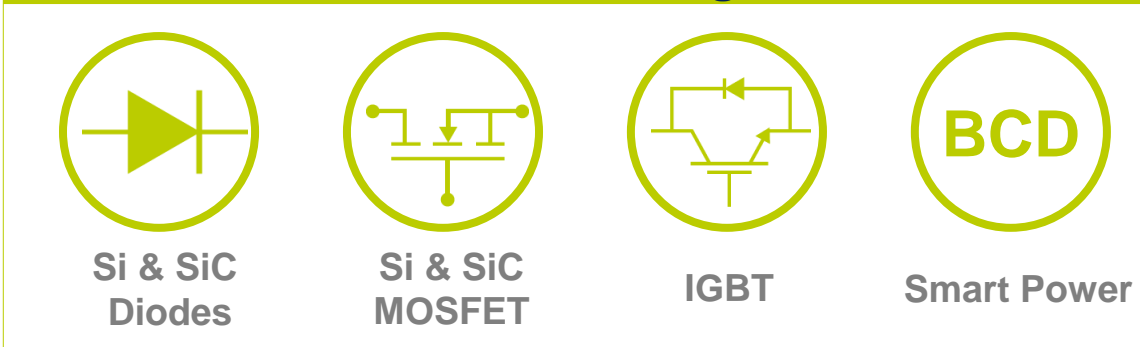
Standard & Custom System Solution



STANDARD Portfolio

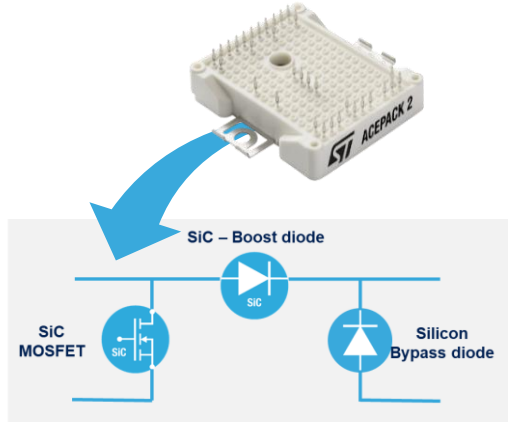
Plug&Play Module for Traction inverter, On-Board Charger and DC-DC converter

Silicon and SiC Technologies Portfolio



CUSTOM Solutions

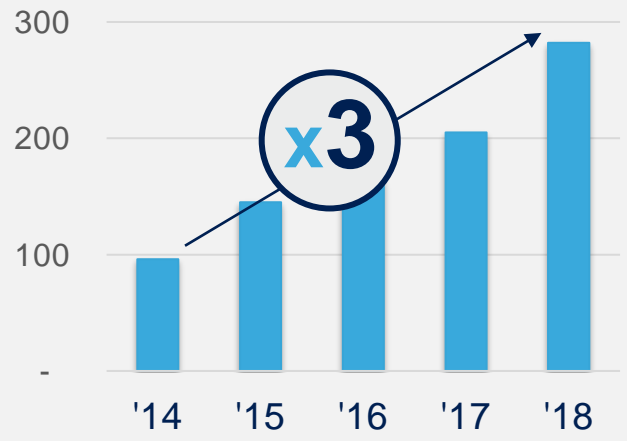
Combining semiconductor and package technologies addressing multiple design topologies tailored to specific customer needs



ADG Leading ADAS Market

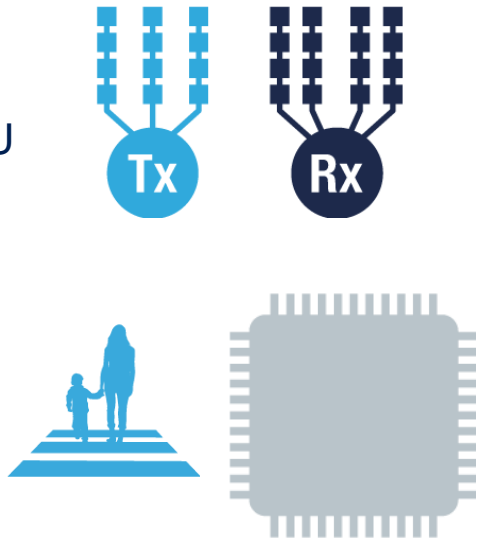
Market Leadership in Core Functions ADAS-Specific ICs Solutions

ADG ADAS Solid and stable revenue growth (\$M)

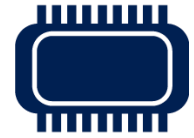


x2
Doubling Business
by 2023

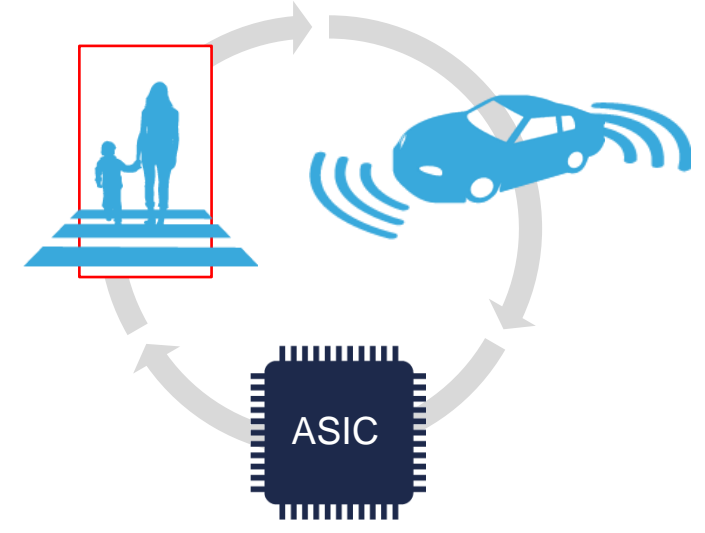
RADAR
MMIC Transceiver & MCU



ASIC Smartpower
Sensor Interface
ADAS-specific Voltage Regulator



>30%
Market Share(*)



Source: Strategy Analytics, ST Internal

(*) Share on ADAS-SAM including Processor, MMIC, Application Specific

Active Safety and Autonomous Driving

Multiple ST Developments Supporting Silicon Content Increase in ADAS Systems

Leading Vision-based system with Mobileye



78[#]

2018 new car models launched

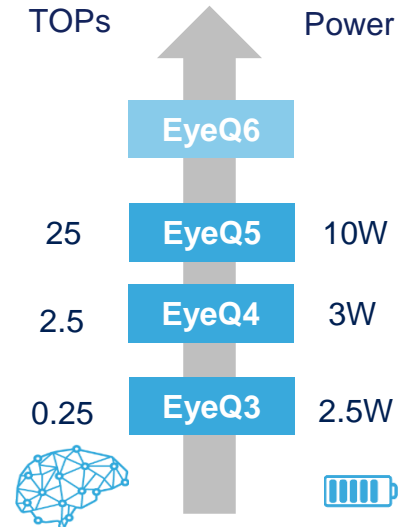
32^M

Mobileye EyeQ systems delivered to OEMs globally

EyeQ5

- 1st product designed for Automotive in 7nm FinFET suitable for both ADAS and Autonomous Driving market
- Functional samples delivered to customer in Dec 2018
- High volume business already acquired with car makers

Today under field test



Moving towards autonomous vehicles with Auto-parking ability

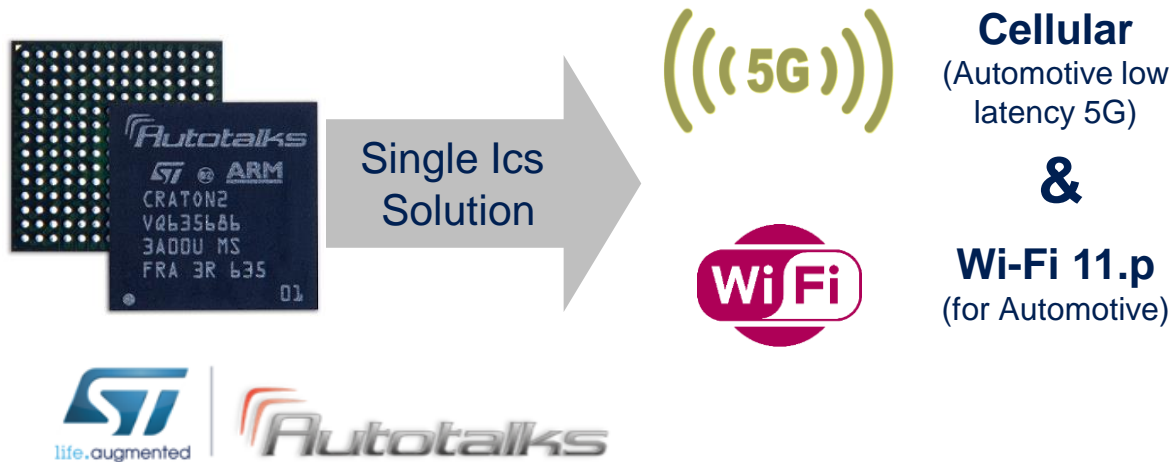
Panasonic

- Advanced solution for mobility and Autonomous Parking
- Co-development leveraging ST Expertise in designing safe and secure Automotive SoCs and Panasonic leadership in image manipulation and system design
- 16nm technology samples delivered

ADAS Beyond Vision

Leading Innovation with 5G Cellular V2X and High Precision GNSS

Market 1st dual-mode solution supporting
5G Cellular V2X

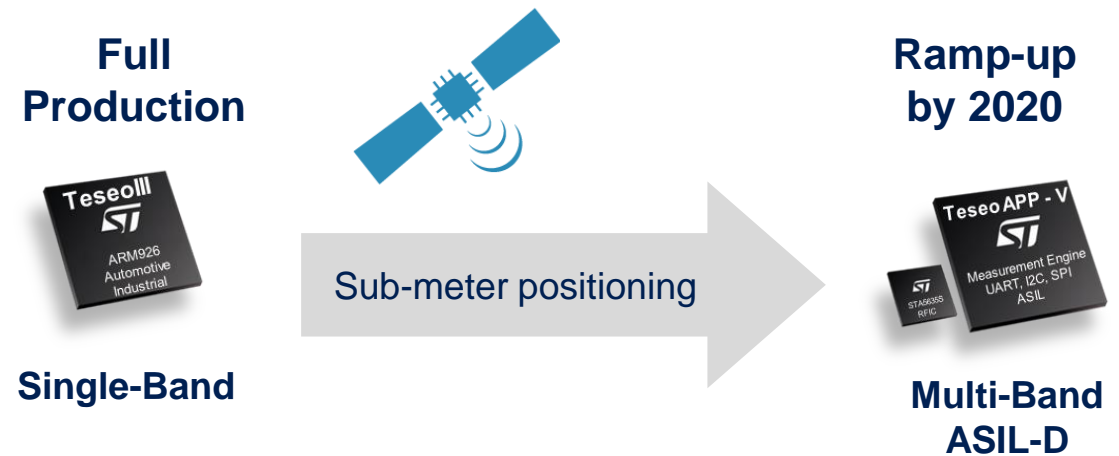


Autotalks solution awarded for production:

- 4 of the top 10 automakers deploy Autotalks V2X solution
- > 10 Tier1s selected the chipset
- Volume production by 2020



TESEO APP: Precise Positioning enhancing
Assisted and Autonomous Driving



- Sub-meter positioning for Assisted Driving
- Multi-constellation(*) system including now Indian System (NAVIC) with 3 customers certified with ST solution (1st in the market)
- Enabling ADAS (Tolling, Insurance Box, Assisted Driving...)

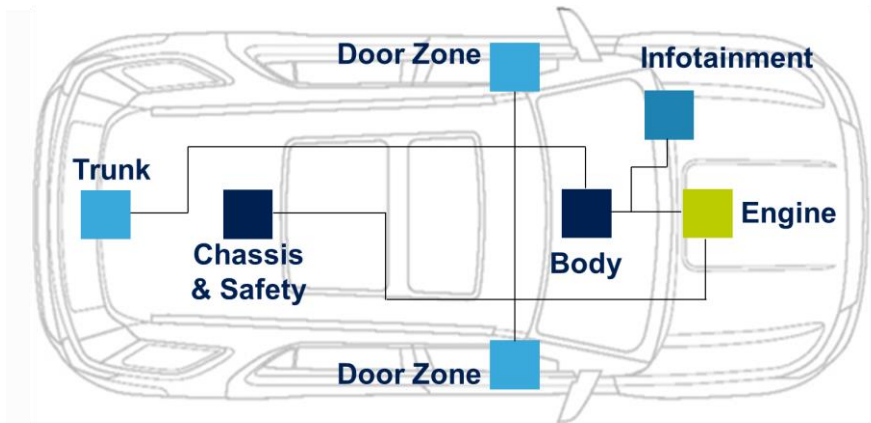
(*) GPS, Galileo, Glonass, Beidou, NAVIC, QZSS

Car Digitalization: New Architectures

...Software accounting for 30% of vehicle value by 2030

ST Technology enablers: FD-SOI 28nm with embedded Phase-Change Memory (PCM)

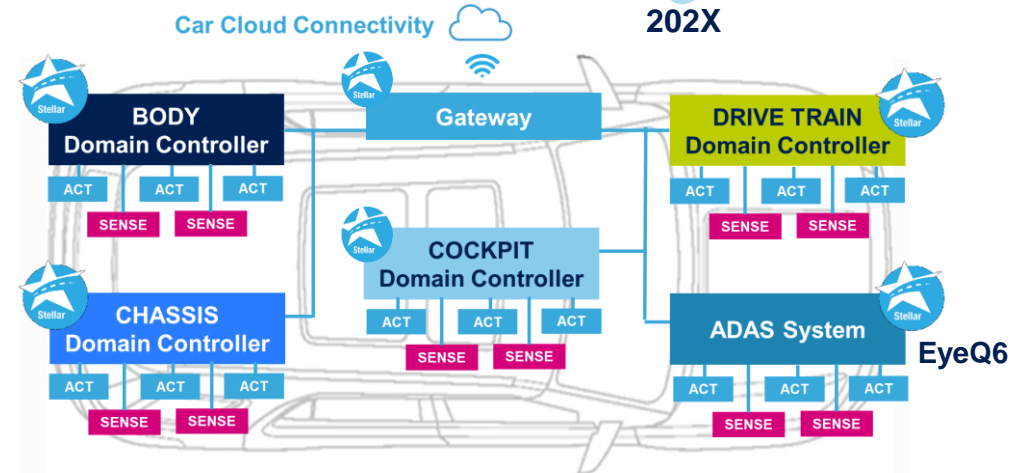
2017



x10

Car Computational Power

202X



Distributed Architecture: 9k DMIPs per Car

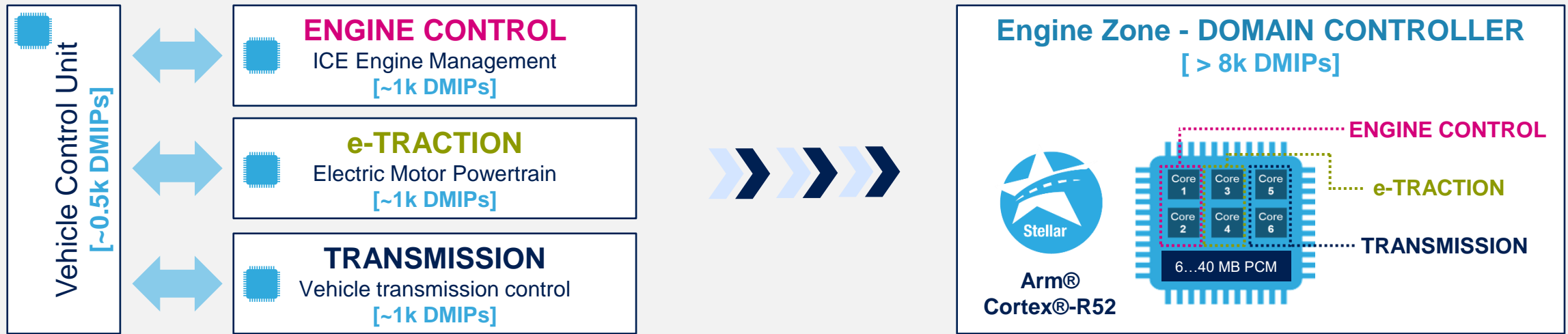
- Local Control Units with up to **130 ECUs/Car** (with 8-16-32-bit MCUs)
- Limited connectivity and in-vehicle data flow (up to 10 Mbit/s)
- Heavy and expensive harness
- Extremely complex car software management
- No car functionality upgrade

Integrated Real-time Domain Architecture: 90k DMIPs per Car

- ~5 Domain-Control Units with higher power computation: **+30% Silicon Value**
- **Stellar** with multiple Arm® Cortex®-R52 cores embedded Phase-Change Memory (PCM)
- Autonomous Driving Super-computer (MPU ext. Memory) **~100 Trillion Operations per second**
- Architecture simplification, SW rationalization, harness drastic reduction
- Easy car functionality reconfiguration and SW upgrades
- High-speed in-vehicle communication
- Over-the-Air Software upgrade capability

...from ECUs to Domain Controllers

Example: Evolution for Vehicle Traction



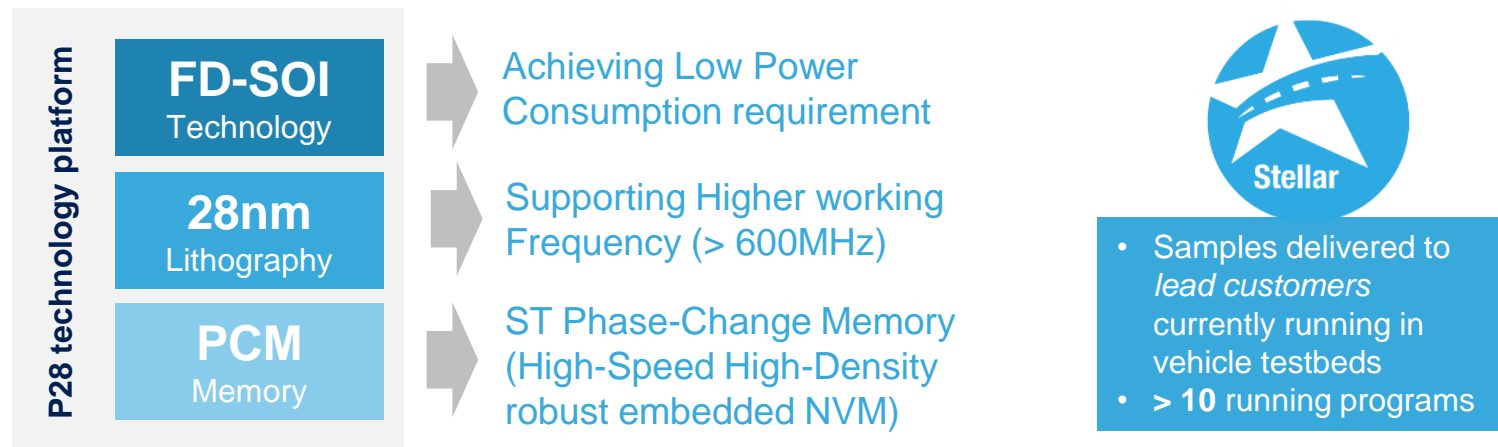
Requirements:

- High density technology
- Real-time
- Working Frequency > 400MHz
- Low power consumption
- >16 MB of high speed access Non-Volatile Memory



Stellar: ST 28nm FD-SOI with embedded Phase-Change Memory

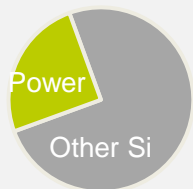
ST in-house production at Crolles300



- Samples delivered to lead customers currently running in vehicle testbeds
- > 10 running programs

Power Share in Industrial TAM(*)

>25%



Industrial Applications – A Solid Base ST Leadership in Power Solutions



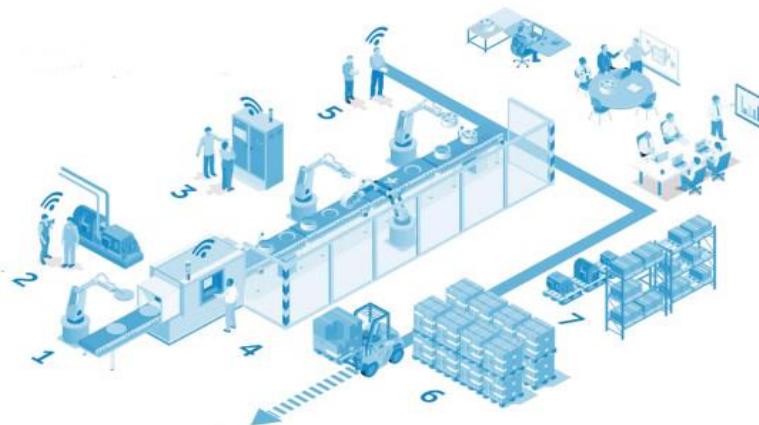
#2 In Industrial Power Discretes



#1 Discrete supplier in many industrial application domains

- Power tools
- Medical Diagnostic
- Security & Surveillance
- Networking systems
- Building Safety systems
-

Smart Factory



Smart Home



Automation

>15% Share LV MOSFET in High-End Industrial

Energy Management

>30% HV MOSFET Superjunctions in Lighting & Power conversion

Motor Control

>10% Share IGBT & IPM in Home Appliance



Source: IHS Markit

(*) Estimation based on Manufacturing & Process Automation, Power & Energy, Building & Home Control, and other industrial

STPOWER Portfolio

















Broad range Power Offer Tailored to the **Industrial Market**



Silicon HV & LV
MOSFETs
Silicon Carbide
MOSFET
IGBT
Modules



Continue to expand penetration in Industrial
outperforming the market

Supporting Continuous Growth			
HV MOSFETs	IGBT & Modules	SiC MOSFETs	LV MOSFETs
 Gaming & SmartTV	 Air-conditioning	 EV Charger	 Adapter
 Charging Station	 Washing Machine	 UPS	 Power Tool
 LED Lighting	 Solar Inverter	 Industrial Motor	 Garden Tools
 Solar Inverter	 Induction Heating	 Power Supply	 e-Scooter

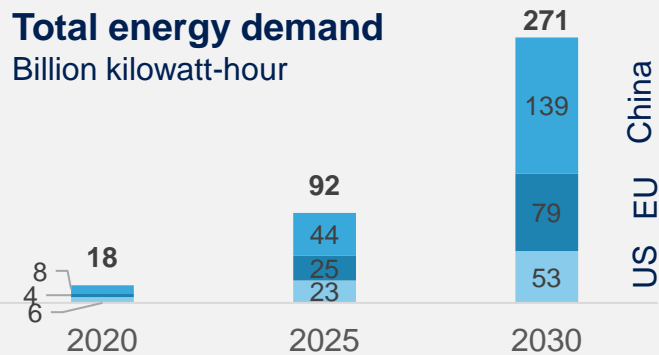
Scalable Solution for Charging Pile

Strongly Contributing to Power Silicon Pervasiveness in Industrial

50B\$ WW investment for 280kW per hour by 2030

Total energy demand

Billion kilowatt-hour

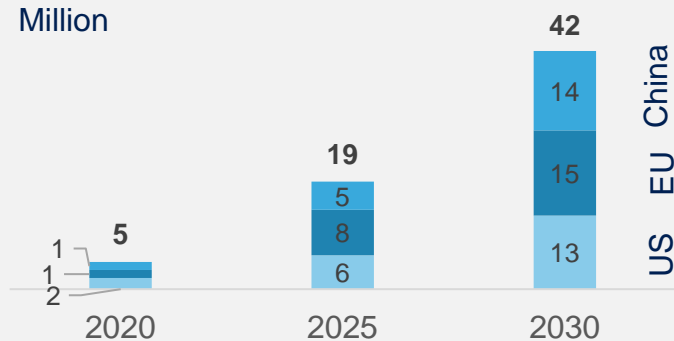


280 BkW-h

Estimated charging energy demand for electric vehicle

Estimated Number of Chargers

Million

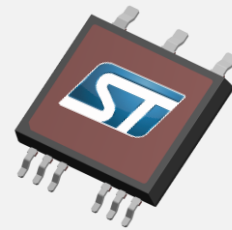


50 B\$

2030 Investment plan to meet the target

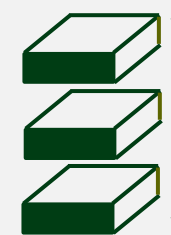
Application Scalability with ST Power Modules

ACEPACK™ SMIT



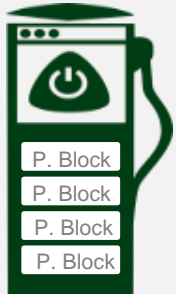
Up to **x4**
ST ICs/Power Block

Power Block
~ 20 kW



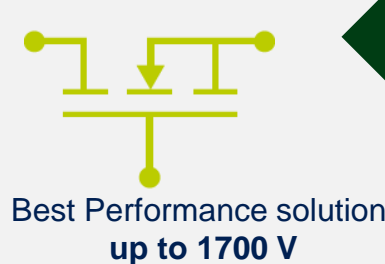
Up to **x18**
Power Block

Charging Pile:
60 – 350kW



Solutions Tailored to Customer Needs

SiC MOSFET



High Power, High Efficiency

Balancing Cost & Performance

Si IGBT



Power Module Solutions for Industrial

Intelligent Power Module SLLIMM™

Granular offer with ≈70 Part Numbers



Power Module ACEPACK™

Silicon MOSFET & IGBT, Silicon Carbide MOSFET



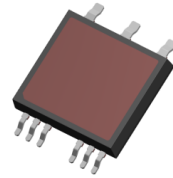
30W



500W



3kW



5kW



20kW

Home Appliances

Washing Machine



Fridge



Air Conditioning



Motor Drive

Motor Pump



Electric Motor



Energy Conversion & Storage

Wind Turbine



Solar Inverter



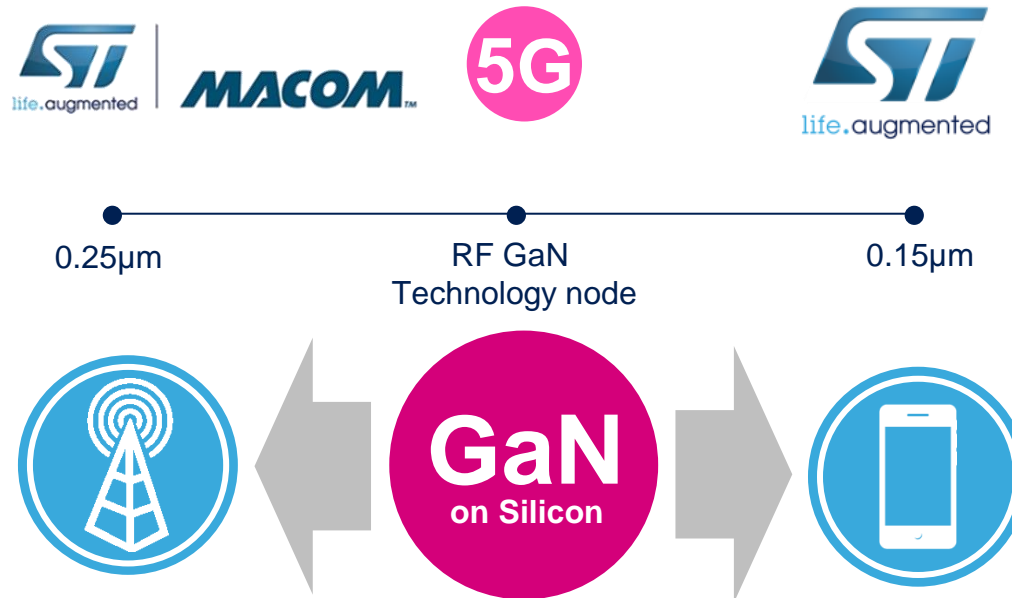
ADG Supports the Company Strategy in 5G GaN Power RF Amplifiers

Telecom Base Station

- Business Model: ST 8" technology development and manufacturing based on MACOM IP
- GaN on Silicon displacing LDMOS with significant cost advantage vs. competitor GaN on SiC solutions
- Engaged with major world wide market players
- Production Start: 2019. Volume ramp-up by 2020

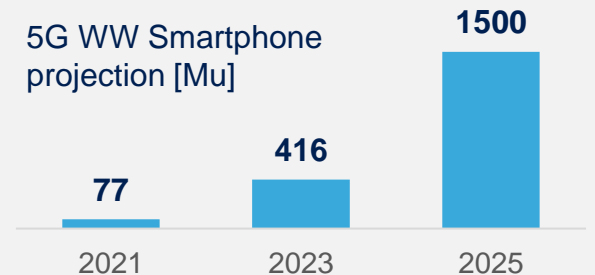
Targeting
>50%
Base Station Market Share

Capability to address
>80%
of 5G Demand



Mobile & Handsets market

- ST licenses MACOM IP
- Targeting GaN on Silicon RF Power amplifiers for handset
- GaN on Silicon huge cost advantage vs traditional GaAs and competitors GaN on SiC grants an effective market penetration
- Engagements with market key players already initiated



2019

...scaling manufacturing capacity for these opportunities

2023

ADG is committed to **outperform** the market growth in **Automotive** and in **Industrial** application domains

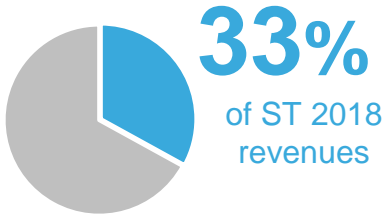
- ADG is ready to support the mobility transformation, seizing market opportunities coming from electrification and digitalization with a flexible product offer to satisfy the needs of our customers
- ADG is well equipped to support the Industrial market domain thanks to a complete offer of Power and Discrete products covering multiple applications
- ADG supports the 5G strategy of the company thanks to an innovative Power-RF product offer and an extended partnership
- Technology innovation, complemented by world-class manufacturing, remains a priority to support new Automotive, Industrial and Personal Electronics trends, with a strong focus on new power materials (wide bandgap) and digital applications (FD-SOI and Phase Change Memory)

Analog, MEMS & Sensors Group

Benedetto Vigna

President
Analog, MEMS and Sensors Group





AMS Group at a Glance

Key Financial Data by Sub-Group

Group 2018 Revenue

\$3.15B

Analog, MEMS & Sensors Group

\$1.35B

Analog

\$1.8B

MEMS & Sensors

FY18 vs FY17 Growth

AMS
+20%

Analog **+11%**

MEMS & Sensors **+28%**

A wide range and diversified product portfolio to support a large customers base

Serving more than
70,000
Customers

AMS Strategy

Products

Analog

- General Purpose
- Application Specific

MEMS & Sensors

- MEMS Sensors & Actuators
- Specialized Imaging Sensors

Markets

- Strategic **focus** on industrial & automotive end markets
- Address specific large **opportunities** in personal electronics
- **Selective** approach in communications equipment and computers & peripherals focusing on advanced power management

Analog Products For All End Markets

Automotive

Industrial

Personal Electronics

**Communications
Equipment,
Computers & Peripherals**

General Purpose

**Wireless
Charging**

**Power & Energy
Management**

Motor Control

Automation

Connectivity

Analog – General Purpose

Power Management

AC-DC
Converters

DC-DC
Converters

Battery
Management
ICs

Hot Swap
Converters

Linear
Voltage
Regulators

LED Drivers

Interfaces

USB Type-C
&
Power Delivery

USB Charging
Controllers &
Transceivers

Standard
Interfaces

Advanced
RS485
Interface

Signal Conditioning

Operational
Amplifiers

Current Sensing
Amplifiers

Comparators

Voltage
Reference

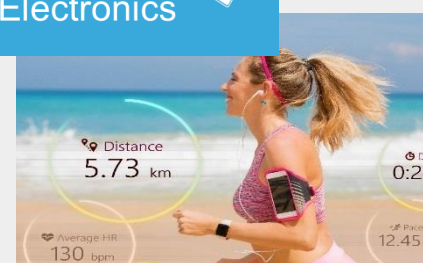
Industrial



Automotive



Personal
Electronics



Communications
Equipment,
Computers & Peripherals





Analog – Application Specific Wireless Power solutions

Next

30 W - Under Development -
Suitable for industrial applications e.g. power tools

15 W Multi-Coil, Multi-Market

Larger charging area & freedom of positioning

15 W Smartphones and Tablets

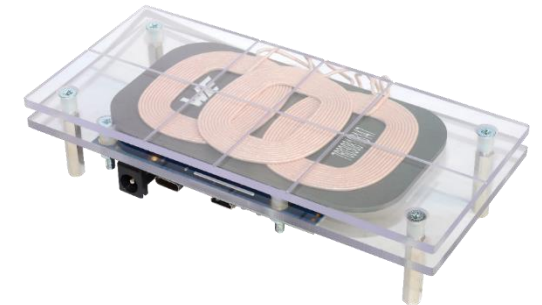
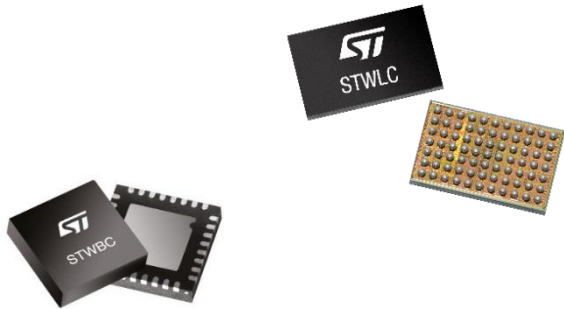
Charging up to 3 time faster Qi 1.2.3 certified

5 W Smartphones

Qi 1.2 certified

1 - 2.5 W Wearable Devices

Optimized for ultra-compact battery-operated



Analog – Application Specific Industrial

Focus Area

Product Leadership



Power and Energy Management

Powerline Communication ICs



120 Millions smart meters with ST solutions
38% Market Share*



Motion Control

Motor Drivers



>1 Billion low voltage motors driven by ST smart power solutions
11% Market Share*



Automation

Intelligent Power Switches



>1 Billion I/O channels in factories with ST drivers
12% Market Share*

12% of business in 2018 coming from Products less than 2 years old



Solutions
from Watt to kW

Analog – Application Specific Power & Energy Management

High-Efficiency / High-Voltage Converters



ANALOG



High End Combo Architecture



DIGITAL



75 W

AC-DC High-Voltage Converters

Wireline, Wireless, USB-PD Chargers

ASSP for LED Lighting

Power Factor Correctors

500 W

AC-DC Controllers

Analog & Digital Combo (PFC+ Ctrl)

Over 1,000 W

Digital Controllers

SiC, GaN Isolated Drivers

Secondary-Side Controllers



Analog – Application Specific Flexible Solutions for all Types of Motors

Stepper



Brushed DC



Brushless DC



Broad portfolio with more than 130 products and more than One Billion Units sold


Galvanic Isolation

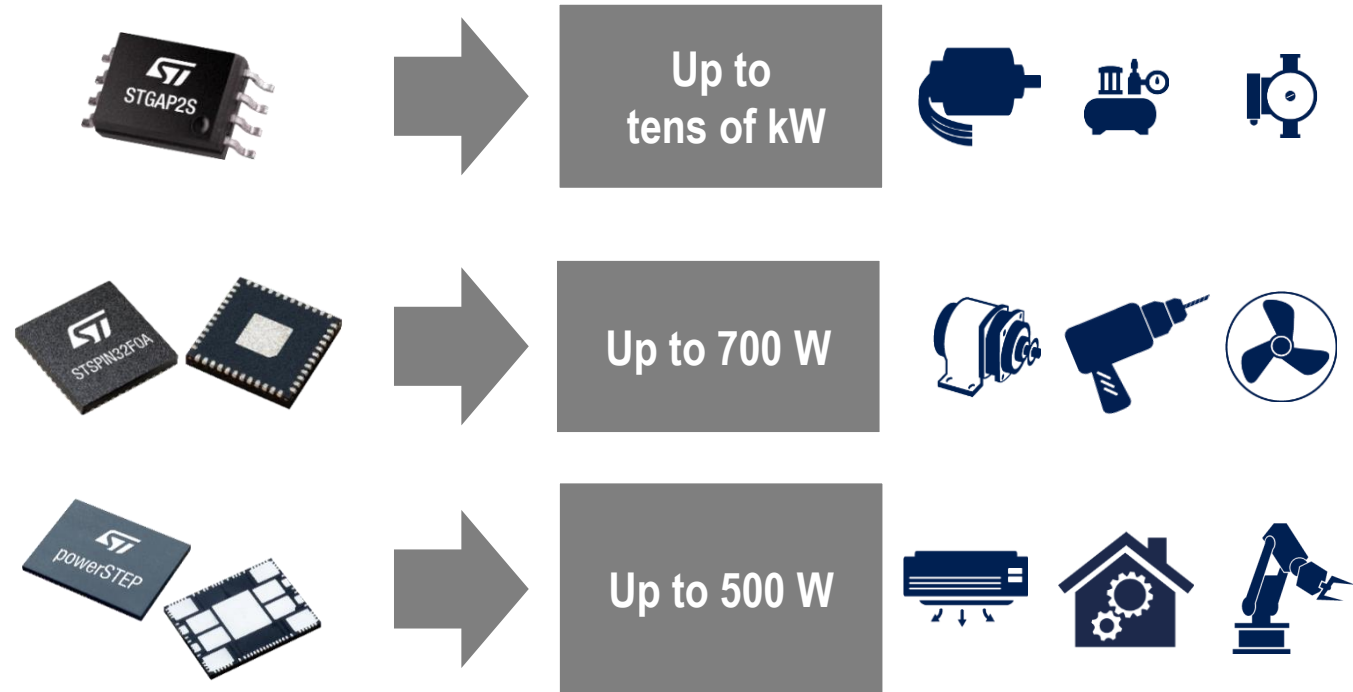

Motor Control




Power Transistors (Si or SiC)

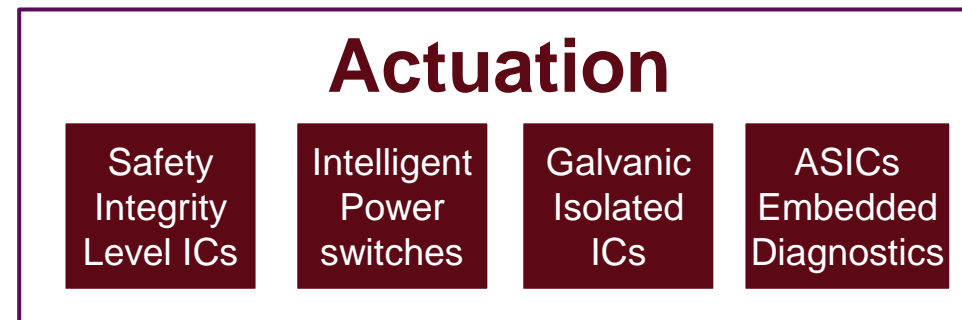
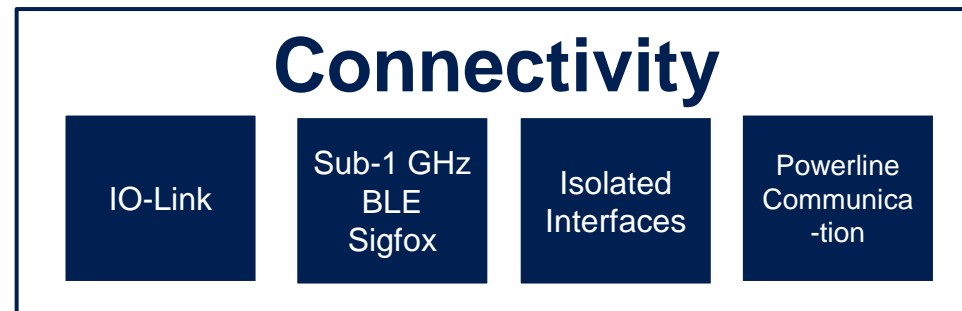

Microcontroller

Heterogeneous Integration



Smallest footprint and most power efficient Module

Analog – Application Specific Factory Automation



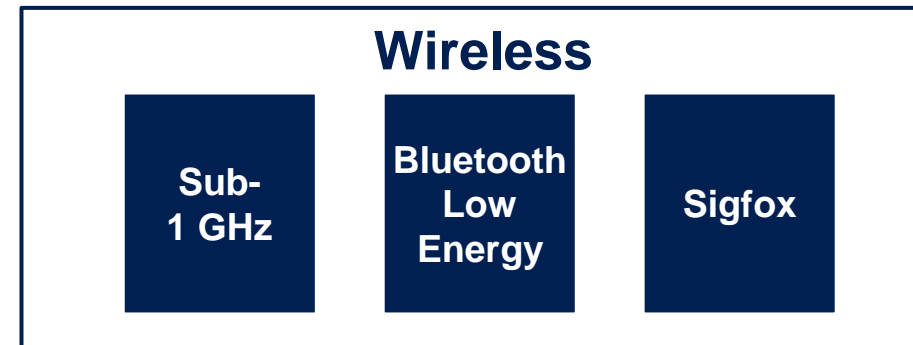
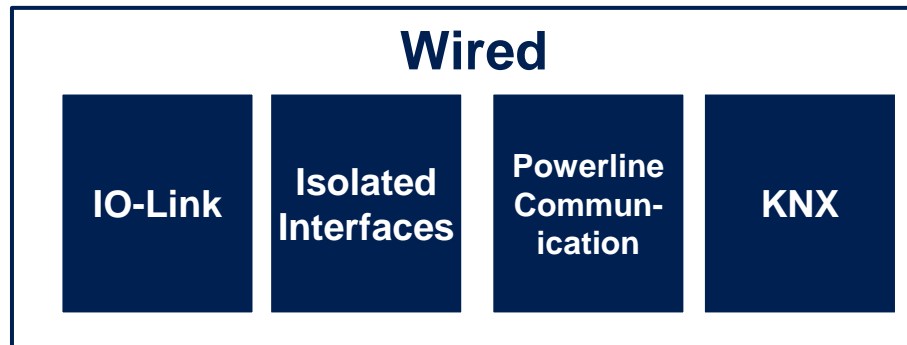
- Communication and **Flexibility** to adapt in real-time to external events
- **Robustness** and reliability thanks to embedded intelligence and diagnostics
- Higher efficiency and **Safety** at all points in power usage
- **Distributed** intelligence, decentralized diagnostics

Based on **BCD, BiCMOS, Galvanic Isolation**

Emerging Industrial Applications Driven by Connectivity and Sensors



KNX
Transceiver



Ultra Low Power
BLE

SW and HW Tools Enabling New Applications

Development Platforms and Reference Designs

Wireless Industrial Node



ISM330DLC
6x IMU. Wide Bandwidth

IIS2DH
Accelerometer. Wide bandwidth, Ultra-low power

IIS2MDC
Magnetometer. Low-Noise, Low Power



BlueNRG-Tile

Pressure Sensor

Accelerometer + Gyroscope

Magnetometer

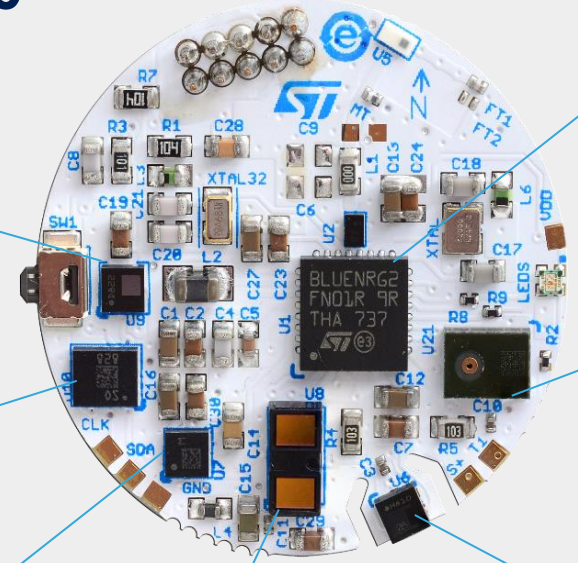
Time of Flight

BlueNRG SoC



Microphone

Humidity + Temperature



Sensors & Actuators Covering All End Markets

Automotive

Industrial

Personal Electronics

Communications
Equipment,
Computers & Peripherals

MEMS Actuators

MEMS Sensors

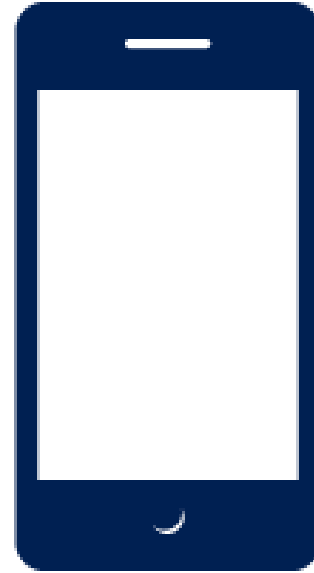
Specialized Imaging
Sensors



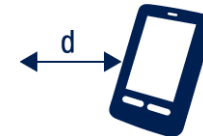
Personal Electronics

What AMS did in the Last Year

Motion and **pressure** sensors wins in the flagship models from most of the world's top smartphone and wearables manufacturers



Multiple design wins and growth of volume shipments for **FlightSense™** products in smartphones



Wins for **power management**, **voltage regulators**, **motor drivers**, and **touchscreen controllers** for platforms from major smartphone makers



50%

Market Share in Motion MEMS in
Personal Electronics &
Automotive Telematics

MEMS Sensors & Actuators Technology and Products

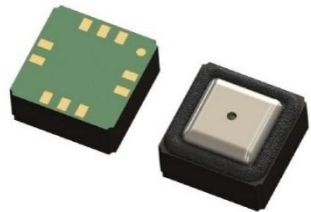


Next Generation ThELMA*

- Higher accuracy
- Ultra-low power
- Embedded Machine Learning Core



Motion sensors for
Personal Electronics,
Automotive
& Industrial

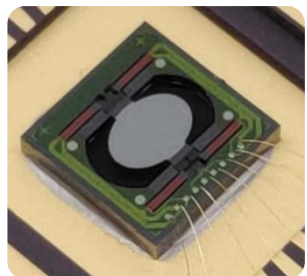


Next Generation BASTILLE*

- Higher accuracy
- Size reduction
- Waterproofing



Environmental sensors
for Personal Electronics
& Industrial



Thin Film Piezoelectric PεTRA*

- Innovative piezoelectric materials
- Higher efficiency
- Lower cost



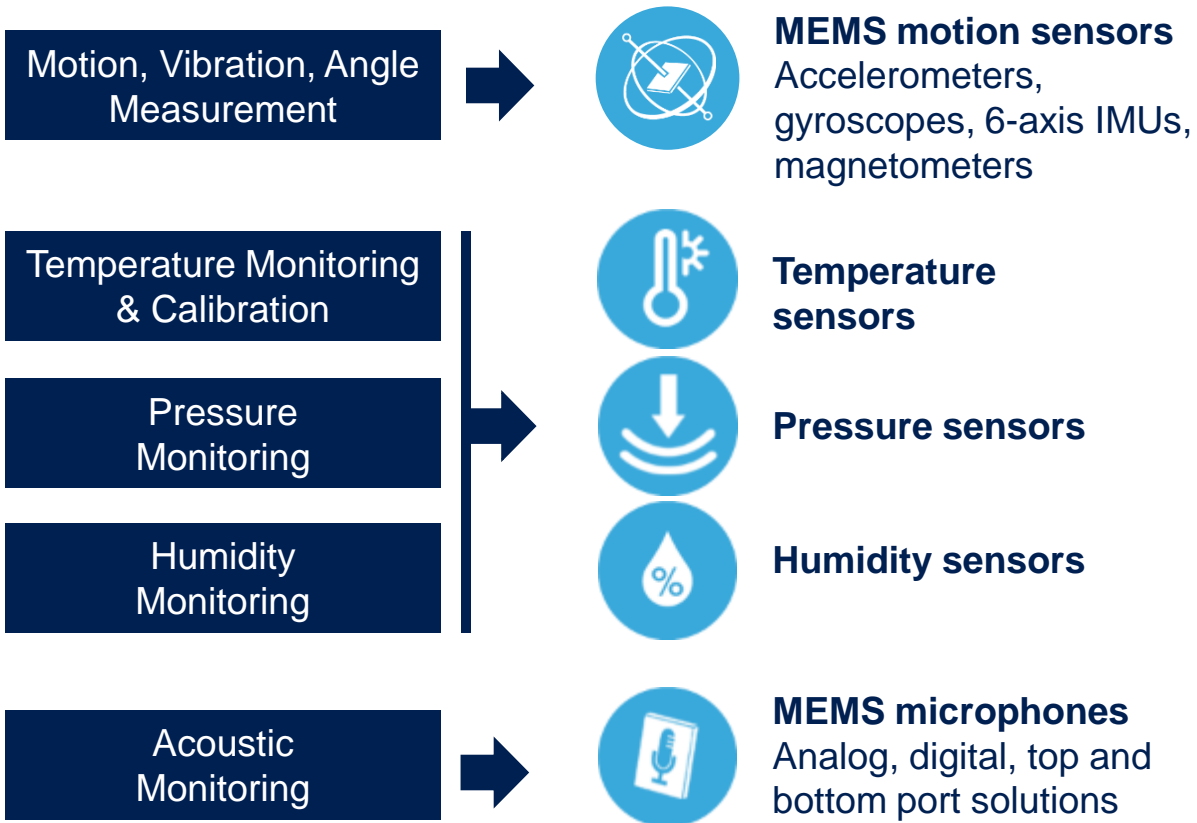
Microactuators
for Ink Jet printing,
Speakers &
Infrared Scanners

*ST proprietary MEMS technologies

Source: IHS Markit

MEMS Sensors

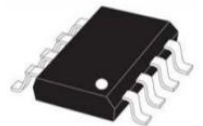
Higher Accuracy for Industrial & Automotive



Inclinometer



Hi-g accelerometers for airbags



More intelligence with Embedded Machine Learning

10 to 1,000 Times Power Saving

Industrial Robots



Personal Electronics



Sensors
Data



Computation
Block



Decision
Tree



Specialized Imaging Sensors

Technology Focus



Time of Flight

- Direct & Indirect, SPAD & Fast PhotoDiode
- Increasing resolution
- All-in-one & low power
- Multi-zone & multi-object capability
- 3D-BSI, 40 nm SPAD

Structured Light

- Global Shutter
- High Quantum Efficiency
- 3D-BSI

Ambient Light Sensor

- High sensitivity
- Small size & low power
- Flicker detection

3D Sensing
for smartphones
(Front facing and rear facing)
and automotive
(LiDAR & in cabin)

Proximity and ranging Sensors
for Personal Electronics
and Industrial

Low cost spectrometers
for home & building automation

Expanding our Imaging Sensing Offer

3D & Depth sensing
in smartphones
% application type

- Rear Facing Laser Autofocus
- Rear Facing Depth
- Front Facing Depth

2018



2019



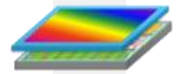
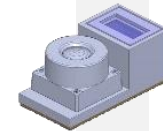
2020



2021



Time of Flight



From 1 pixel to 1Mpixel, from 2m up to 6m, from 27° to >70° Field of View

Stereoscopic and Structured Light

Global Shutter Sensor



Up to 2.3Mpix by shrinking pixel size & embedding Image Signal Processing

Diversifying our Imaging Offer For Automotive



Sensing & Viewing Camera

Rolling Shutter

- High Dynamic Range (HDR)
- Low Noise
- High Sensitivity
- FSI
- Flicker Free
- No Memory
- Low Noise
- High Sensitivity
- BSI



In-Cabin Optical Sense

Global Shutter

- HDR
- Low Noise
- High sharpness
- Multi zone
- FSI



LiDAR

FlightSense™

- integrated SoC receiver solution
- 40nm & 3D CMOS
- SPAD

Takeaways

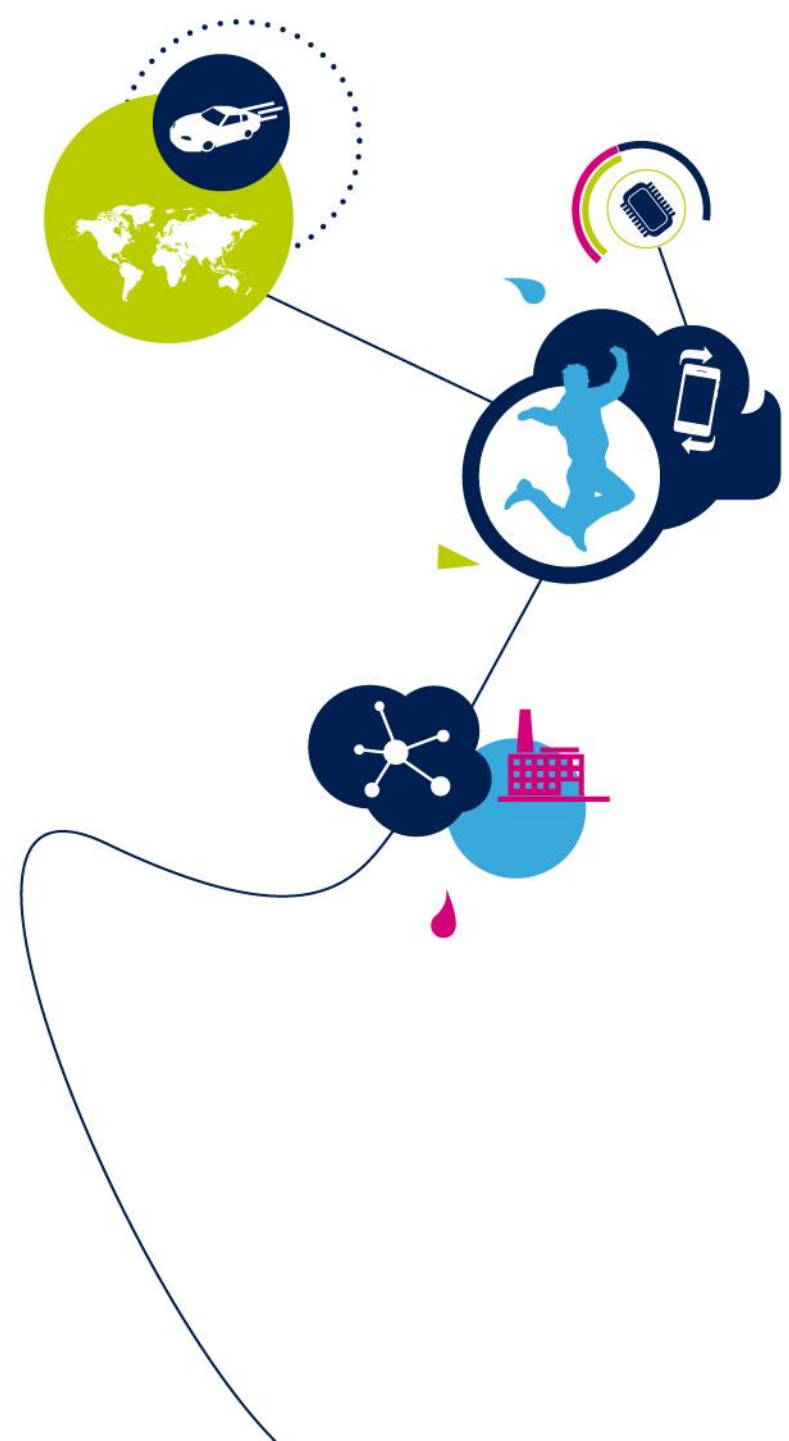
- Strategic focus in **Industrial** with Analog (GPA and ASSP) and Sensors
- **Broadest** Sensor and Microactuator portfolio in the industry expanding in Automotive and Industrial markets
- **Innovation** driven by a wide IP and Technology portfolio to boost growth on emerging applications

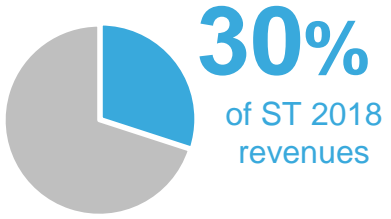
Well positioned for balanced growth with both Distribution and Key Customers

Microcontrollers & Digital ICs Group

Claude Dardanne

President
Microcontrollers and Digital ICs Group





MDG Group at a Glance

Key Financial Data by Sub-Group

Group 2018 Revenue

\$2.94B

Microcontrollers & Digital ICs Group

\$2.29B

MMS

\$0.65B

Digital

FY18 vs FY17 Growth

+11%

MDG

MMS

+11%

Digital

+11%

MMS Microcontrollers & Memories
Digital Digital and Mixed ASICs, Aerospace,
Defense and mmW Communication

Microcontrollers & Digital Group

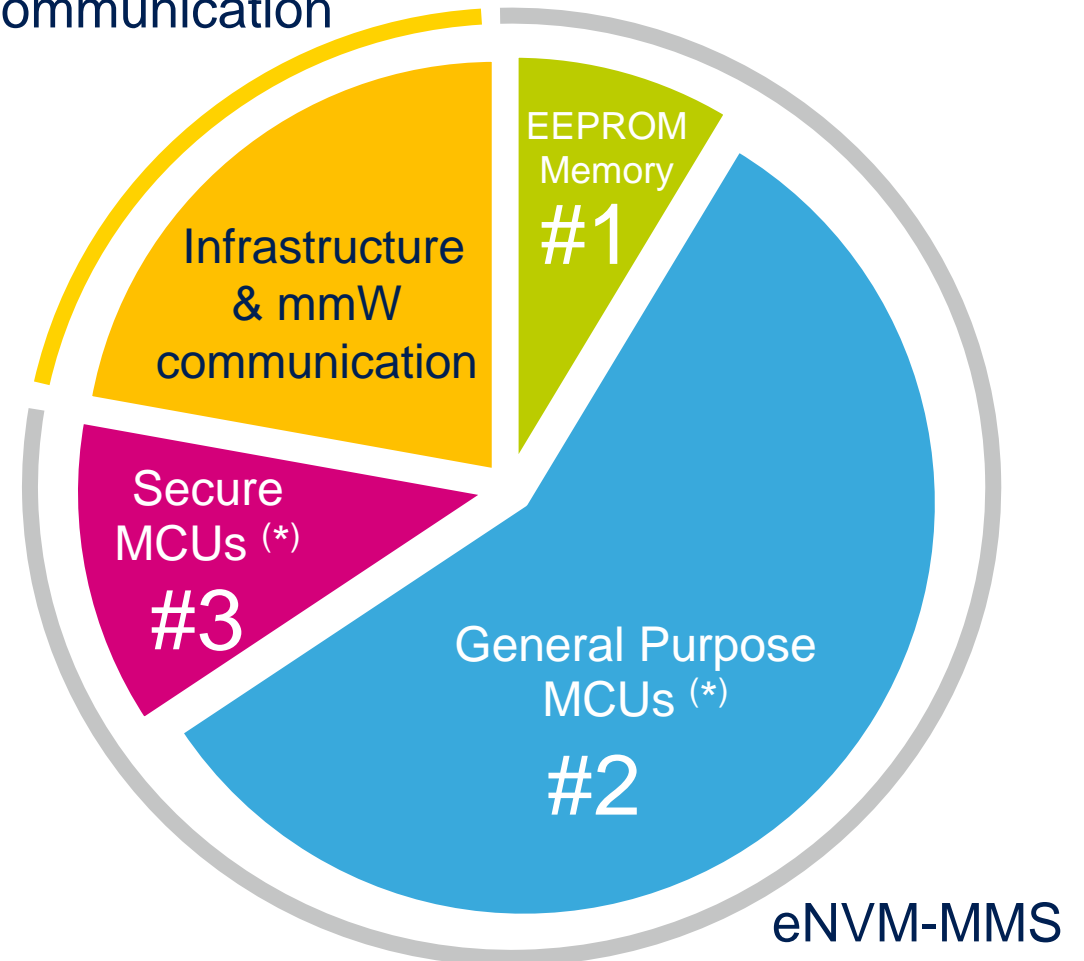
2018 Revenues Split

- ~ 70% Revenues with Microcontrollers
- ~ 20% Revenues with Digital products
- ~ 10% Revenues with EEPROM memories

Three Year Target

- Leadership on Embedded Processing (*)
- Migration of Digital competences to Industrial (MPU/AI) & RF mmW, capitalizing on ST differentiated technologies & IP
- Consolidate leadership in EEPROM Memories

Wireless
Communication



MDG Products for all End Markets

Automotive

Industrial

Personal Electronics

Communications
Equipment,
Computers & Peripherals

Embedded
Processing

Advanced Secure
Solutions

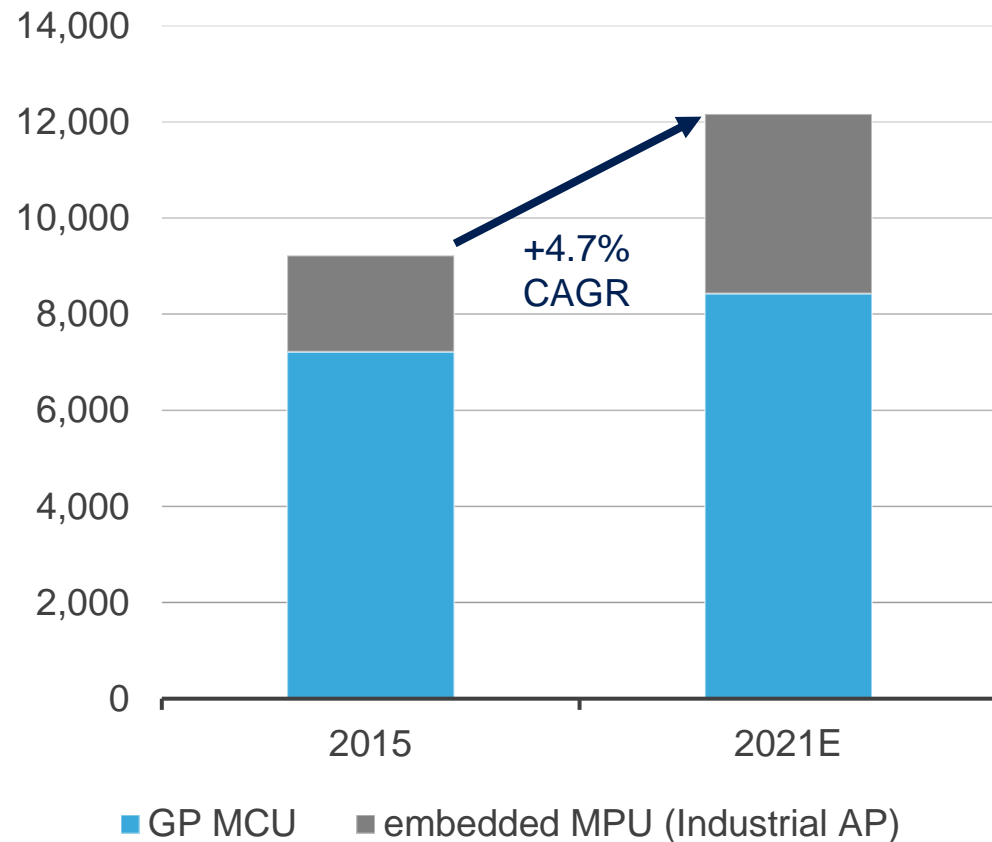
RF EEPROM
Memories

60 GHz short
range connectivity

5G, RF mmW
communication

Embedded Processing Market Trend

Embedded Processing* TAM



Growth Driver Industrial

- The brain of a large variety of applications
- IoT pervasion accelerated by 5G deployment
- Artificial Intelligence disruption at the edge
- New applications enabled by secure IoT

- Industrial Robotics / Factory Automation
- Medical Diagnostic and imaging
- Drones
- Point of Sales

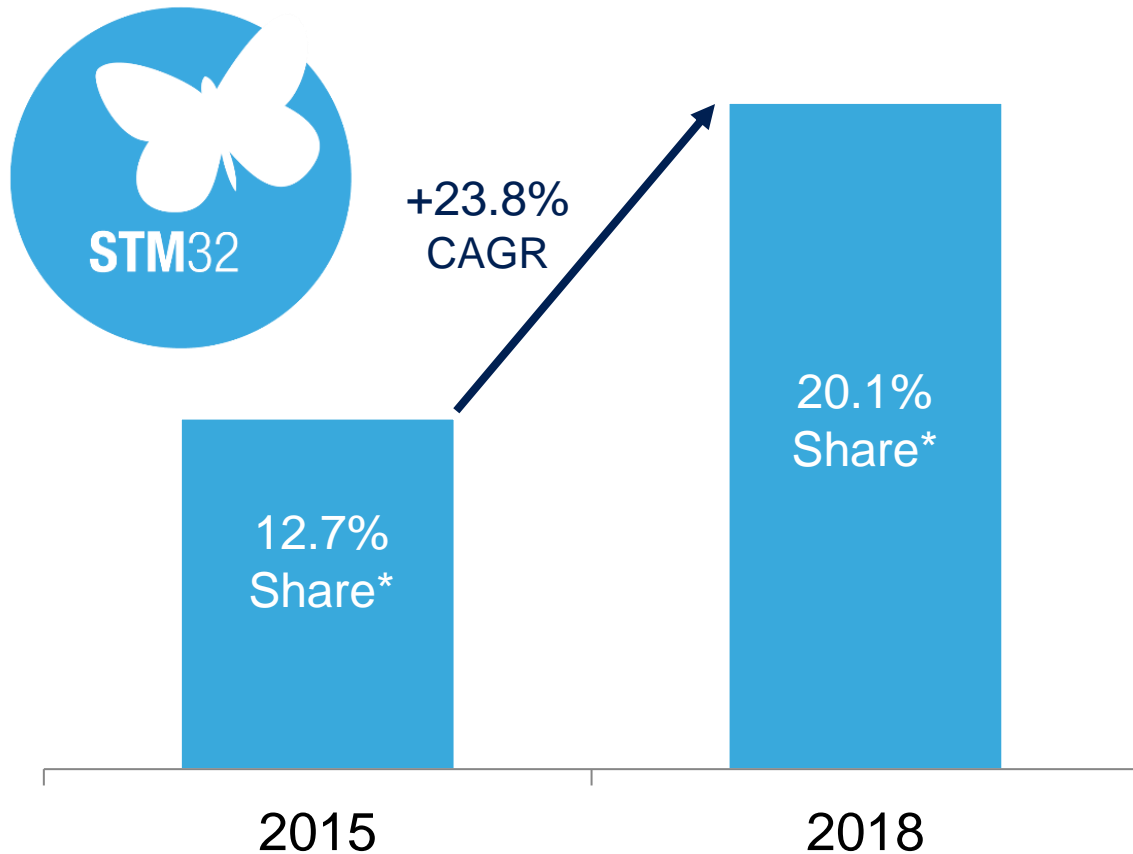
- Appliances
- Wellness & fitness
- Additive manufacturing
- Portable Point of Sales
- Industrial & Power tools
- Smart Metering
- Personal healthcare
- Smart Farming

* Excluding Automotive MCUs
Source: WSTS and ST estimates

ST & Embedded Processing

ST Embedded Processing Revenues *

Mainly STM32 MCUs



* Excluding Automotive MCUs
Source: WSTS

STM32 Microcontroller family

- Based on single or dual ARM Cortex M core
- Broadest global portfolio
- > 1000 products available
- Serving more than 60,000 customers worldwide
- More than 4 Billion units shipped from 2008
- Advanced technology down to 18nm FD-SOI

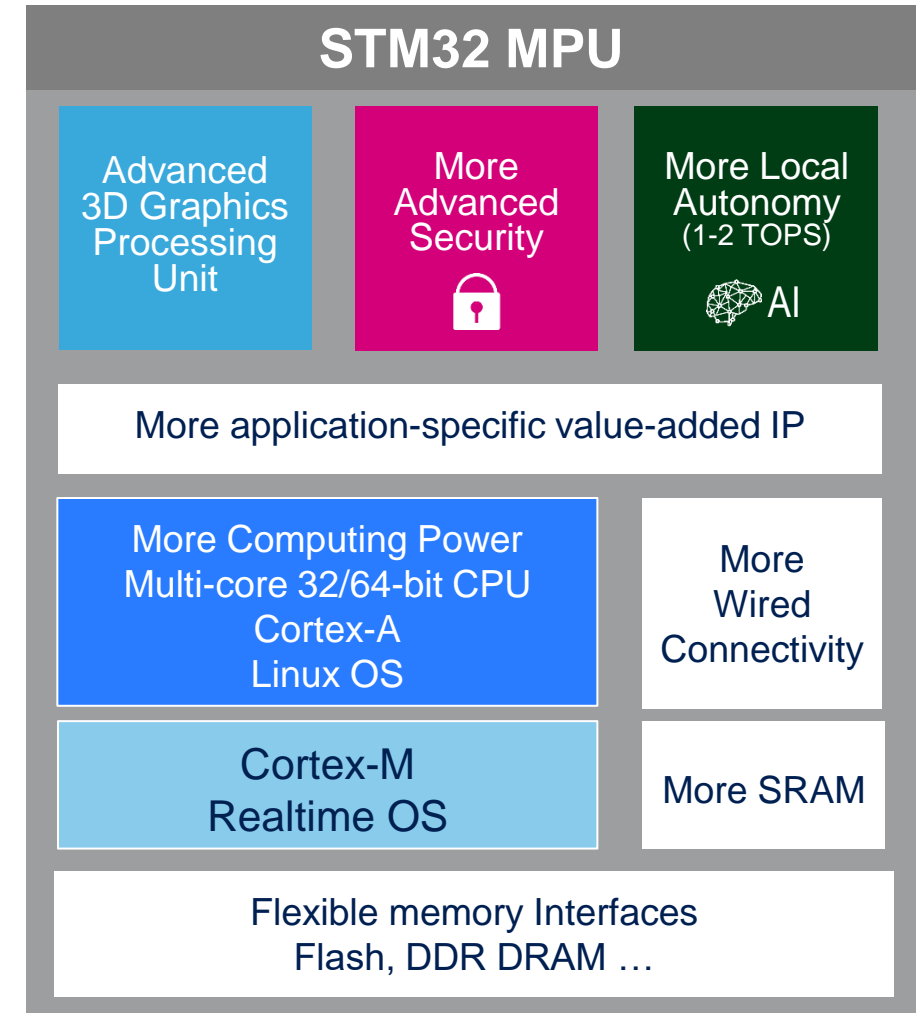
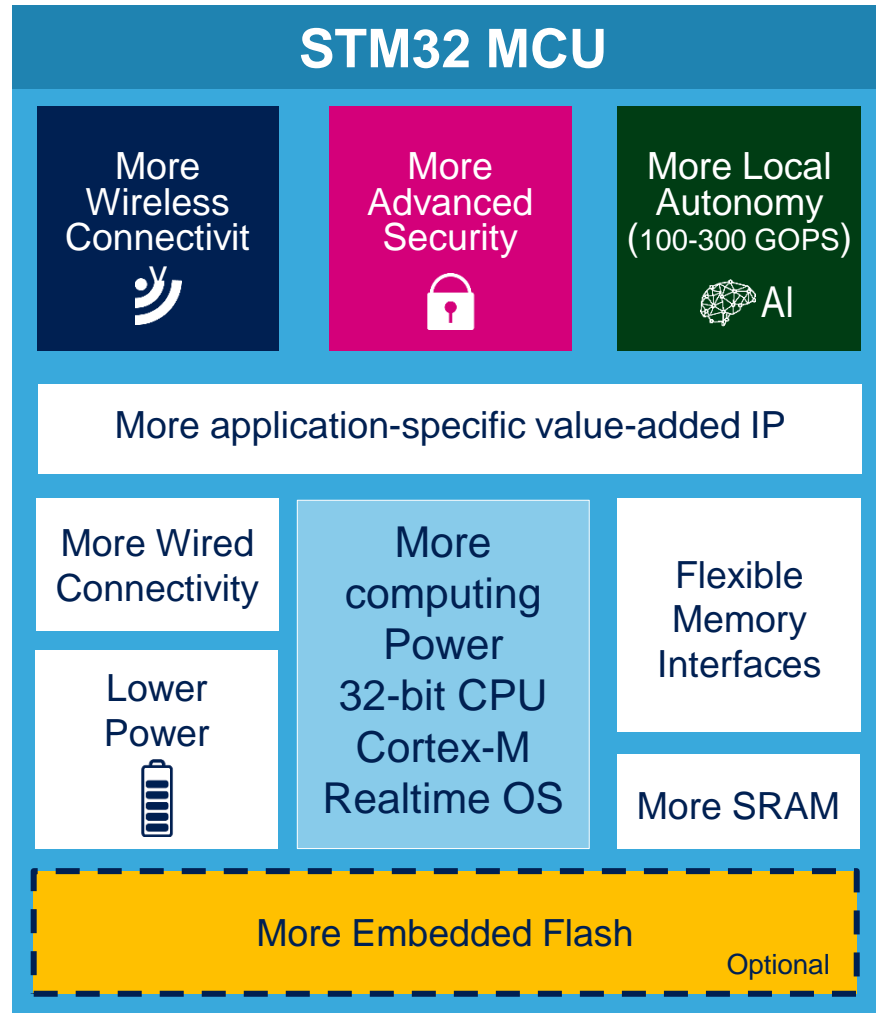
STM32MP Microprocessor family

- 1st product launched 1Q19
- Multi-core Arm Cortex-A cores
- Very high performance
- Advanced Technology down to 16nm FinFET

STM32 Product Family

Strengthening Embedded Processing

Expanded ecosystems



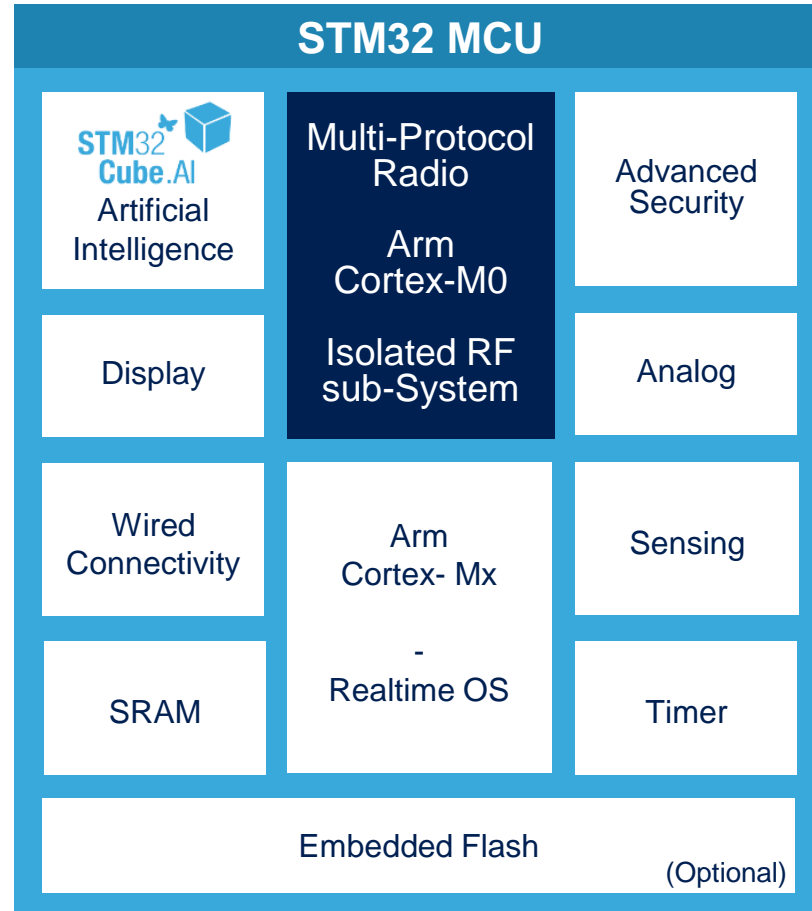
Advanced Non-Volatile Memory technology ... 18nm FD-SOI

Advanced Digital technology ... 16nm FinFET

STM32 Wireless Connectivity

Non-cellular Communication

- Dual-core architecture
- Entry level to high end
- Ultra low power
- Embedded security
- STM32Cube.AI support
- Software compatibility
- STM32 ecosystem



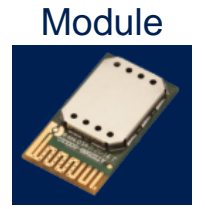
Multi-Protocol Offer

Indoor

- Bluetooth
- Thread
- ZigBee
- Wi-Fi



Outdoor

- LoRa
- SigFox
- 802.15.4



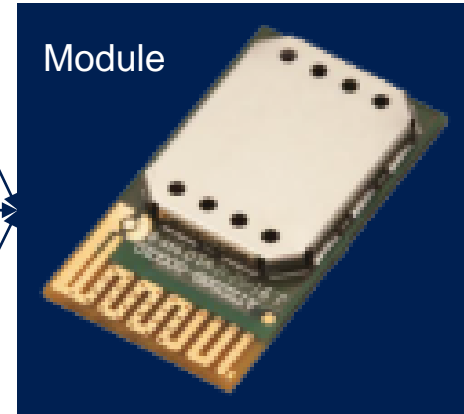
STM32 Wireless Connectivity

IoT Cellular Communication

  Dual CPU architecture
Ultra low power
STM32Cube.AI
STM32CubeIDE

  NB IoT & LTE-M modem
through partnership

  eSIM - OS
First Global Platform
certified product
for M2M
GSMA remote SIM Provisioning



Massive pervasion
expected with 5G
network deployment

- City lighting, traffic
- Logistics asset tracking
- Environment air quality
- Industry 4.0
- Home access control
- Smart metering for utilities

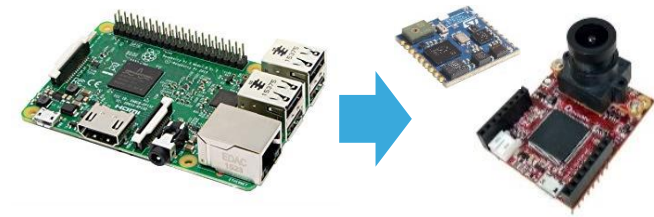


STM32 Enables AI on the Edge

Innovation & Simplicity

- Business expansion: Deployment on current applications
- Business creation: Access to new applications
- Cost & power consumption optimization: Microprocessor applications run on microcontrollers
- Extend to high performance: Additional computing power to access vertical applications

STM32  
Cube.AI



STM32 Solutions for Embedded AI

Extensive Toolbox to Easily Create Your AI Application



AI extension for STM32CubeMX
to map pre-trained **Neural Networks**



Software examples for Quick prototyping
Audio and Motion Function packs



STM32 **Community** with dedicated
Neural Networks topic




STM32 AI Partner Program
with dedicated Partners providing
Machine or Deep Learning engineering services

Neural Networks on STM32
Simple, fast, optimized




STM32 Machine Learning Use Cases

Low




- Sensor analysis
- Activity recognition (motion sensors)
- Stress analysis or attention analysis

Medium



- Audio & sound
- Speech Recognition
- Object detection

High



- Objects detection / classification / tracking
- Natural Language Understanding / Speech Synthesis

10s MOPs

GOPs

0.5-1 TOPs

1-2 TOPs

MCU

From IP embedded in MCU/MPU to dedicated SOC

SAGEMCOM

Industrial Maintenance Module



Smart Shoes
Human Activity Tracking

nnf
no new folk studio

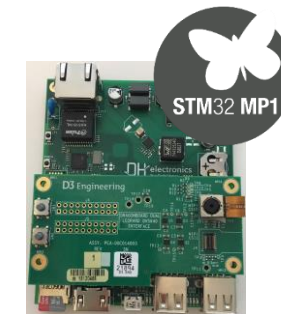
Object & Gesture Detection device



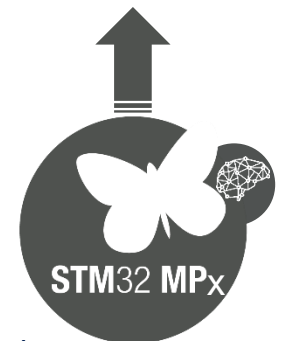
neonode



OpenMV Machine Vision Camera



Arrow Avenger96 Board +
Camera Module

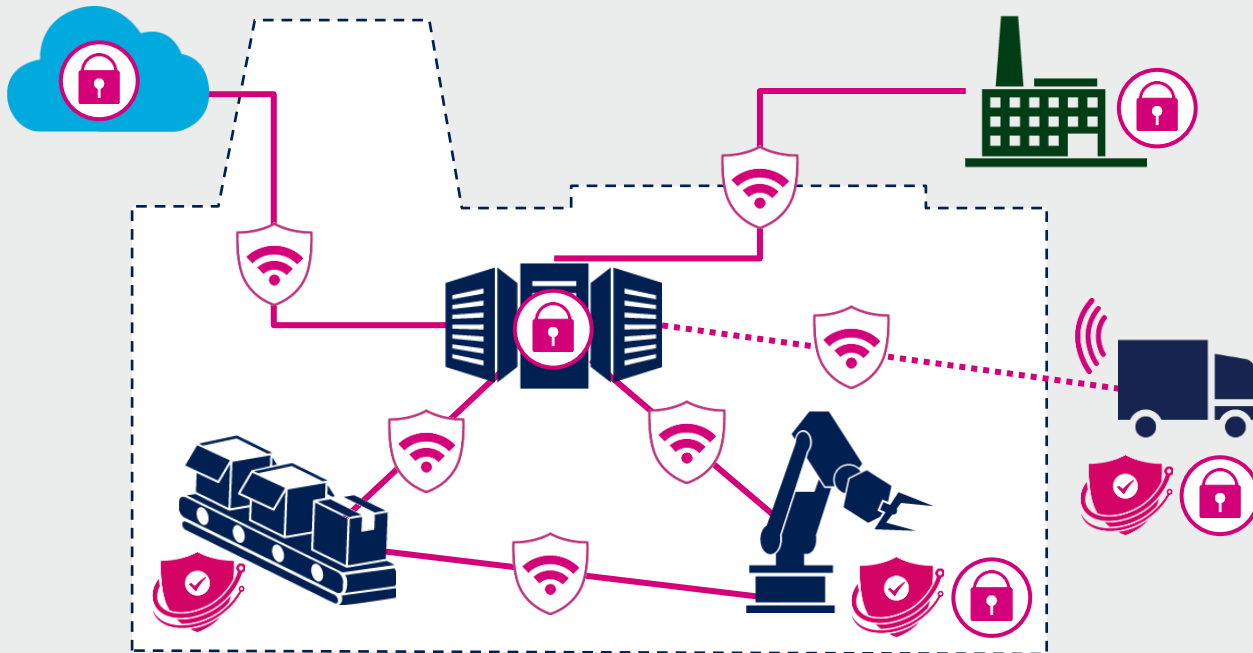




Making everything secure

ST Solutions for IoT Security

End-to-end security covering the full ecosystem



System integrity
Secure boot and crypto services



Authentication and verification
Secure storage of keys and parameters



Secure communication
Secure Over-the-Air FW install & update



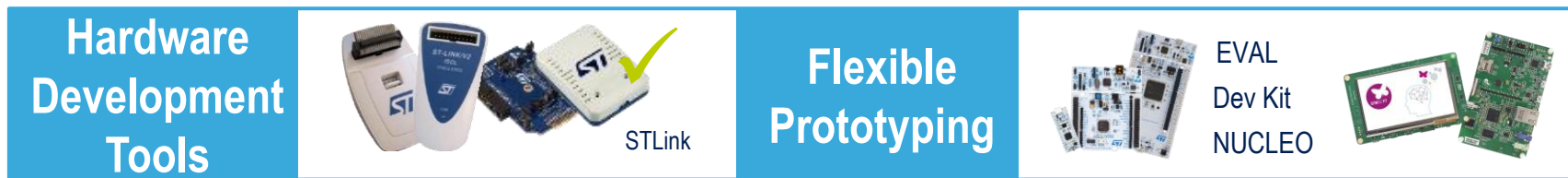
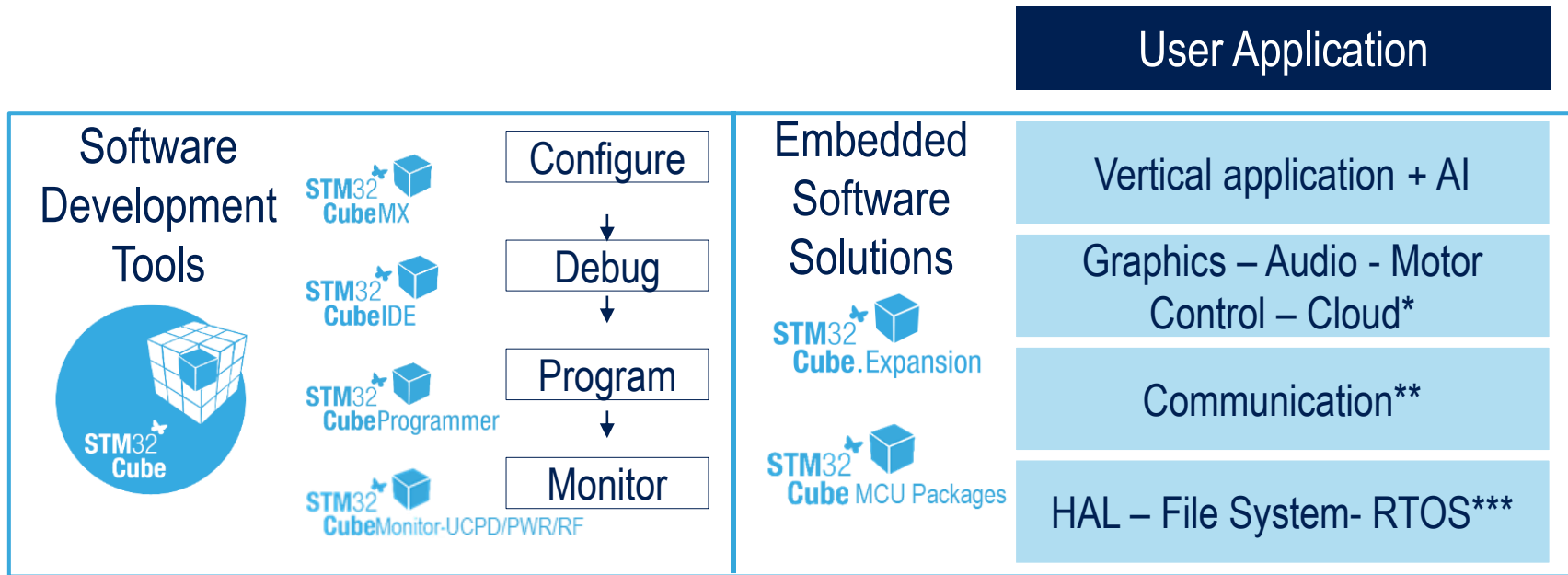
CC = Common Criteria
Security certification



PSA = Platform Security Architecture
ARM framework certification

State-of-the-Art STM32 Ecosystem

Key Criteria for MCU/MPU Choice by OEMs



* Cloud providers:

- aws
- Microsoft Azure
- Google Cloud
- IBM
- Tencent Cloud
- Alibaba Cloud
- Baidu Cloud
- 机智云 Gizwits

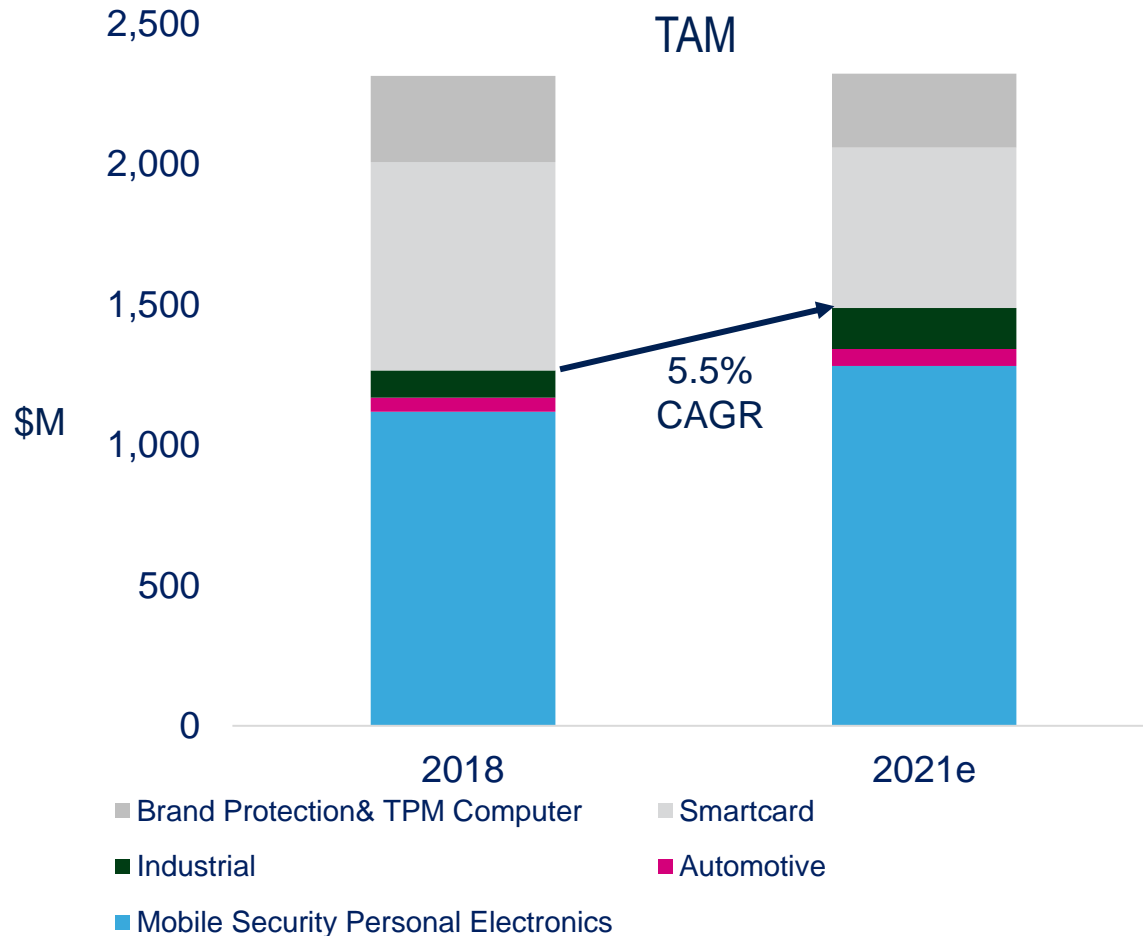
** Connectivity protocols:

- Wi-Fi
- sigfox
- LoRa
- Bluetooth
- NFC

*** Open Source & Framework:

- OpenSTLinux Distribution
- Complete offer Partner Open Source & Framework

Secure Solutions Growth Driver Markets



Industrial



TAM 2019 = 99M\$

CAGR 2018-21: + 14.6%

- Secure IoT solution (STSAFE)
- M2M solution (eSIM)

Automotive



TAM 2019 = 56M\$

CAGR 2018-21: + 6.9%

- Secure connected car (eSIM & eSE)

Personal Electronics



TAM 2019 = 1165M\$

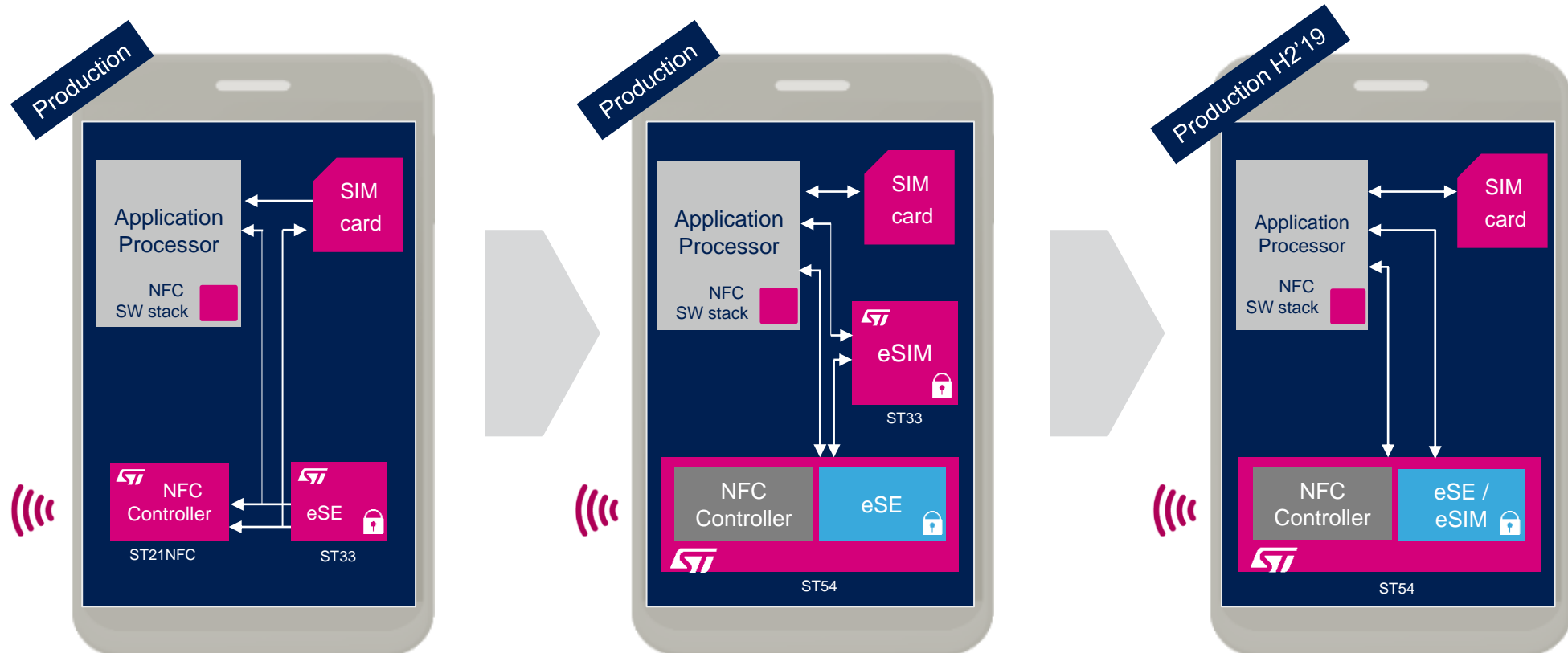
CAGR 2018-21: + 4.6%

- Mobile security transactions (NFC, eSIM, eSE)
- Smartphone, wearable...

Mobile Security Solutions

Leading Market Position in eSIM (*)

Volume production for eSIM products
Deployment of ST Secure Element + NFC controller SoC solution



Over 1 Billion ST33 Secure Elements Sold

Personal Electronics



ST33G / ST33J
in eSIM consumer
GSMA SAS-UP sites
certified



ST33F
Introduction of 1st
Secure Element

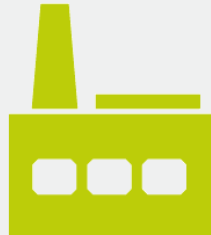


Automotive



ST33-A
Automotive grade compliant

Industrial / M2M



ST33-M
supporting the growing
IoT & industrial market

Computer / TPM



STSAFE-TPM
solutions for computer &
secure IoT

Secure Solutions

Complete Portfolio to Cover all Market Needs



Secure Automotive

ST33-A eSIM, eSE
ST33-A TPM

Automotive



M2M for Industrial & IoT

ST32-M
ST33-M
M2M Solutions

Industrial



Mobile Security Consumer

ST33 eSIM, eSE
ST21NFC
ST54

Personal Electronics



Banking & ID

ST31
STPay
ST53



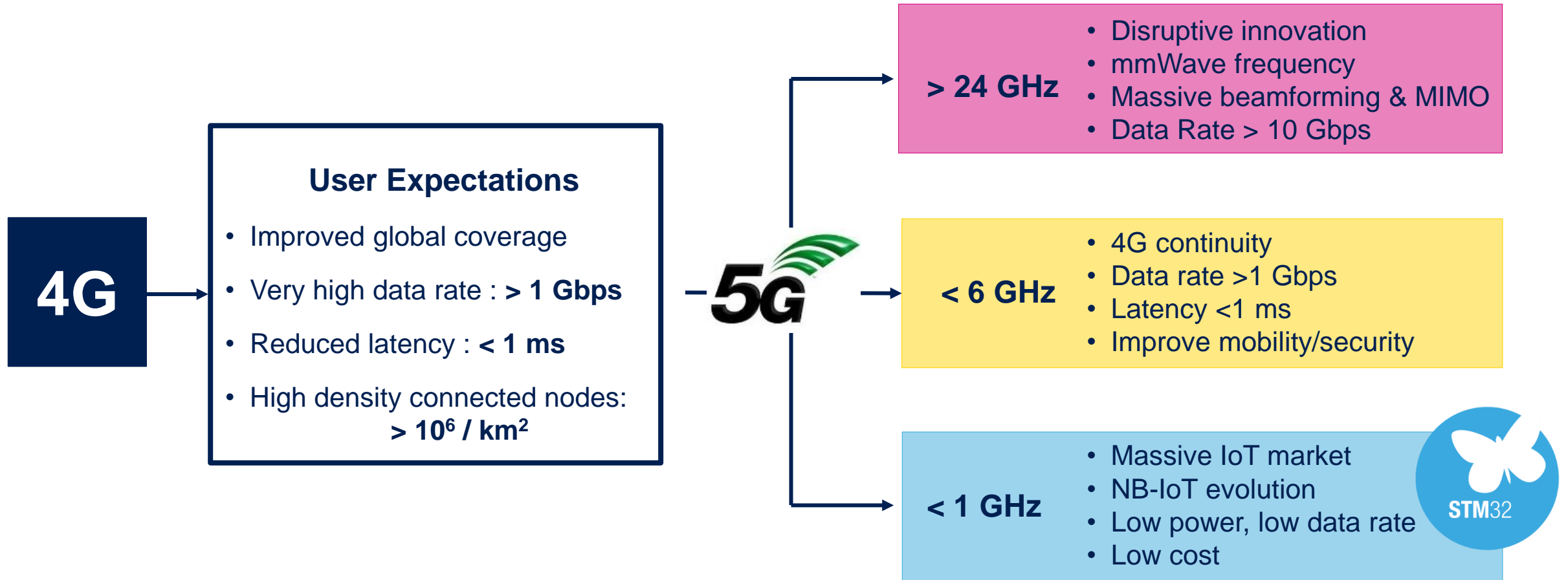
Authentication

STSAFE-A
STSAFE-J
STASFE-TPM
Custom

Computer &
Accessories

Wireless Communication Trends

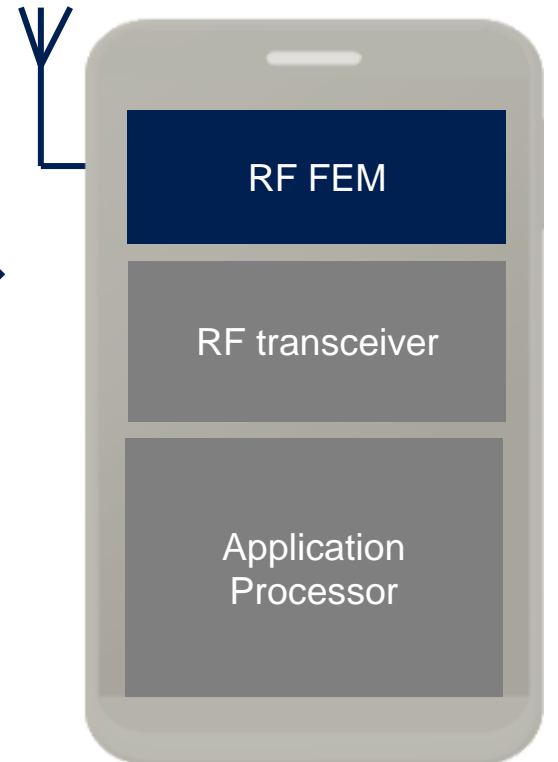
The 5G Disruption



5G RF for Smartphones

ST Silicon Technologies for 5G RF Front-End Modules

- 5G massive multi-band requirement expands Si content in Front End Module (RFFE)
- ST RFSOI and SiGe technologies extensively used in RF Front End modules
- 5G deployment starting with sub-6 GHz
- mmW >24 GHz deployment expected for hot spots, high density city center connections
- RFFE ST Solutions also deployed in 5G Base stations

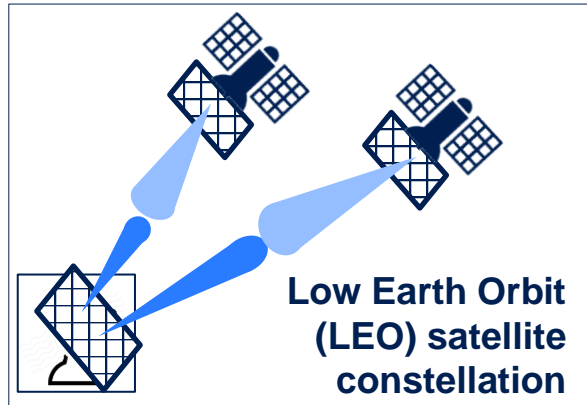


4G	5G Frequency Spectrum	
Legacy band 600 MHz – 2.6 GHz	5G bands extension 3.1 GHz - 6 GHz	5G mmW bands 24 GHz - 40 GHz

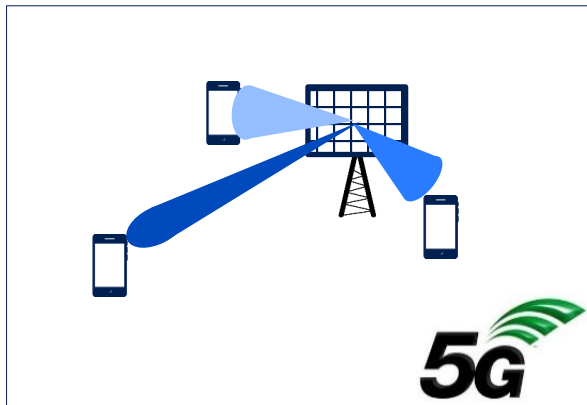
130nm RFSOI	Production		
65nm RFSOI		Production	
55nm SiGe			Prototype

Phased Array Antennas

Disruptive mmW Solutions for Communication Networks



Low Earth Orbit (LEO) satellite constellation



5G

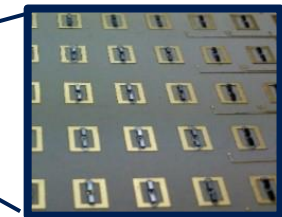
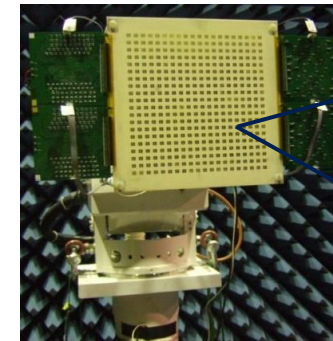
Phased array technology deployment

Beamforming for LEO satellite tracking

Best link budget

Better connection density for 5G networks

Phased array technology enabled by high RF performances Si technologies



From 128 up to 1000 RF chips per antenna

Production ramp-up for satellite communication capitalizing on ST Advanced processes: 130nm SiGe and 28nm FD-SOI

ST60 - 60 GHz Transceiver

High-speed, Low-power Wireless Link for Close Proximity



Industrial



Computer & Peripherals



Personal Electronics



Life-proof connector-free devices

60 GHz RF Transceiver
for cable-free &
connector-free
solutions



Board-to-board
Contactless connection



Firmware upload
Factory automation



Integrated millimeter-wave RF transceiver

- Transfer speeds up to **6 Gbps**
- Very low power: **40 mW**
- Miniature form factor with **optimized BoM**



PC 2-in-1 and mobile continuum



Seamless docking and
on-the-go device-to-device sync



Freedom of movement with
contactless connection

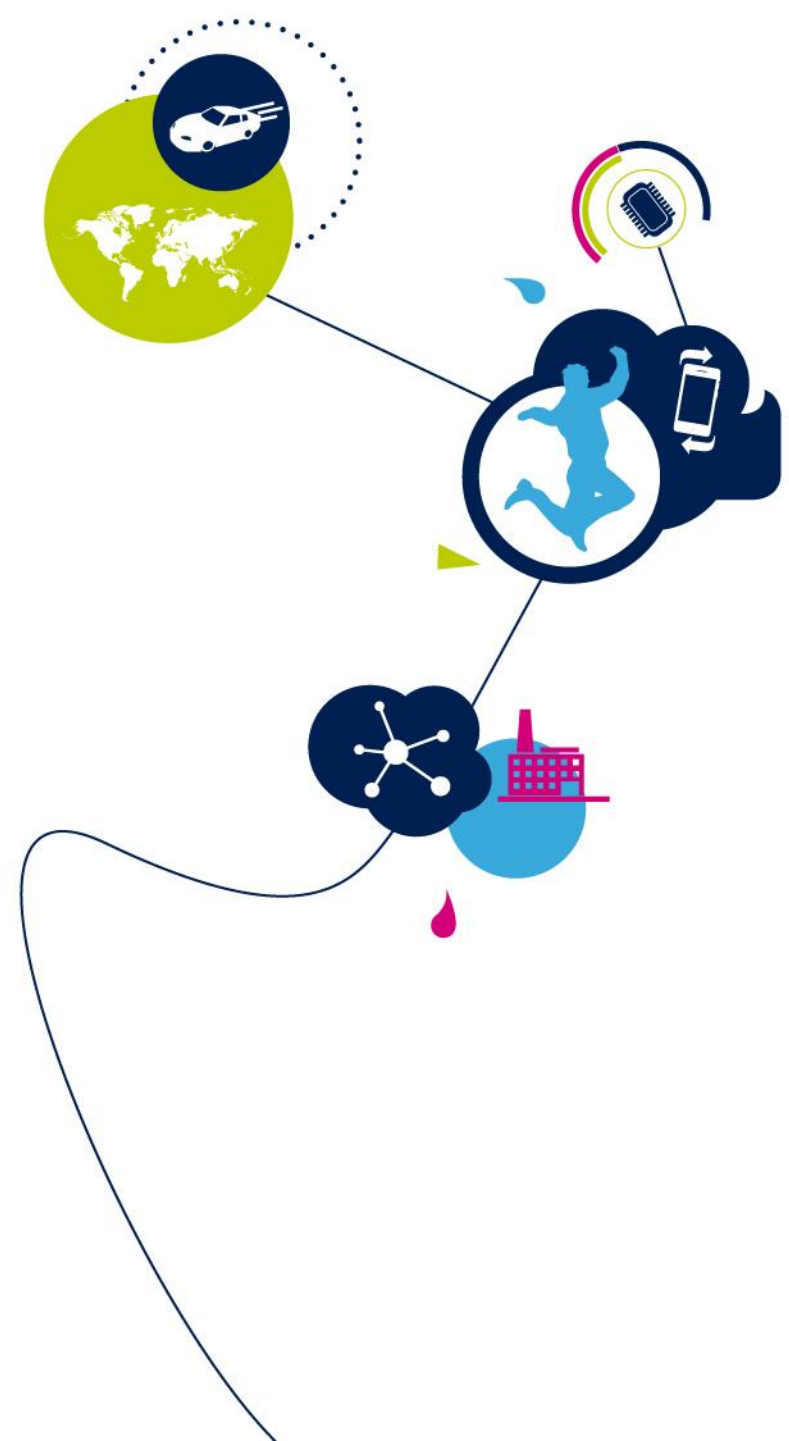
Takeaways

- Reinforce our Embedded Processing leadership position
 - Pervasion of STM32 MPU focusing on industrial market.
 - Proliferation of STM32 MCU SoC embedding wireless connectivity and advanced security
 - Inclusion of AI in all segments (through SW solutions and HW accelerators)
- Establish leadership position for Advanced Secure solutions.
 - Proliferation of eSIM solution for mobile and IoT
 - Pursue NFC / Secure Element and RF EEPROM families deployment.
- Contribute to 5G deployment
 - Key Silicon supplier for RF Front End Module capitalizing on ST advanced technologies
 - Production start of chip set for mmW phased arrays dedicated to LEO satellites

Manufacturing Strategy

Orio Bellezza

President
Technology, Manufacturing and Quality

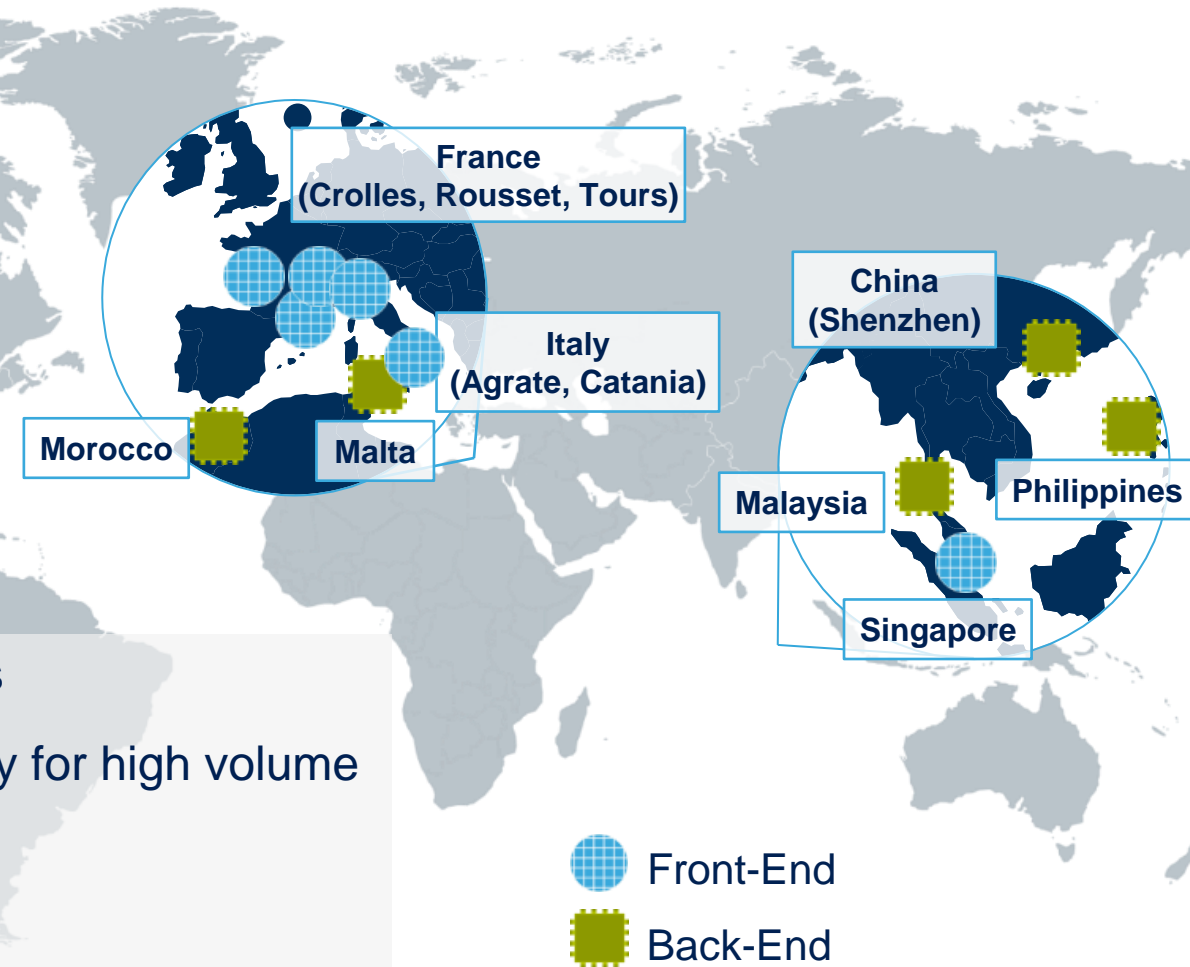


Manufacturing Strategy

a Key Business Enabler

- Integrated internal manufacturing and R&D on differentiated technologies and packages
- Partnership with foundry and OSAT for standard technologies and packages as well as advanced FinFET CMOS
- Offer our customers multiple sources and integrated supply chain control

- SiC and GaN technologies
- 300mm wafer fabs strategy for high volume differentiated technologies
- Power Modules
- Outsourcing



Key Programs

Silicon Carbide

150mm capacity expansion

Vertical integration of substrate supply chain

Gallium Nitride

150mm investment for RF for 5G

Installing 200mm pilot line in Tours for Power Discretes

300mm Strategy

New fab in Agrate to support growth in Smart Power, PMOS and IGBT beyond 2021

Modular expansion of Crolles300, in specialized imaging, FD-SOI 28nm, RF mixed signal and embedded-NVM

Power Modules

Vertically integrated internal manufacturing, Si and SiC capability, multiple sources planned

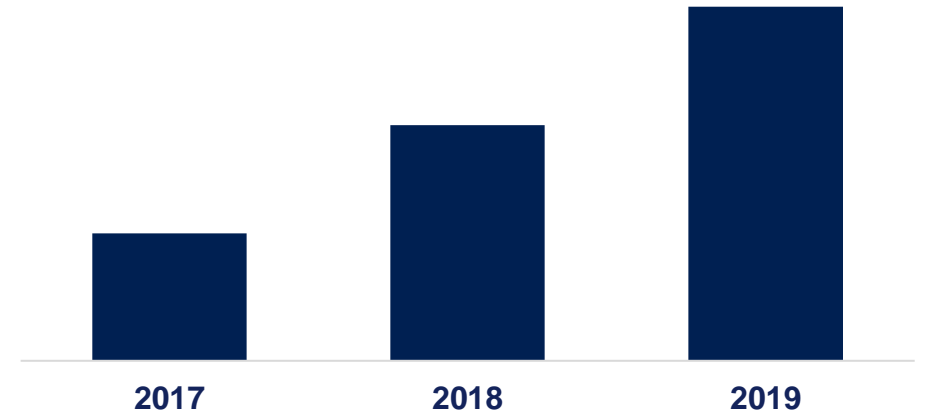
Partnerships with Foundries and OSATs

Increase the number of technologies qualified in outsourcing, targeting 30% Front-End in foundries and >30% back-end in subcontracting

Silicon Carbide Manufacturing

- 150mm in volumes in Catania since 2017
 - Automotive grade Power MOSFET and Diodes
 - Yields and quality at industry standard
 - Second source planned
- Committed to invest for growth - capacity expansion almost 3X in 2019 versus 2017
- Integrated teams of Design, R&D and Fab to support technology development and prototyping
- Secured supply of SiC substrates for future growth

Normalized capacity evolution



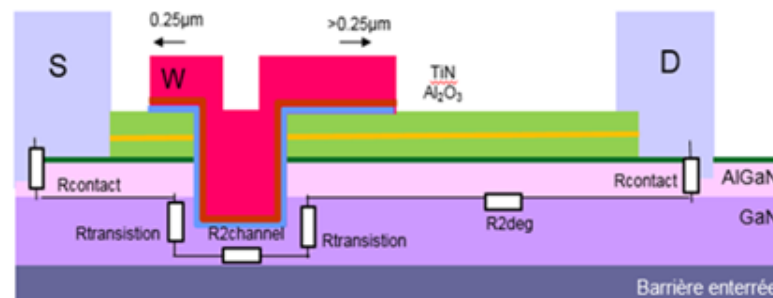
SiC Manufacturing Strategy

Device Manufacturing	Today	2021 Additions	Beyond 2021
Power MOSFET Technology	Gen2/Gen3 (planar)	Gen4 (trench)	Next Generation
Front-End fabs	Catania 150mm	Asia 2 nd fab 150mm	Evolution to 200mm
Back-End plants	Shenzhen	Asia 2 nd plant	

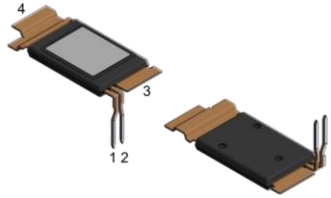
Substrate Supply	Today	2021 Additions	Beyond 2021
External Qualified suppliers	4 qualified suppliers		
External Supply agreements	LTSA with CREE	Enlarge base	
Internal	Norstel technology development & integration	Internal supply 150mm	Evolution to 200mm

Gallium Nitride

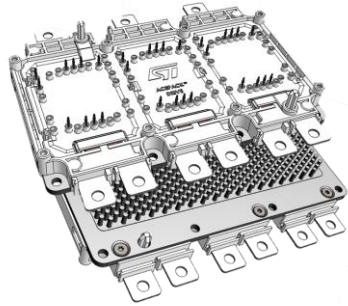
- **RF GaN-on-Silicon** production line in Catania
 - Technology under development, production maturity by end 2019
 - Wafer fab capacity 150mm investment under installation, volume ramp up in 2020
 - Plan to expand in 200mm to support technology roadmap and volume growth starting in 2021
- **GaN for Power Conversion** applications
 - Pilot line under construction in Tours in 200mm, active in H2 2020
 - First volume production start planned by 2021
 - Partnership with CEA LETI for Diodes and Transistor technology development



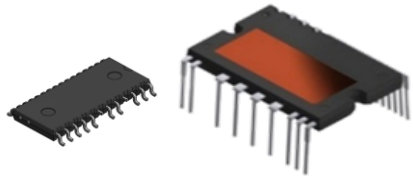
Power Module Manufacturing



STPAK™



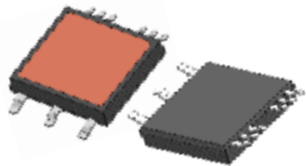
ACEPACK™ DRIVE



SLLIMM™ IPM

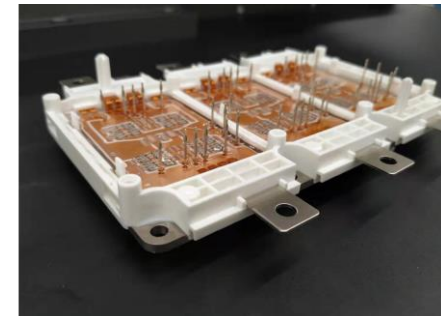


ACEPACK™ 1 & 2



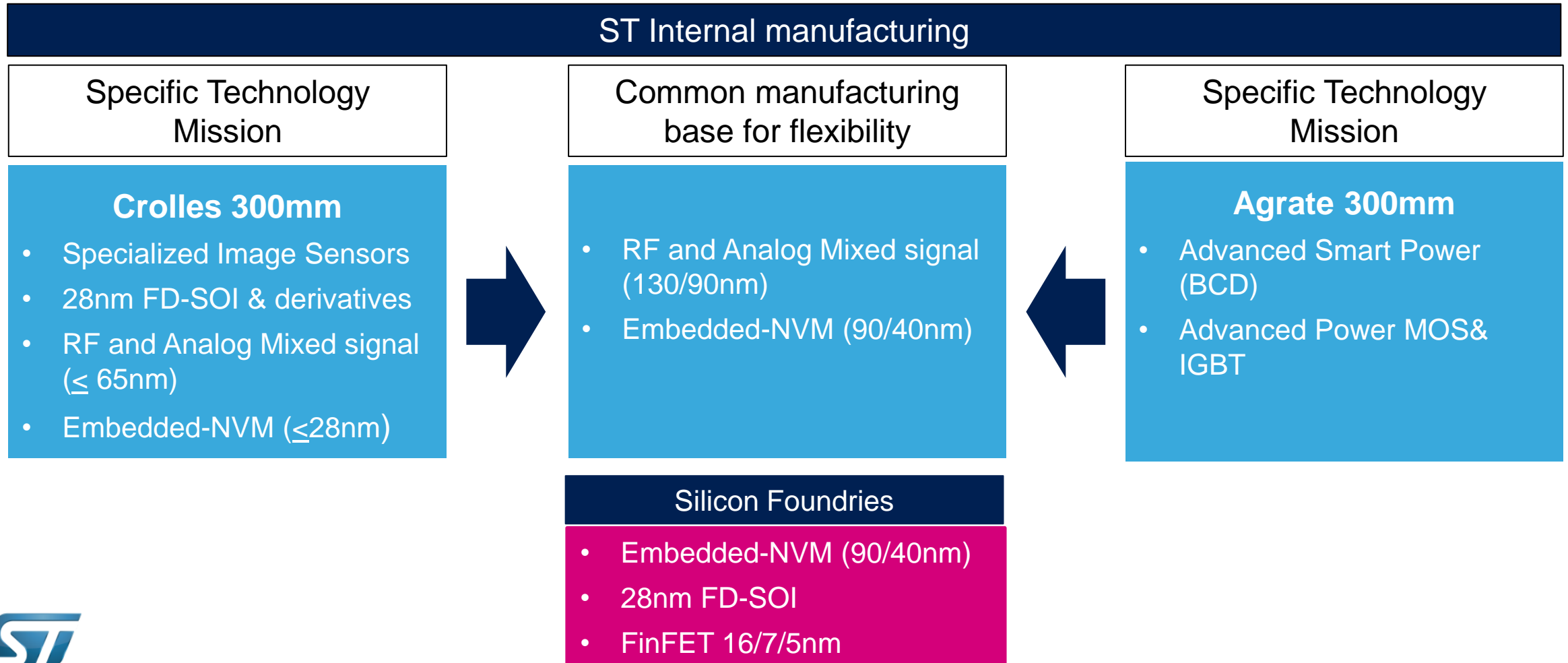
ACEPACK™ SMIT

- Development competence center and prototyping capability in Catania
- Internal production capacity in Asia, supporting standard and customized solutions
- External source active

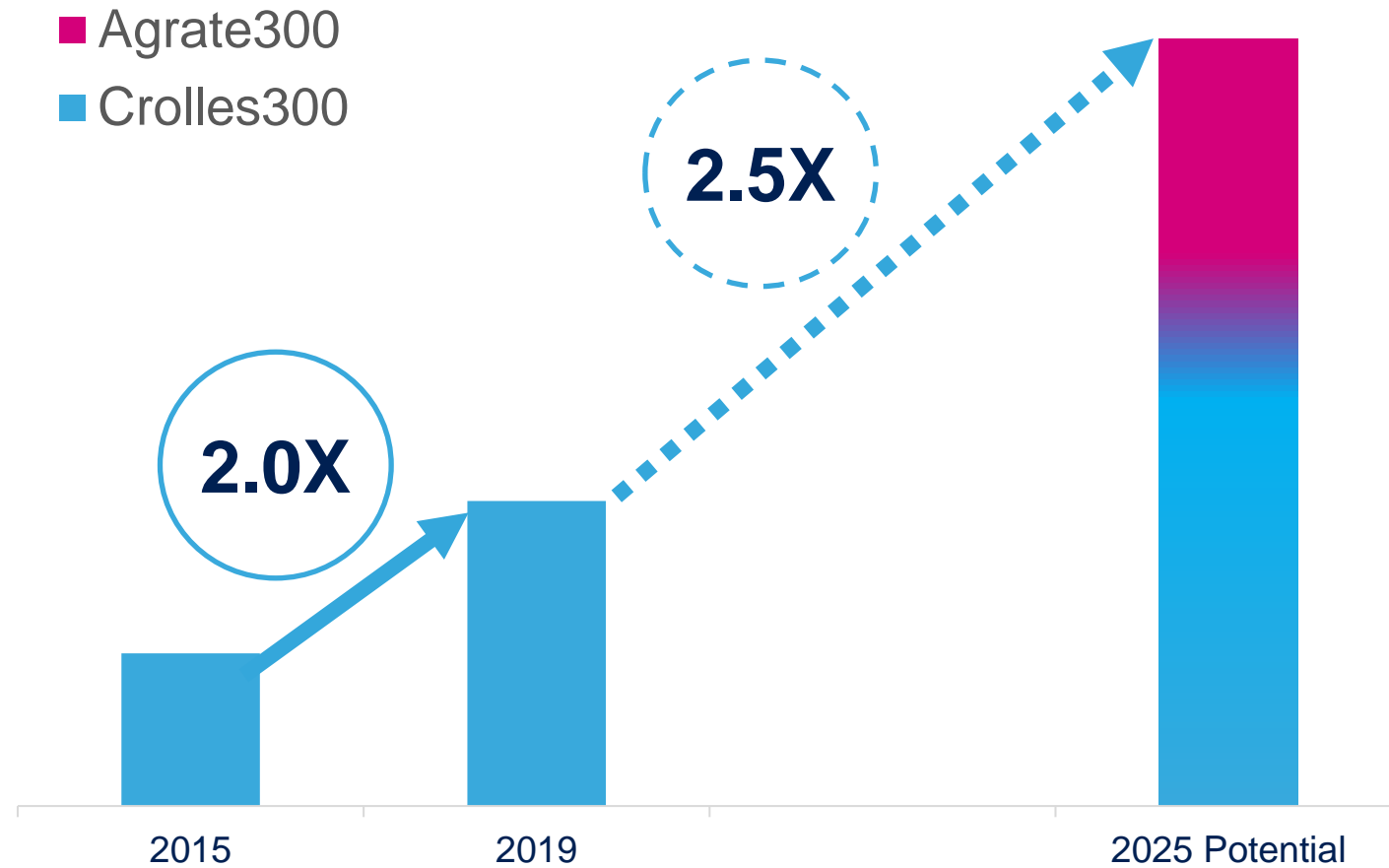


300mm Strategy

Establish 300mm Cluster “Agrate + Crolles + Silicon Foundries”



300mm Internal Capacity





Agrate 300mm Smart Power & Power Fab

Mission and Size

- Development and manufacturing of Smart Power (BCD), Power MOS and IGBT
- About 68,000 m² total covered building space
- About 13,000 m² total clean room, at full build out

Status and Planning

- Development and first industrial deployment phase:
 - Start of construction H2 2018
 - Ready for equipment in H2 2020
 - Wafers out H1 2021
- High volume manufacturing start >2021
- Modular expansion of facilities and clean room, tuned to market demand

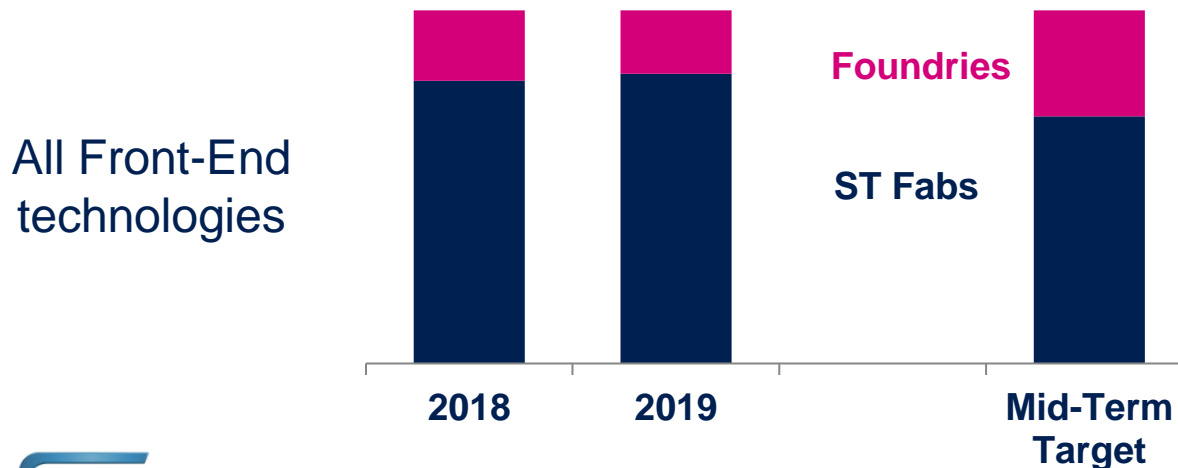
Agrate-Crolles preparation tasks

- Several workstreams in place (facilities, equipment, automation...)
- BCD and IGBT process modules scale from 200 to 300mm, speeding learning curve & qualification

Foundries Strategy

Targeting to increase from ~20% to ~30% of total production value

Extending the number of technologies in outsourcing



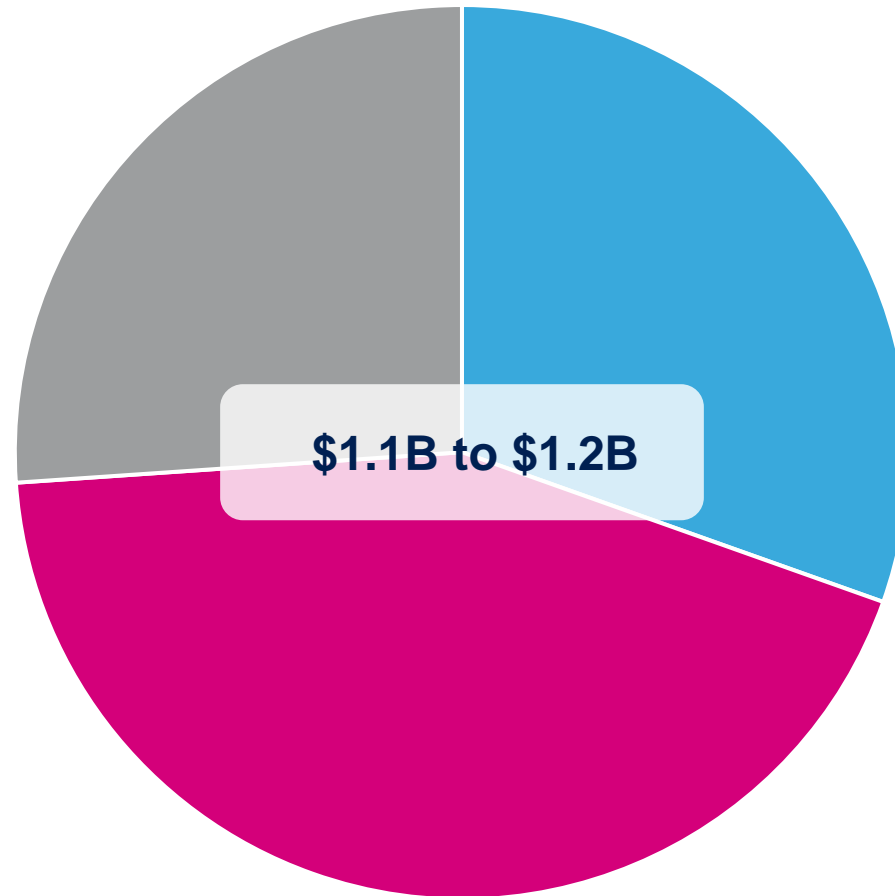
Technology	Sources	
eNVM 180nm	Foundry	
eNVM 90nm	Crolles Rousset	Foundry
eNVM 40nm	Crolles	Foundry
CMOS FD-SOI	Crolles 300	Foundry
FinFET 16/7/5nm	Foundry	
Power MOS LV	Catania Singapore	Foundry
IGBT	Catania Singapore	Foundry
BCD 160nm	Agrate Catania	Foundry
Analog CMOS 130nm	Crolles	Foundry

■ Qualification on-going ■ Active

2019 Capital Spending

Mix change, R&D, others

- Smart power evolution to BCD8/9 for automotive and industrial
- Technology development
- Fab automation, quality, digitalization, equipment obsolescence



Strategic initiatives

- SiC 150mm in Catania
- Agrate 300mm buildings
- GaN in Catania and Tours
- Specialized imaging in Crolles300

Capacity growth

- Power MOS/IGBT in Singapore
- 28nm FD-SOI in Crolles300
- Singapore fab acquisition
- Assembly and Test

Takeaways



Manufacturing is a key enabler to achieve our strategic objectives in balanced make-or-buy strategy

2019 Capital investment plan supports both ongoing business and strategic programs

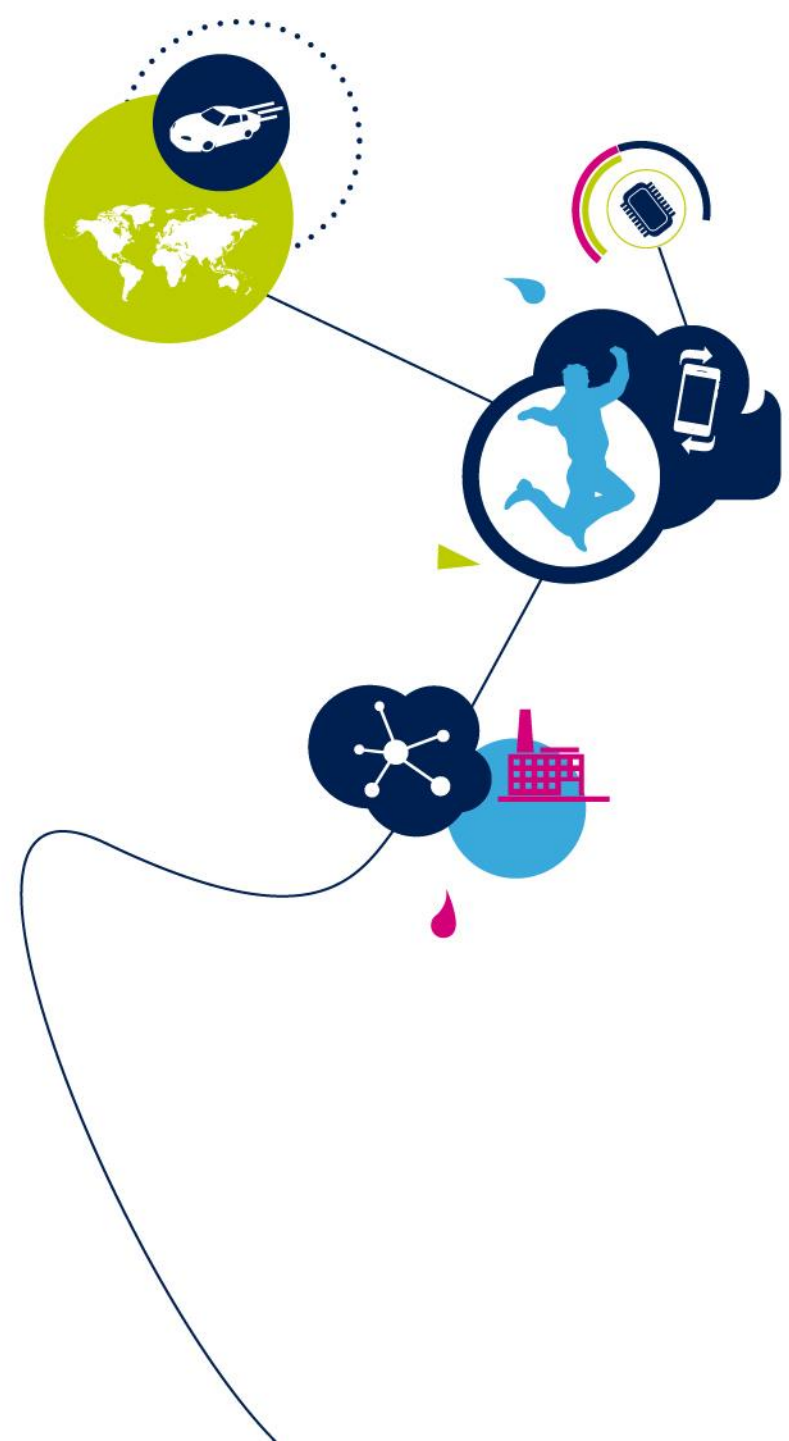
Key programs focus

- SiC growth and vertical integration entering GaN production
- 300mm fab construction in Agrate
- Power modules ramp up
- Increase foundries technology base

Financial Results & Priorities

Lorenzo Grandi

Chief Financial Officer
President, Finance, Infrastructure and Services





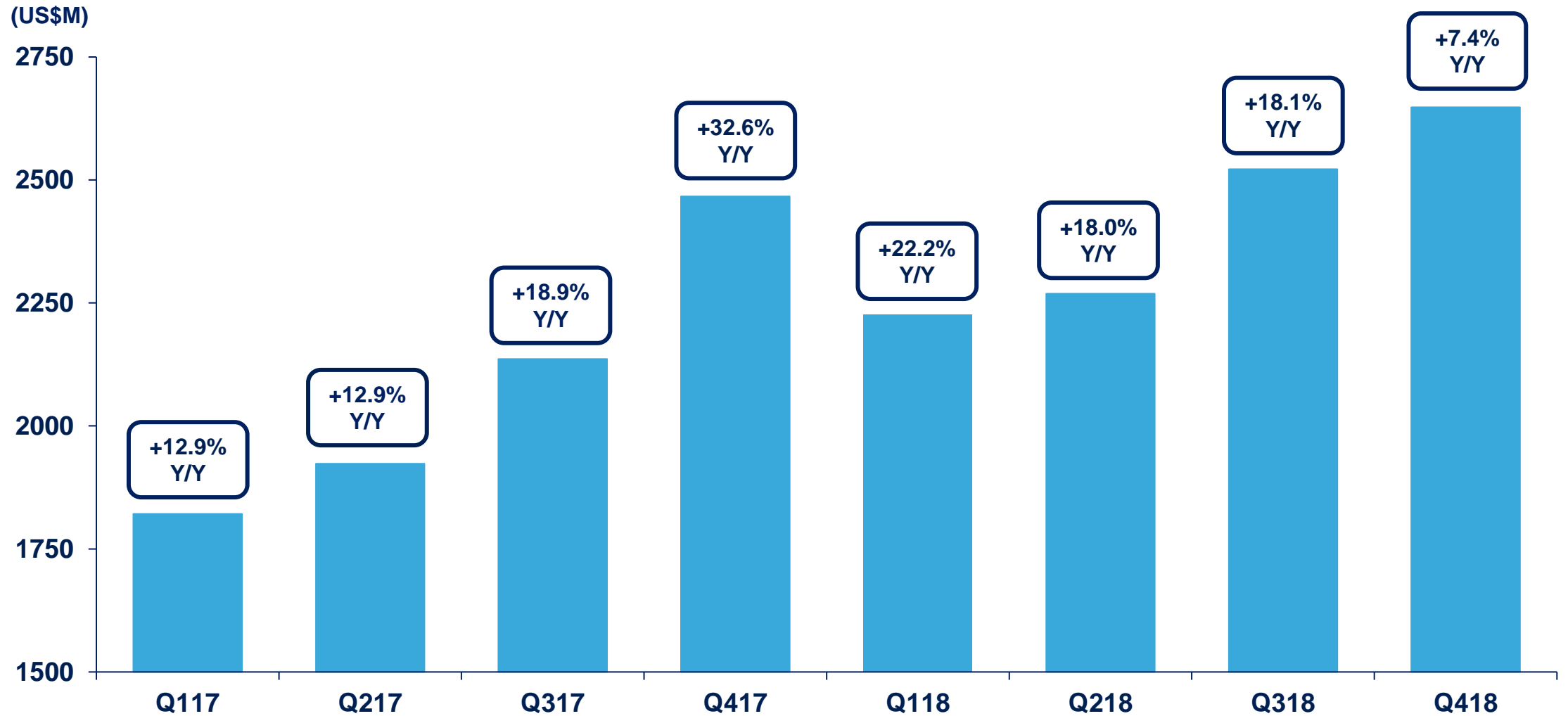
Sustainable Profitable Growth

ST Transformation – from FY15 to FY18

<i>In US\$M</i>	FY15	FY16	FY17	FY18	Δ FY18 vs FY15
ST Revenues	6,897	6,973	8,347	9,664	+ 40.1%
Served Market (SAM) Y/Y	-1%	4%	13%	10%	
ST Revenues Y/Y	-6.8%	1.1%	19.7%	15.8%	
Gross Margin	33.8%	35.3%	39.2%	40.0%	+ 620 bps
Operating Margin	1.6%	3.3%	12.0%	14.5%	+ 1290 bps
Net Income	104	165	802	1,287	+ \$1,183 M
Free Cash Flow*	327	316	308	533	+ 63.0%
Net Financial Position*	494	513	489	686	+ 38.9%

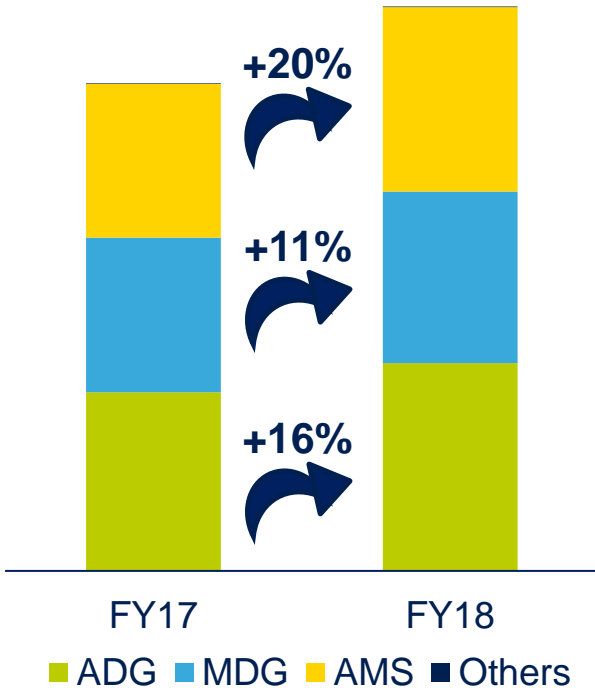
*Non-U.S. GAAP measure. See Appendix for additional information explaining why the Company believes these measures are important.

Solid and Consistent Revenue Growth

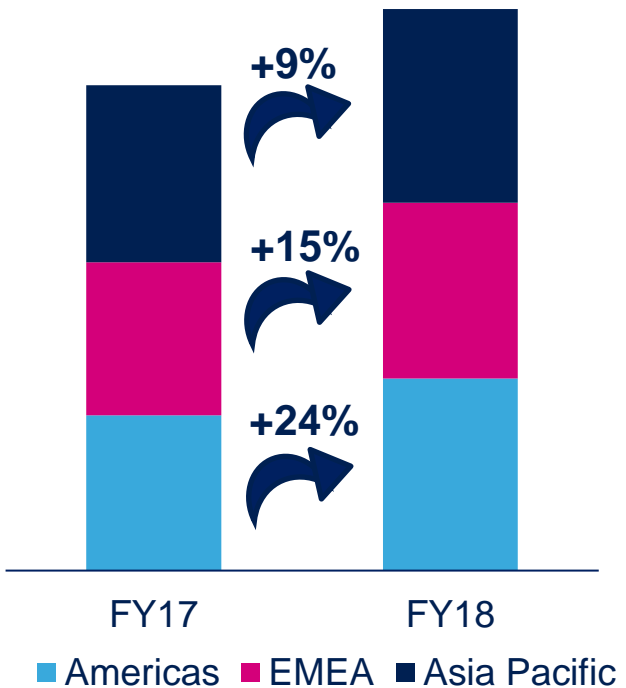


Balanced Revenue Growth

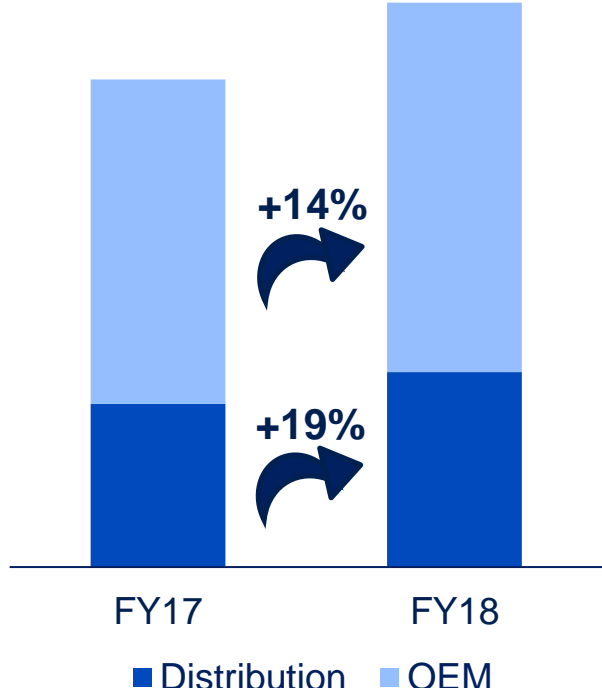
Product Group



Region of Origin

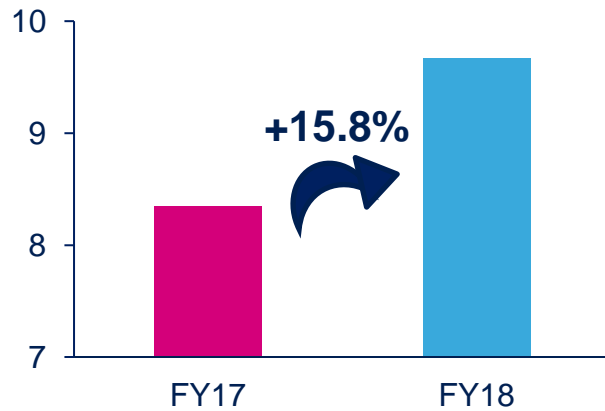


Customer Type

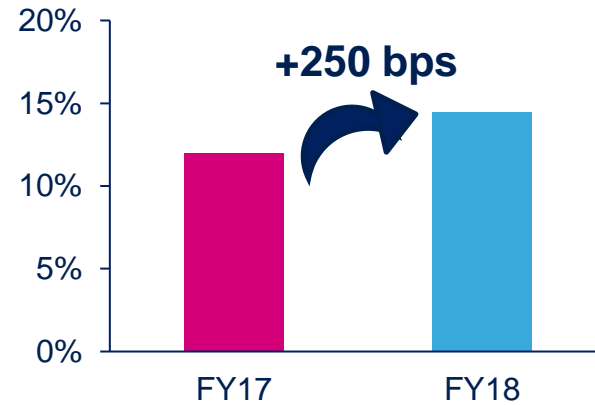


FY18 Financial Highlights

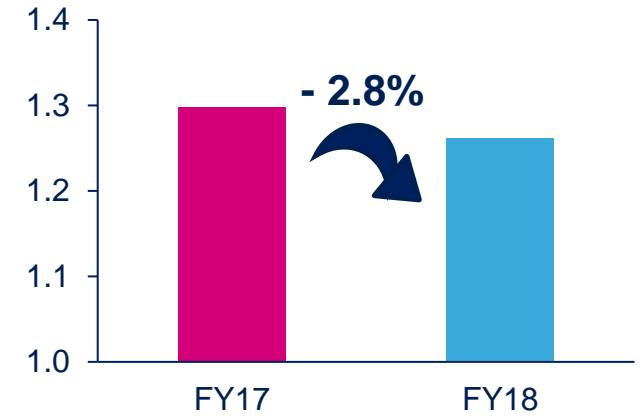
Revenues = \$9.66B



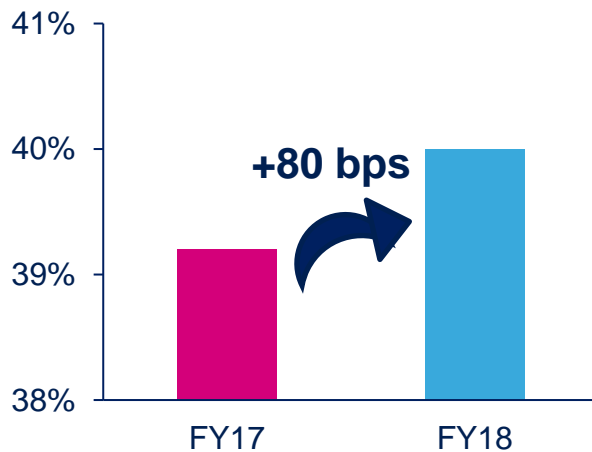
Operating Margin = 14.5%



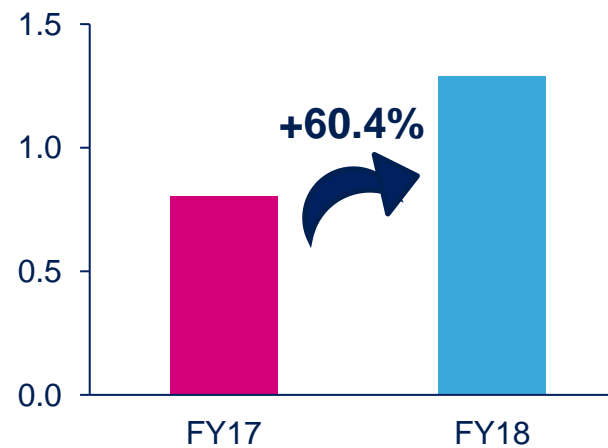
Capex = \$1.26B



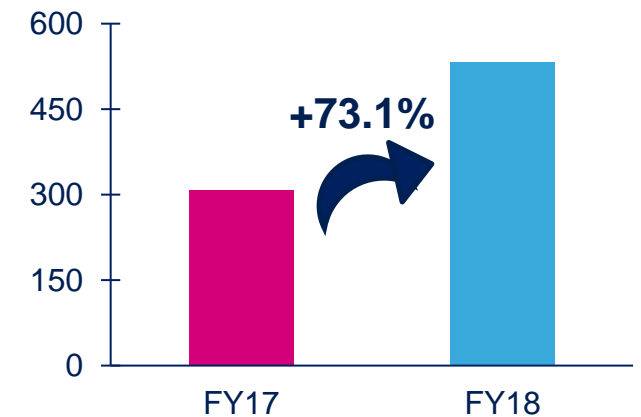
Gross Margin = 40.0%



Net Income = \$1.29B



Free Cash Flow* = \$533M



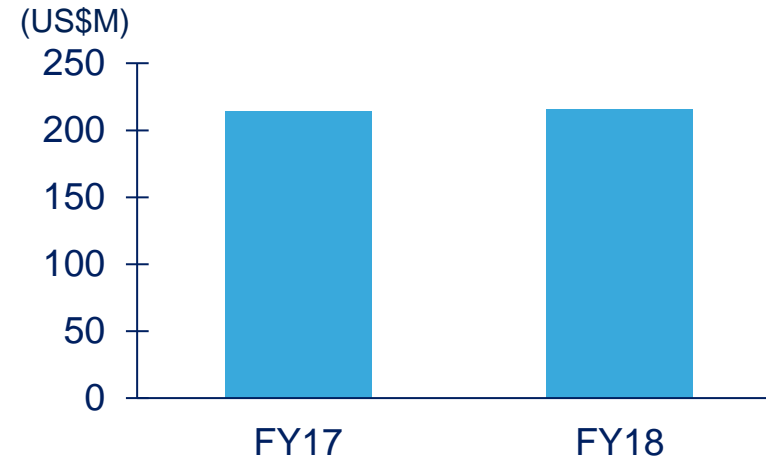
*Non-U.S. GAAP measure. See Appendix for additional information explaining why the Company believes these measures are important

Solid Capital Structure

Net Financial Position*

End of period (US\$M)	Dec 31, 2018	Dec 31, 2017
Total Liquidity	2,596	2,190
Total Financial Debt	(1,910)	(1,701)
Net Financial Position*	686	489

Cash Dividend



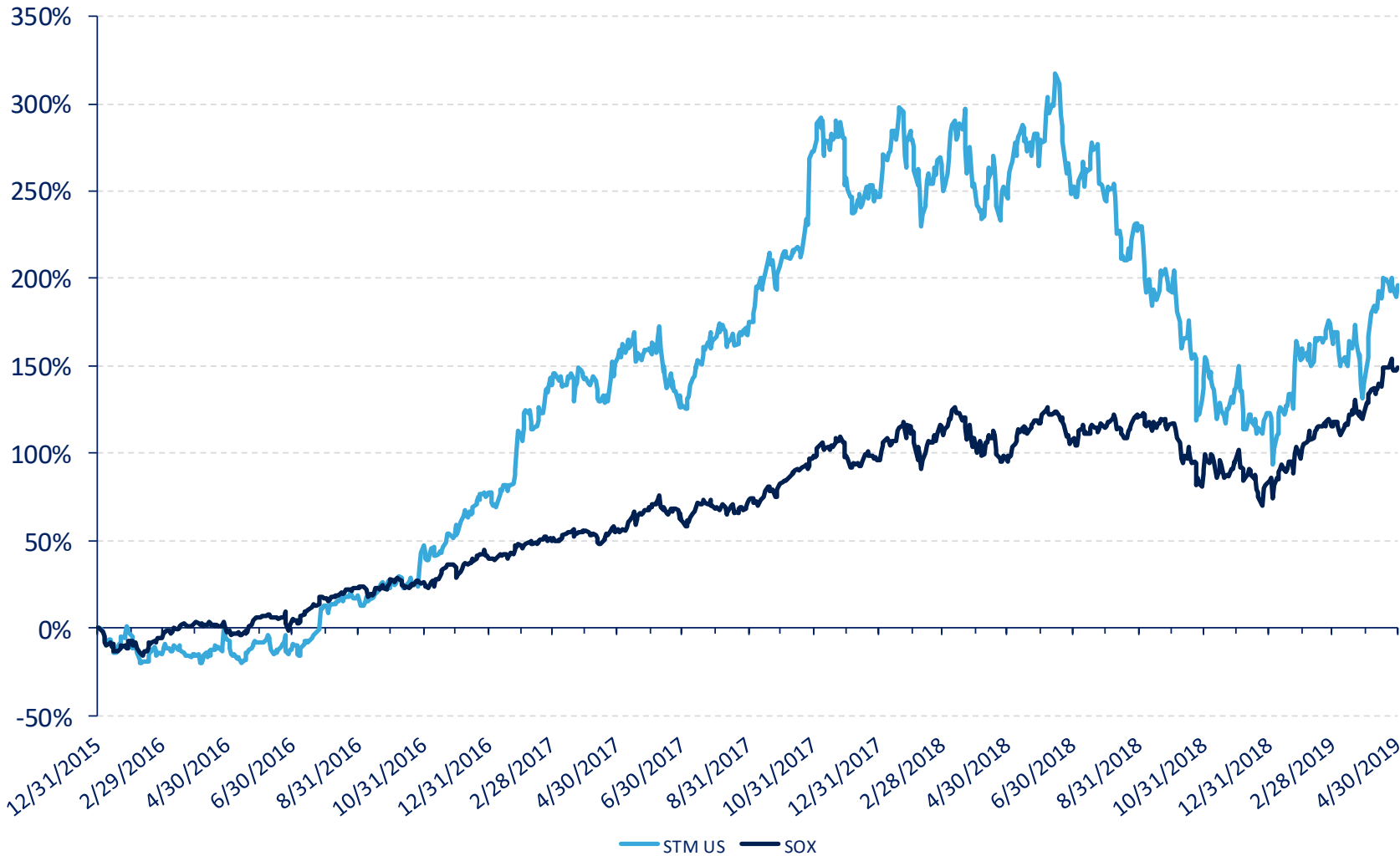
Cash Dividend proposal to shareholders at 2019 AGM is stable at **\$0.24** per share.

On November 5, 2018, STMicroelectronics announced the launch of a share buy-back program of up to \$750 million to be executed within a 3 year period.

Period from	To	Shares Repurchased	Weighted Average Price	Total Amount Paid	Currency
5-Nov-18	10-May-19	10.4M	13.58	141.4M	EURO

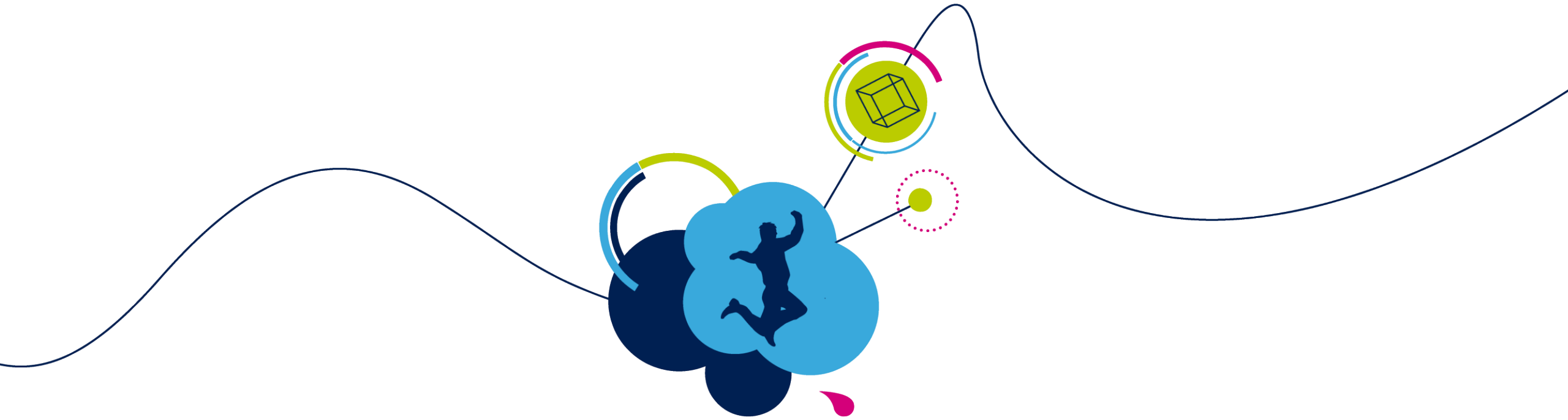
Shareholder Returns

ST vs SOX 12/31/15 - 04/30/19



Range	12/31/2015 - 04/30/2019	
Security	Price Change	Total Return
STM	176%	196%
SOX Index	135%	149%

All rating agencies which report on ST on a solicited basis (Moody's, S&P and Fitch) are aligned in rating ST's credit profile well within investment grade and with Stable Outlook



2019 Outlook

2019 Market Dynamics

Volatile macroeconomic indicators, slowing economic growth and accelerating contraction of certain end markets

May

- **Q119** Eurozone economy grew 1.2% Y/Y, better-than-expected but lower compared to 2.4% Q118 Y/Y growth
US economy grew 3.2% Y/Y, the first time since 2015 that Q1 GDP topped 3%
Chinese economy grew 6.4% Y/Y, better than expected, but matching Q418 growth rate at the lowest level in nearly 30 years

April

- IMF's 2019 world economy forecast lowered to 3.3% from 3.5% forecasted in January. This growth rate is the weakest since 2009.

March

- ECB's 2019 Eurozone economic growth forecasts lowered to 1.1% from 1.7% forecasted in December.
- China set its 2019 economic growth target at 6.0 to 6.5%, the lowest since 1990.

Trade situation negatively impacting business and consumer confidence

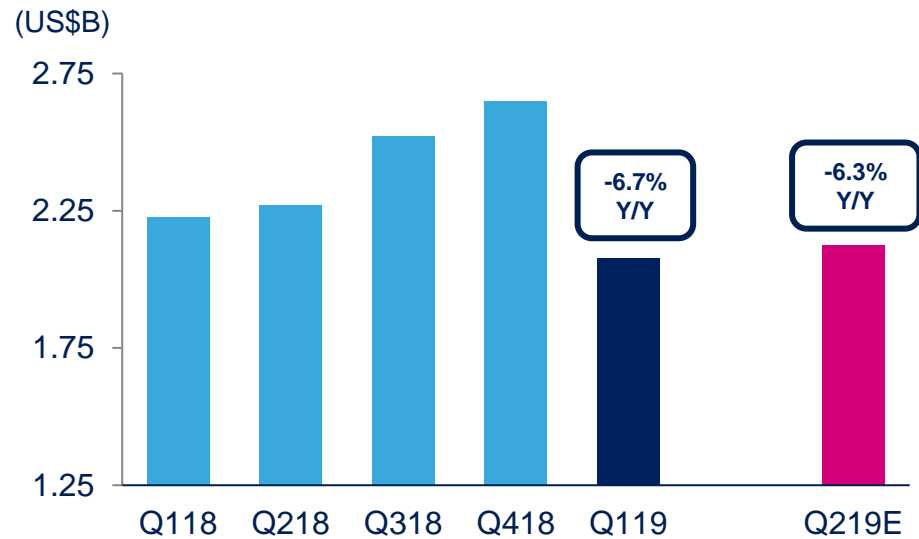
- On May 10th the US introduced additional tariffs on Chinese goods
- Growth of China's manufacturing sector is slowing
- Negative impact on domestic and international supply chains
- Potential for US trade war with Europe

Lack of Growth Catalysts

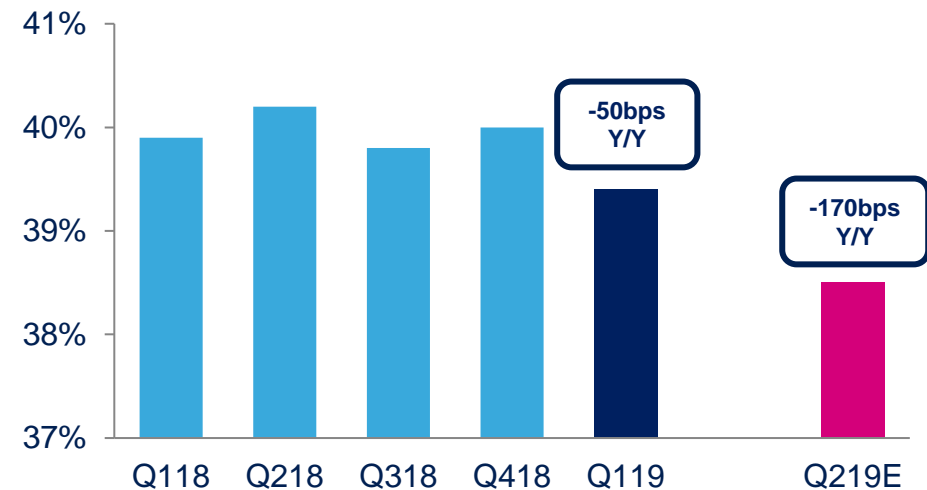
- Volatility in order rates
- Weak end markets
- High inventory levels

Q119 Key Metrics & Q219 Outlook

Q119 Revenues = \$2.08B
Q219 Revenues Outlook = \$2.13B



Q119 Gross Margin = 39.4%
Q219 Gross Margin Outlook = 38.5%



Q219 Revenue Outlook

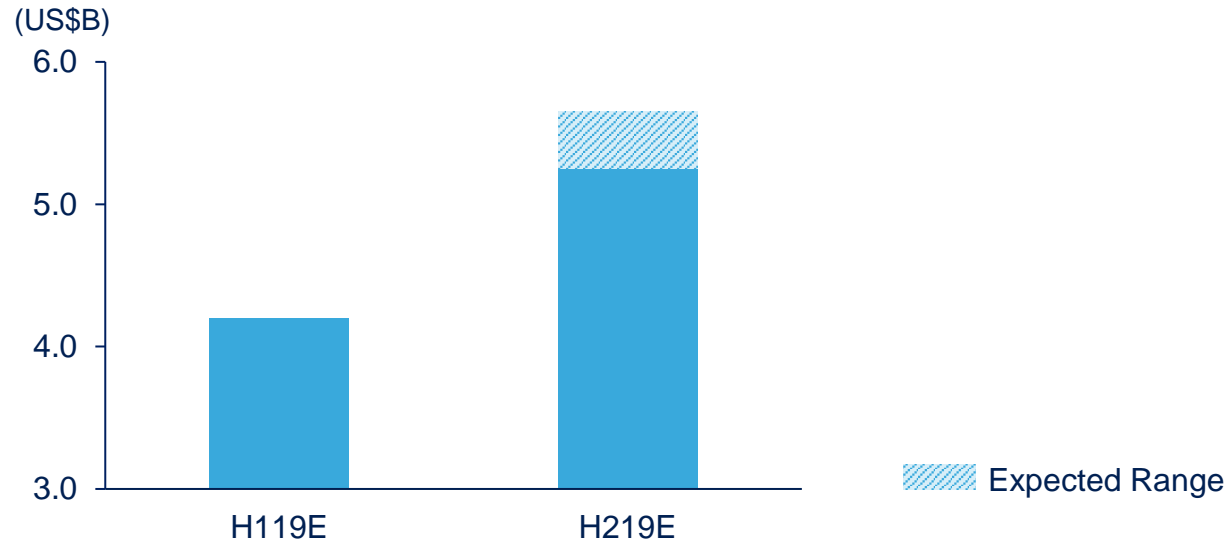
Up Q/Q by about 2.4% (+/- 350 bps)
Down Y/Y by about 6.3% at mid-point

Q219 Gross Margin Outlook

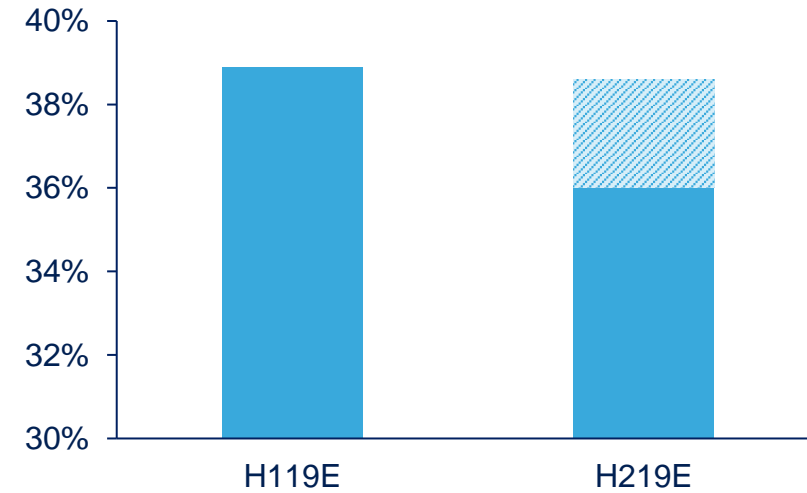
About 38.5% (+/- 200 bps)

H219 Growth Drivers

Revenues H119 to H219



Gross Margin H119 to H219

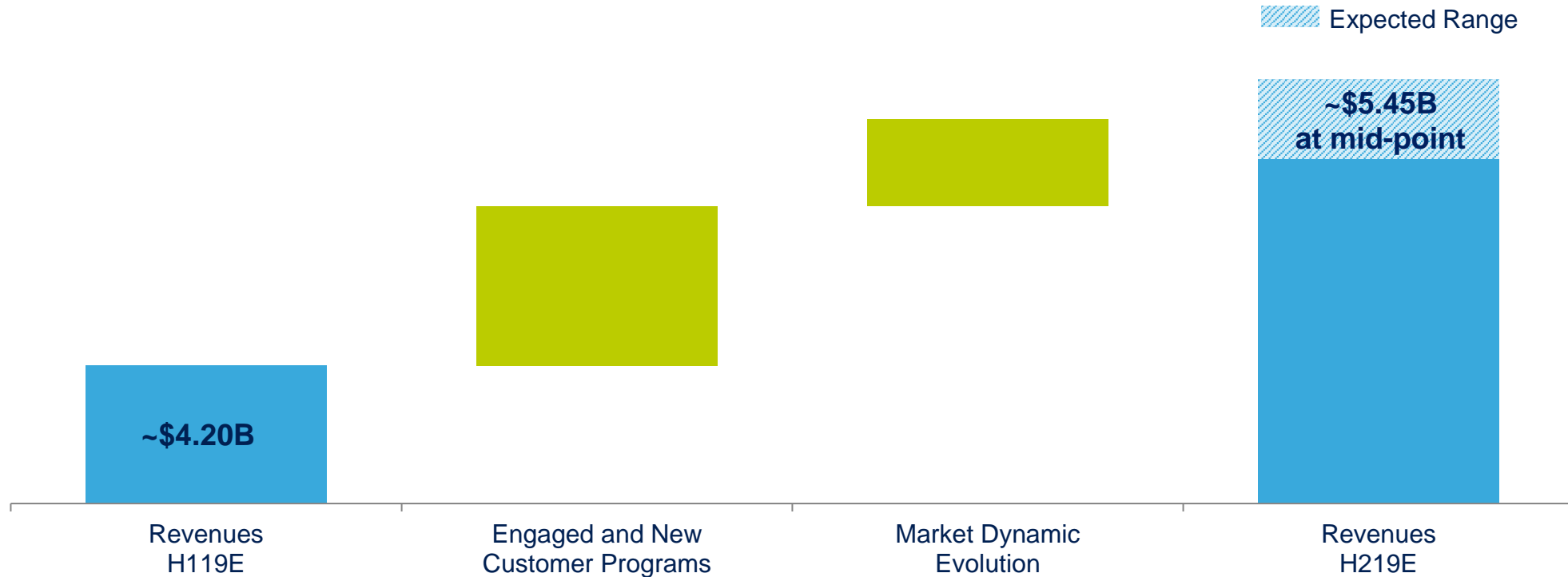


Evolution from H119 to H219

Strong growth planned in H219 compared to H119 across several end markets:

- Automotive
- Industrial
- Personal Electronics

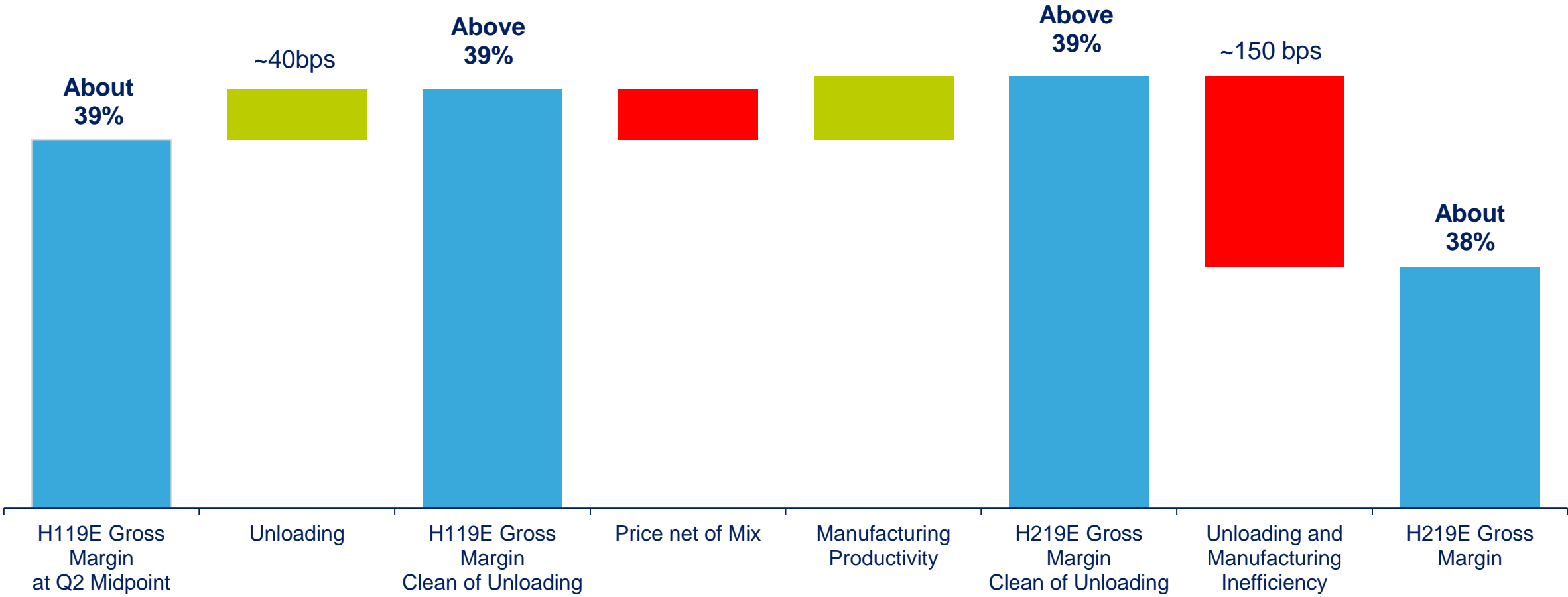
ST Revenue Drivers – H119 to H219



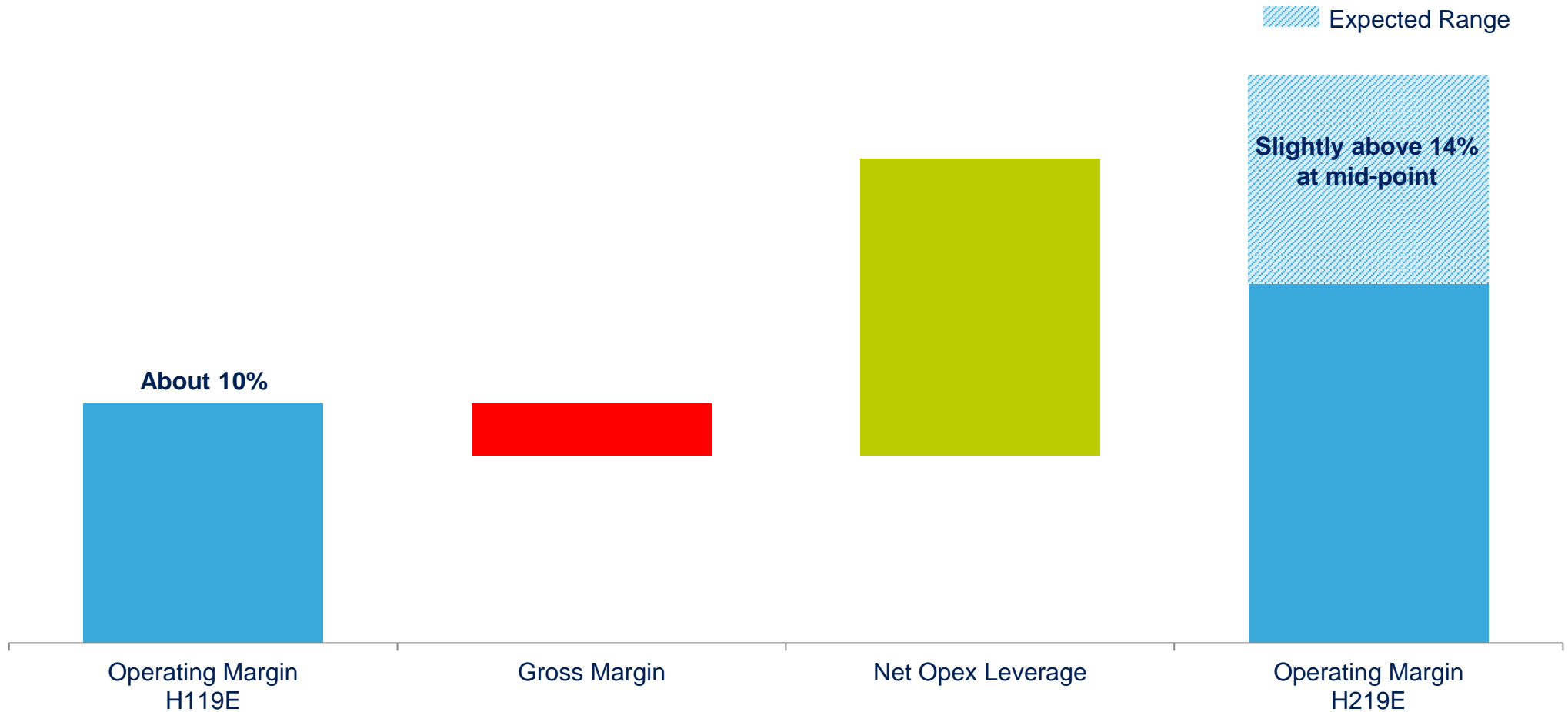
Main Drivers

- Personal electronics (Specialized Imaging Sensors, Secure Solutions, Power Management and RF Front-End Modules)
- Satellite communications deployment
- Silicon Carbide devices to benefit from additional capacity available in H219
- Microcontrollers, Analog and Power Discrete driven by expected improved market conditions

Gross Margin Evolution

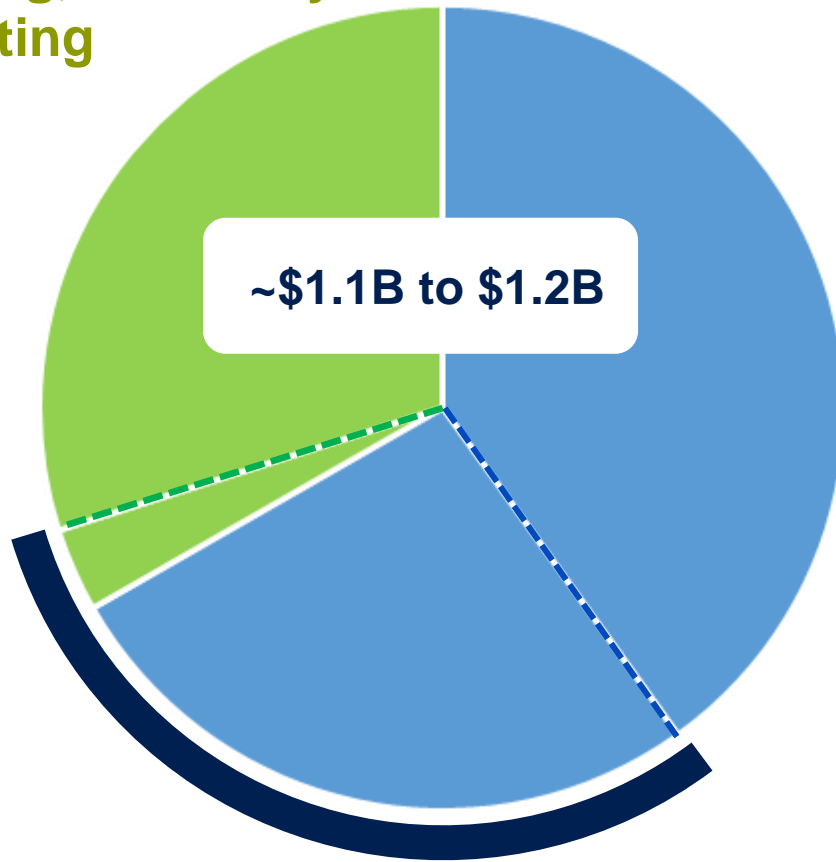


Operating Margin - H119 to H219



2019 Capital Spending

Probing, Assembly
& Testing



Front-End
Manufacturing
and R&D

**Investment and Strategic Initiatives to
prepare future business growth**

Maintenance, R&D and capacity additions
in some of our existing technologies

Plus 3 Key Strategic Initiatives

- New 300mm fab in Agrate for BCD, IGBT and Power technologies
- Expansion of installed capacity for Silicon Carbide and start of production ramp-up for Gallium Nitride for RF devices
- Next generation Imaging sensor technologies

3 Key Strategic Initiatives

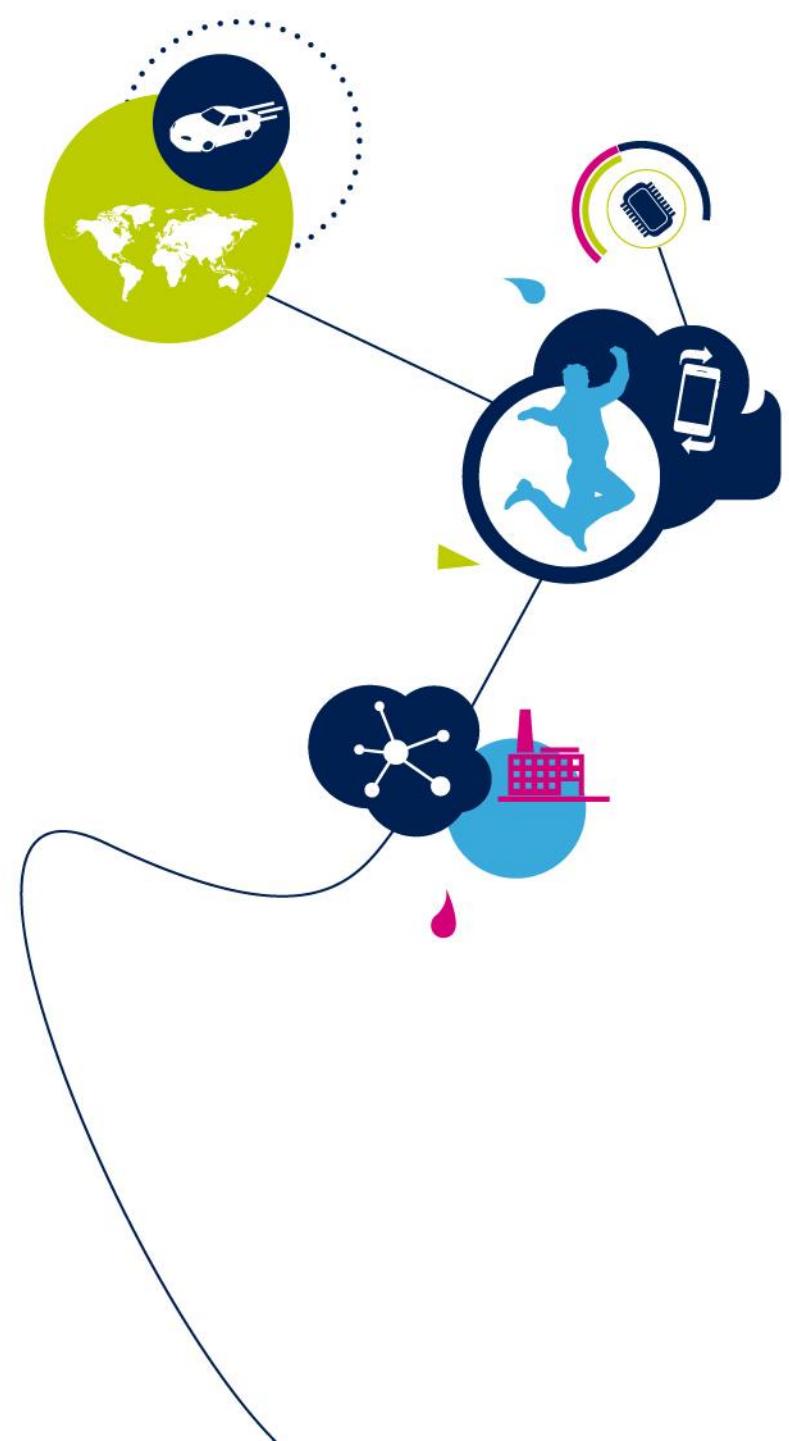
FY19 Scenarios

Served Market (SAM) *	~ -3.0% / +1.3%
ST Revenues	\$9.45 / 9.85B
ST Revenue Evolution	-2% / +2%
Gross Margin	>37% / around 39%
Average quarterly Net Opex	\$620 / 630M
Tax rate	14 / 17%

Slight Decline
to Slight Growth

Strong discipline in protecting the balance sheet and capital spending for key strategic initiatives

Financial Model



ST Growth Catalysts

Automotive

- Car Digitalization
 - ADAS and MCU
- Car Electrification
 - SiC MOSFET and IGBT

Industrial

- Embedded processing solutions
 - MPU, Connectivity and Security
- Analog & Power
 - Applications specific

Personal electronics

- Sensors
- Secure solutions
- Analog
 - Application specific (power management)
- RF Mixed Signal for Front-End modules

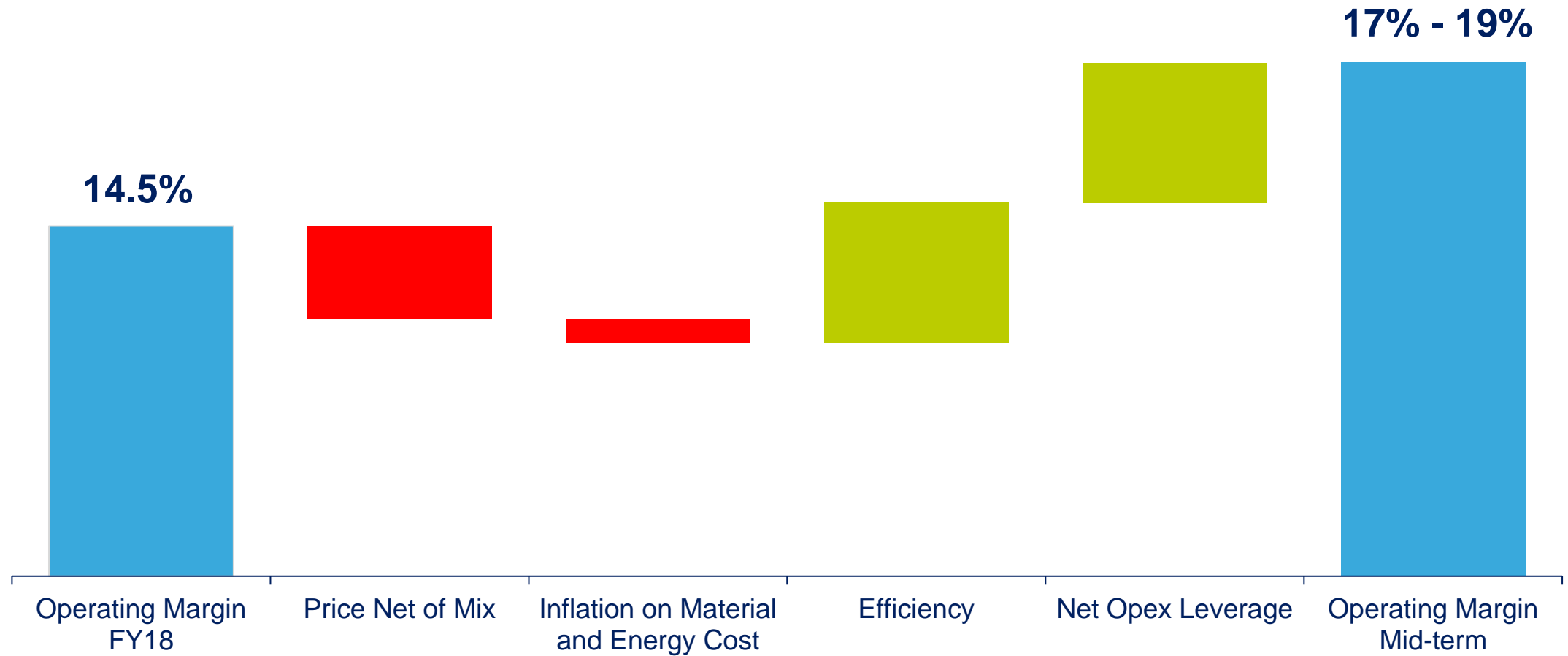
Communications Equipment, Computers & Peripherals

- Power management
- RF Mixed Signal for satellite constellation



Operating Margin Drivers

Mid-term Model

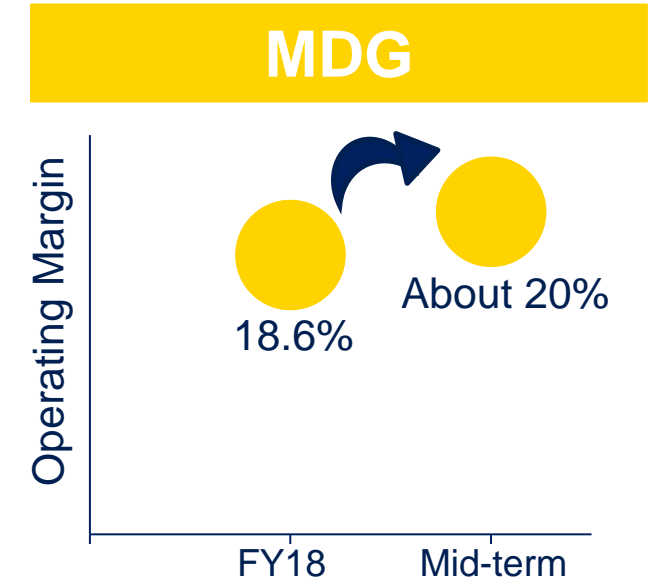
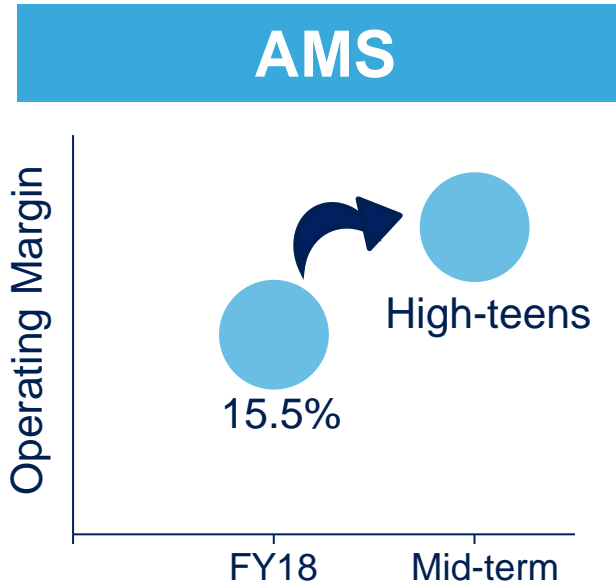
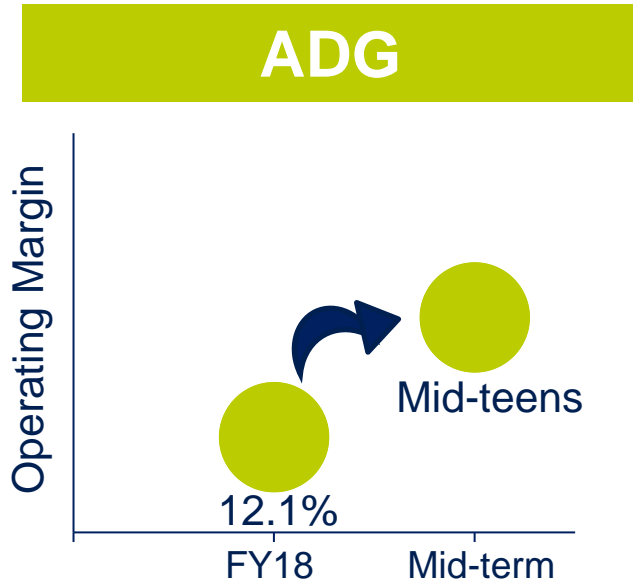


Path to Mid-Term Financial Model*

	<i>Mid - Term Model*</i>
ST Revenues	\$12.0B
Gross Margin	40% - 41%
Operating Margin	17% - 19%
Net Income	\$1.7 - 1.9B
Free Cash Flow	> \$1B

* See Forward Looking Information for full disclosure. Such information is subject to various risks and uncertainties, which may cause actual results and performance of our business to differ materially and adversely from the Forward Looking Information.

Product Group Profitability Evolution



Margin Expansion Drivers

Leverage revenue growth

ADG

Improved mix

ADAS, SiC power devices, IGBT & MCU

AMS

Improved Mix

Analog and Sensors

MDG

Improved mix

MPU, MCU and RF mixed signal

Capital Allocation Plan

Sustain Growth

Capex

- Average yearly Capex of ~ \$1.1 – \$1.5B over the near/mid-term horizon
- Mitigate spending via higher outsourcing

Acquisition

Focused on:

- Organic growth
- Small and targeted strategic acquisitions

Shareholder Return

Dividend

- Dividend payment at \$0.24 per share in 2019
- Dividend consistent with our planned cash generation

Share Repurchase

- In Q418, we announced the launch of a share buy-back program of up to \$750 million to be executed within a 3 year period



Value Proposition for Shareholders

ST Value Proposition for Shareholders



Commitment to organic
and self-financed growth



Strong focus on
Long-term value creation



Significant opportunity
to increase profitability



Capability to increase
shareholder value

STMicroelectronics Capital Markets Day 2019

